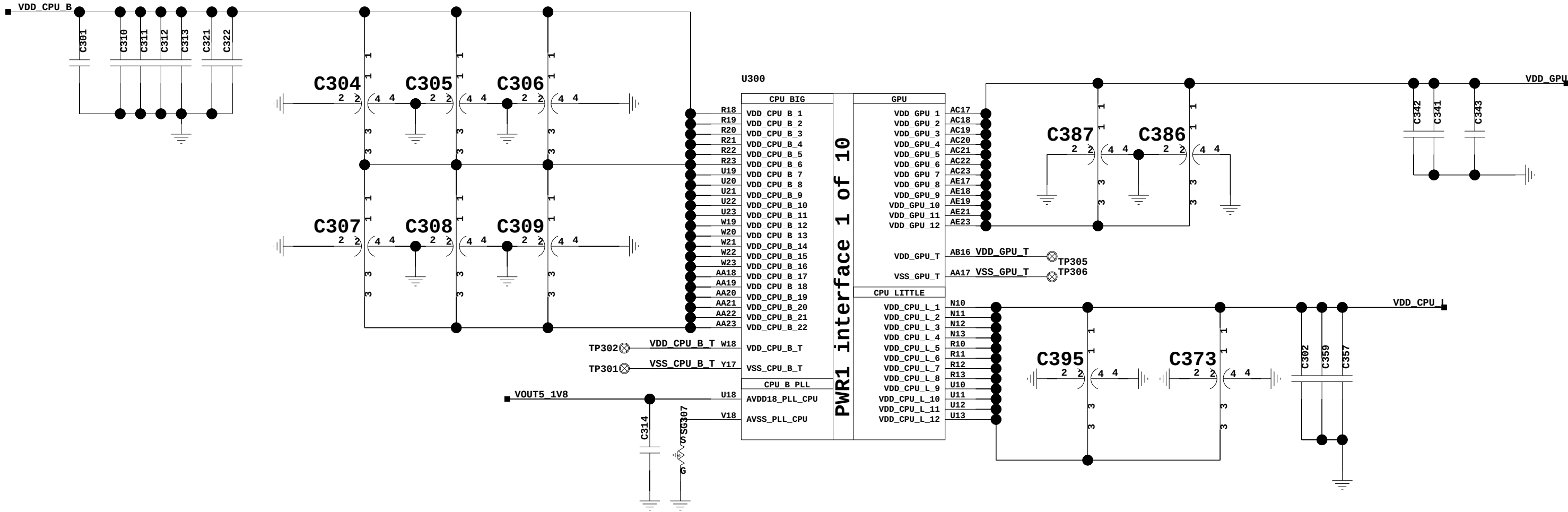


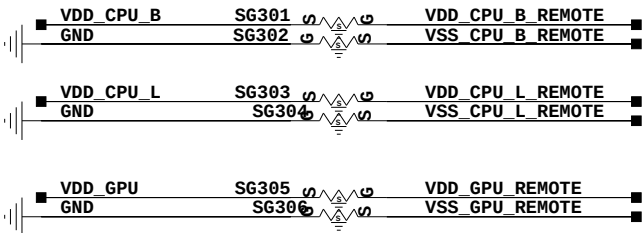
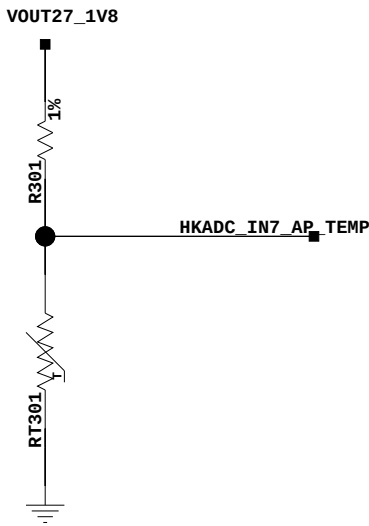
	1	2	3	4	5	6
A	Baseband Schematic			MODEM Schematic		
	1.	Contents		31.	RF Interface	
	2.	Block Diagramm		32.	RF PMU	
B	3.	SOC PWR1		33.	RF Transceiver	
	4.	SOC PWR2		34.	RF FRONT END HB	
	5.	SOC PWR3		35.	RF FRONT END B42	
C	6.	SOC HS Interface		36.	RF FRONT END MB	
	7.	SOC GPIO Interface		37.	RF Front End LB	
	8.	SOC RF Interface		38.	RF Front End Switch /Main ANT	
D	9.	SOC GND		39.	RF Front End Diversity	
	10.	PMU LDO		40.	RF Front End Diversity	
	11.	PMU BUCK & HI6422-1		41.	Reserved for CDMA Modem	
	12.	PMU MISC & BUCKBOOST		42.	Reserved for CDMA Modem	
	13.	HI6422-2		43.	Reserved for CDMA Modem	
	14.	UFS and LPDDR		44.	Reserved for CDMA Modem	
	15.	Battery & Fuel guage		45.	Reserved for CDMA Modem	
	16.	USB/Scharger V300/Switch		46.	Reserved for CDMA Modem	
	17.	LCD Interface		47.	Reserved for CDMA Modem	
	18.	Reserved		48.	Reserved for CDMA Modem	
	19.	Flash LED		49.	RESERVED	
	20.	Camera Interface		50.	RESERVED	
	21.	ISP Reserved		51.	RF Front End M1	
	22.	Codec HI6403		52.	Hi1102 POWER	
	23.	Audio/SPK/VIB		53.	Hi1102 Interface	
	24.	Headphone		54.	Hi1102_RF_FrontEnd_2G	
	25.	Audio		55.	Hi1102_RF_FrontEnd_5GHz	
	26.	X-Sensor1		56.	RF_FRONT_END_Diversity_M1	
	27.	X-Sensor2		57.	NFC	
	28.	SIM/uSD Card		58.	RF Transceiver2	
	29.	FPC Interface		59.	RFIC2 PA+PMU	
	30.	Test Point/Shielding		60.	ANT Tuner	
				The type and specification of the components refer to the BOM		
						2018-07-06
					ECA NO	DATE
	DESIGNED	CHENZHENBIN 00264464		HL1JSNM		03025GKM_SCH1ZH
	REVIEWED	MABO 00278126				
			VER	PART_NUMBER	SHEET 1_Content00	
			E	03025GKM	HUAWEI TECH CO.,LTD.	
	1	2	3	4	5	6

	1	2	3	4	5	6
A	2.Block Diagram					
B						
C						
D				The type and specification of the components refer to the BOM		
						2018-07-06
					ECA NO	DATE
	DESIGNED	CHENZHENBIN 00264464			03025GKM_SCH1ZH	
			HL1JSNM			
	REVIEWED	MABO 00278126			03025GKM	
			VER	PART_NUMBER	SHEET 2_Block Diagram	
			E	03025GKM	HUAWEI TECH CO.,LTD.	
	1	2	3	4	5	6

3.SOC PWR1



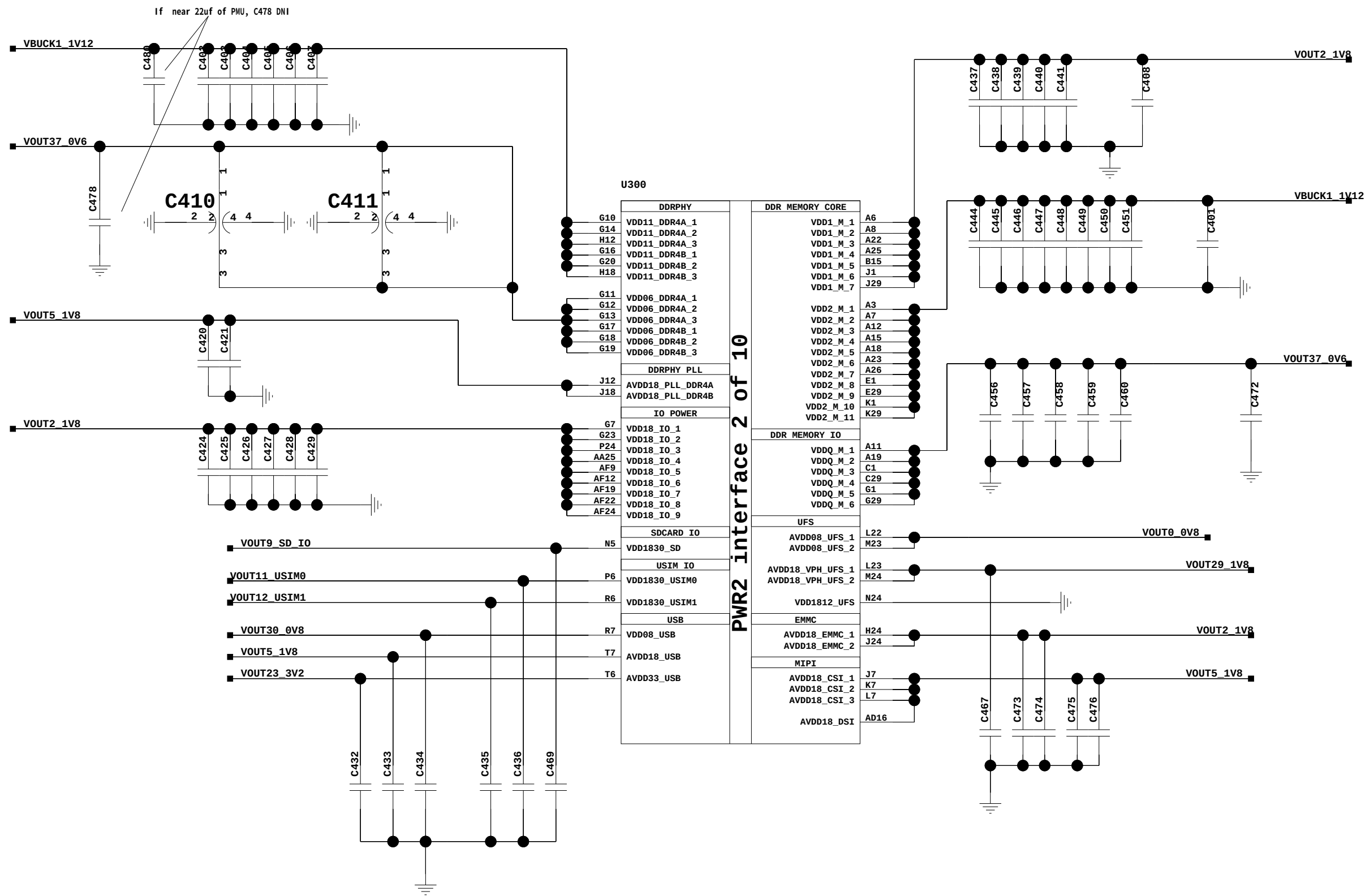
AP Temperature DET



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEEB_SOC PWR1 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

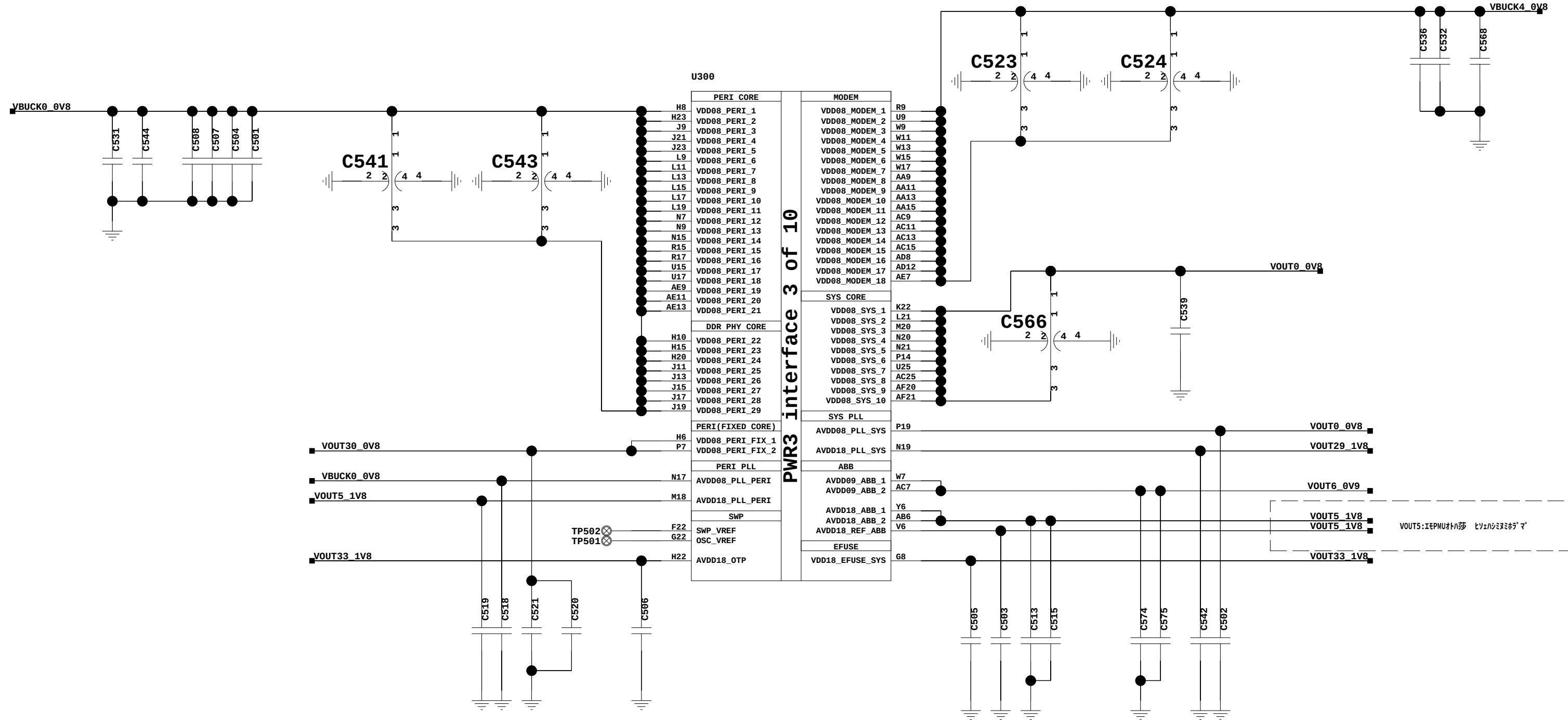
4.SOC PWR2



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 4 SOC PWR2 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

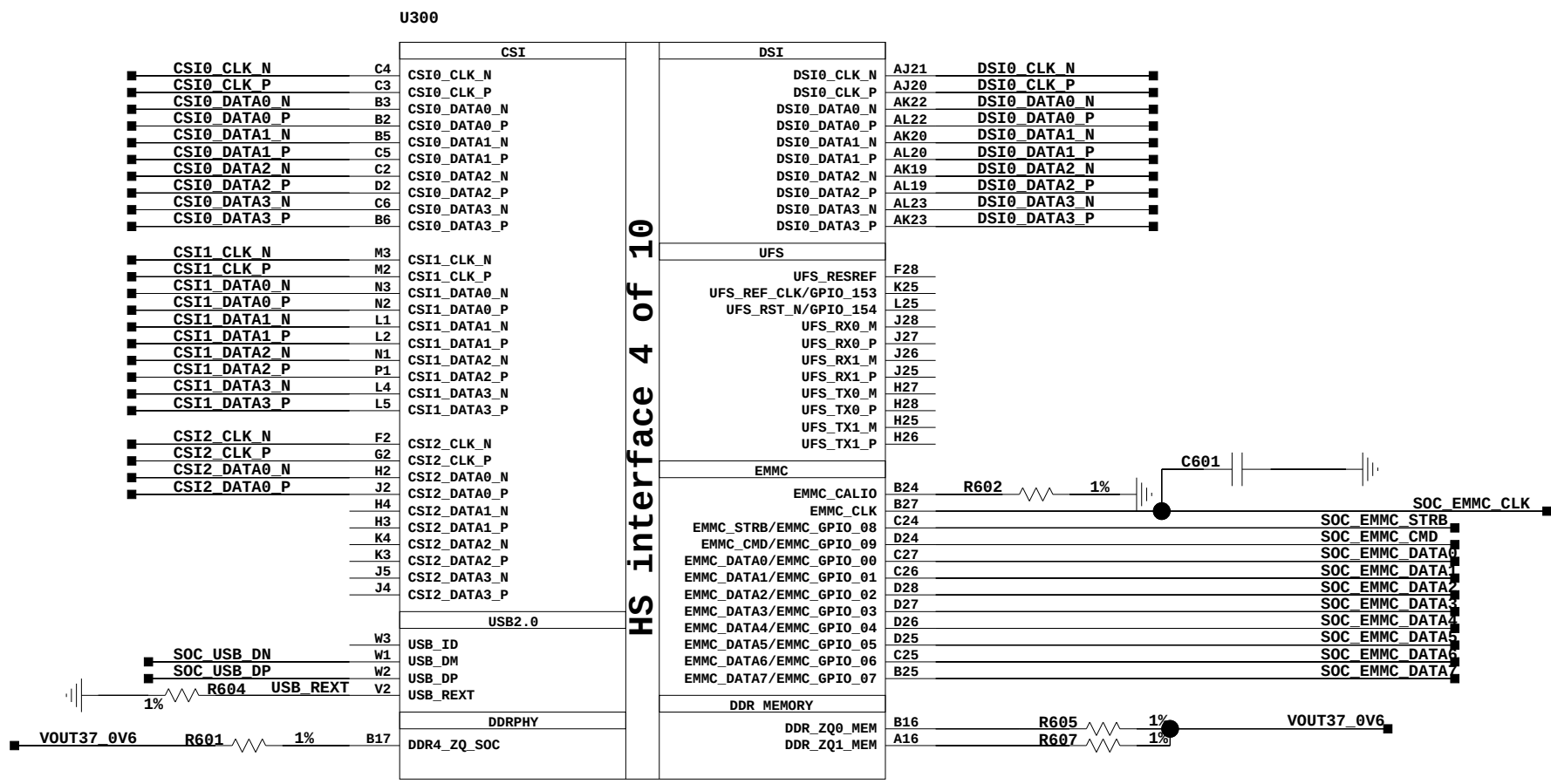
5 . SOC PWR3



The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		5_SOC_PWR3 03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	OF 60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

6.SOC HS INTERFACE



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	6	6
		E	03025GKM	HUAWEI TECH CO.,LTD.	

7.SOC GPIO INTERFACE1

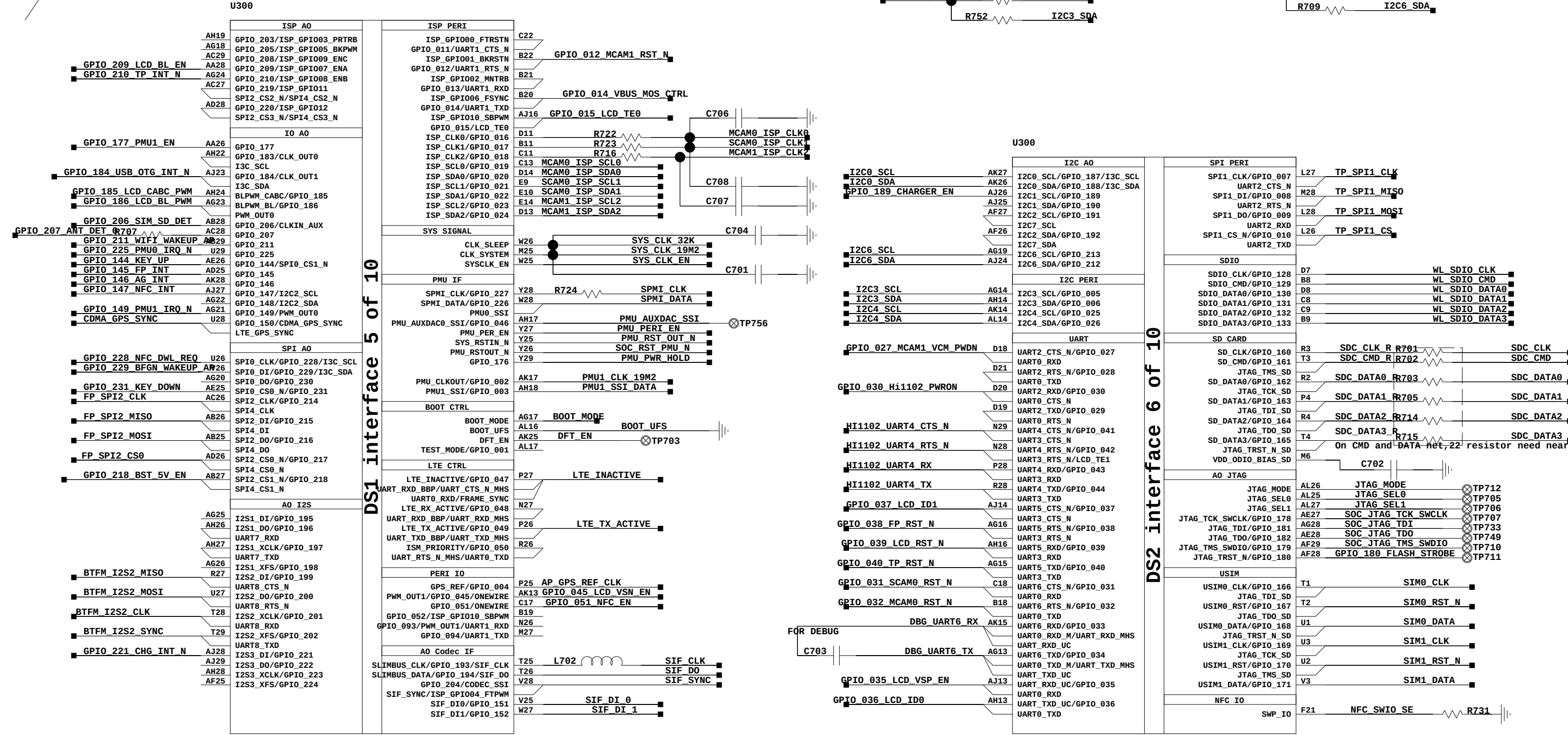
A

B

C

D

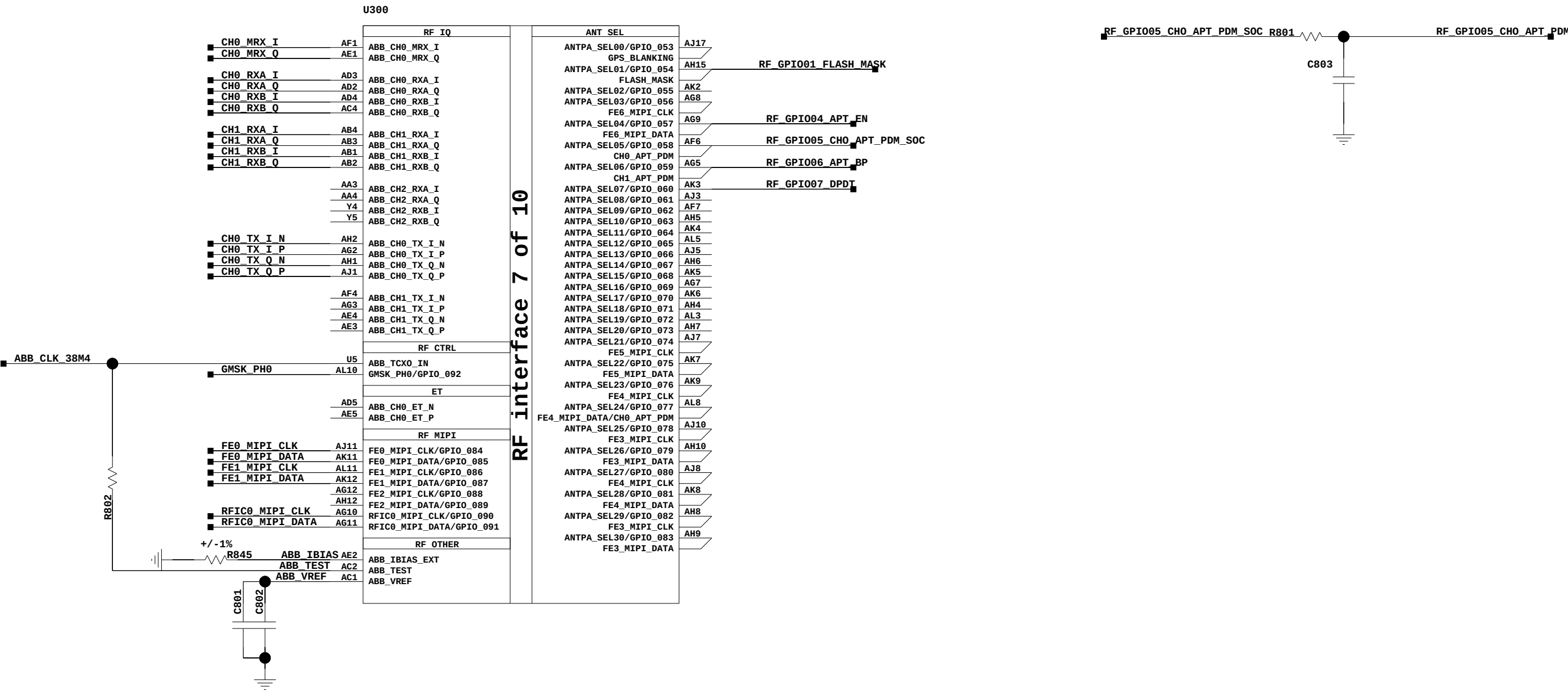
This TP Type Use For BGA Fanout



The type and specification of the components refer to the BOM

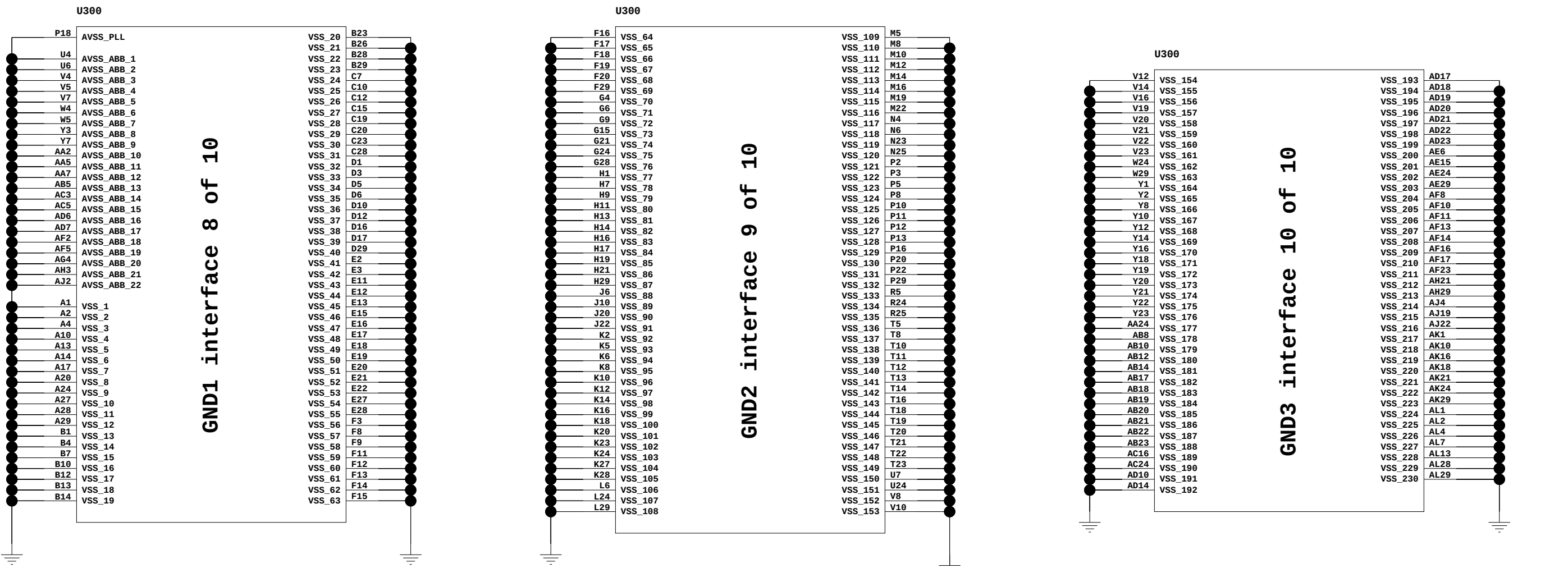
					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	7_S00E3PIO Interfac00	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

8.SOC RF INTERFACE



The type and specification of the components refer to the BOM					
					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	8 SOC RF Interface 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

9.SOC GND



The type and specification of the components refer to the BOM					
					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	9_S006END60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

10. PMU LDO

U1001

Misc1 Interface 1 of 4

Output default current TYP voltage function

Output	default	current	TYP voltage	function
LD01	OFF	350	1.09	RFIC0 AVDD
LD02	ON	900	1.8	PMU dig/RFIC/SOC1V8IO/64031V8/LPDDR4X VDD/UFS
LD03	OFF	200	1.8	RFIC0 AVDD2
LD04	OFF	200	1.8	LCD1V8 IO/TP1V8 IO
LD05	ON	500	1.8	PHY ANA/ABB AVDD1V8
LD08	OFF	140	1.8	6403ANALOG/CLASSD1V8
LD09	OFF	50	1.8/2.95	SD IO
LD011	OFF	50	1.8	SIM0
LD012	OFF	50	1.8	SIM1
LD013	OFF	150	2.85	S camera analog
LD014	OFF	70	2.85	RF FEM/AUXDAC
LD015	ON	800	2.95	EMMC/UFS VDD
LD016	OFF	800	2.95	SD card
LD017	OFF	100	2.8	LCD TP VCI
LD018	ON	350	1.8	fp/SENSOR IO FP AVDD/CON IO/NFC IO
LD019	OFF	300	2.8	M camera anlog
LD020	OFF	400	1.11	M Camera Core
LD021	OFF	180	1.8	Camera io
LD022	OFF	150	2.8	Back Camera Analog
LD023	ON	150	3.2	HKADC
LD024	ON	200	2.8	X Sensor AVDD
LD025	OFF	400	2.85	Camera VCM
LD026	ON	30	1.35	38.4 AVDD
LD027	ON	50	1.8	HKADC
LD028	OFF	50	1.8	RF MIPI I/O
LD029	ON	140	1.8	UFS PHY/SYS CLK BUF
LD030				
LD031	OFF	300	3.0	Vibrator
LD032	OFF	400	1.1	S Camera Core
LD033	OFF	120	1.8	EFUSE
LD034	ON	150	3.45	CODEC RCV/MICBIAS

The type and specification of the components refer to the BOM

DESIGNED	CHENZHENBIN 00264464	HL1JSNM	03025GKM_SCH1ZH
REVIEWED	MABO 00278126	VER	PART_NUMBER
		E	03025GKM
			SHEET 10_P00 LD00
			HUAWEI TECH CO.,LTD.

10. PMU LDO

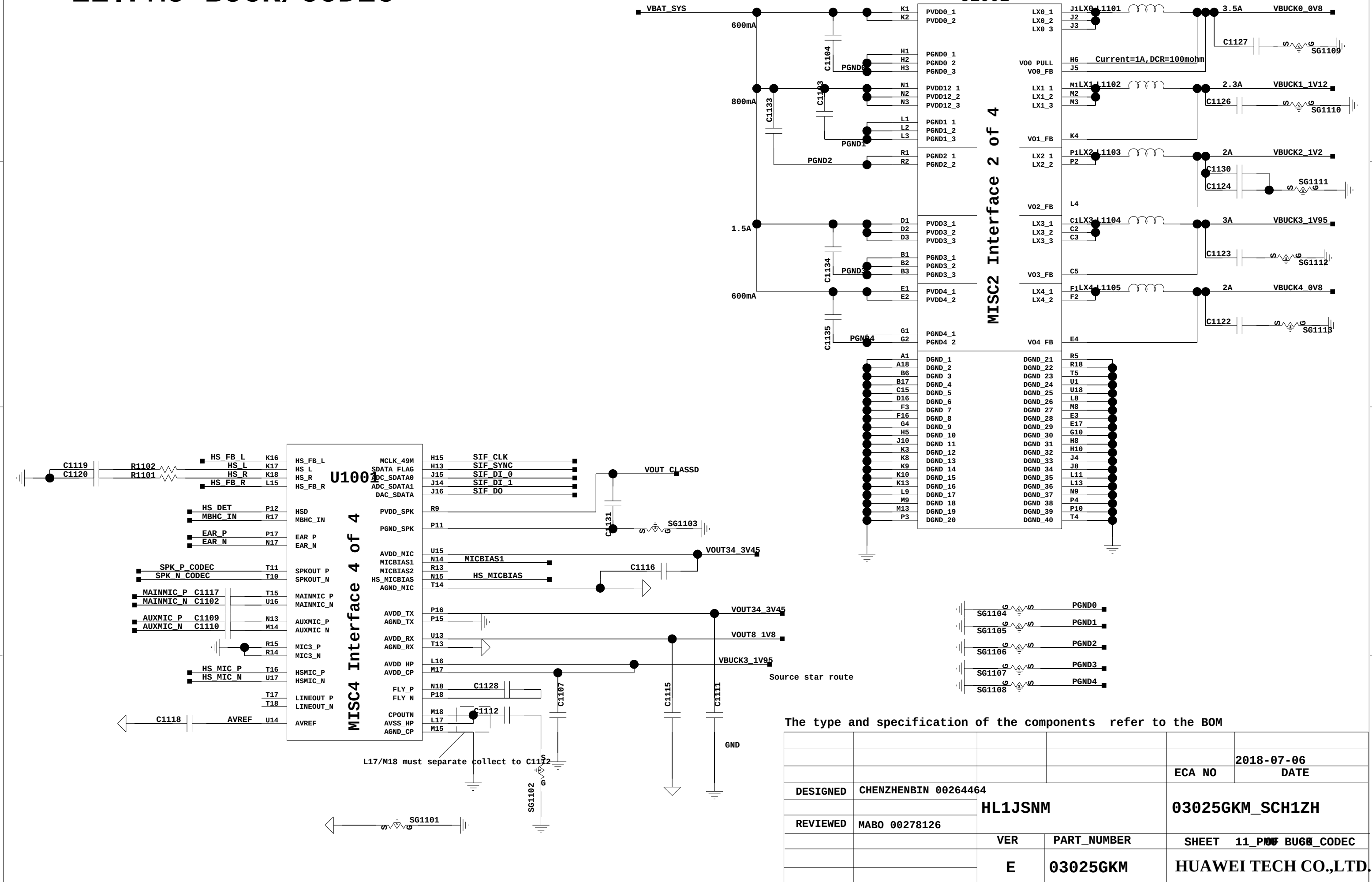
U1001

Misc1 Interface 1 of 4

Output default current TYP voltage function

Output	default	current	TYP voltage	function
LD01	OFF	350	1.09	RFIC0 AVDD
LD02	ON	900	1.8	PMU dig/RFIC/SOC1V8IO/64031V8/LPDDR4X VDD/UFS
LD03	OFF	200	1.8	RFIC0 AVDD2
LD04	OFF	200	1.8	LCD1V8 IO/TP1V8 IO
LD05	ON	500	1.8	PHY ANA/ABB AVDD1V8
LD08	OFF	140	1.8	6403ANALOG/CLASSD1V8
LD09	OFF	50	1.8/2.95	SD IO
LD011	OFF	50	1.8	SIM0
LD012	OFF	50	1.8	SIM1
LD013	OFF	150	2.85	S camera analog
LD014	OFF	70	2.85	RF FEM/AUXDAC
LD015	ON	800	2.95	EMMC/UFS VDD
LD016	OFF	800	2.95	SD card
LD017	OFF	100	2.8	LCD TP VCI
LD018	ON	350	1.8	fp/SENSOR IO FP AVDD/CON IO/NFC IO
LD019	OFF	300	2.8	M camera anlog
LD020	OFF	400	1.11	M Camera Core
LD021	OFF	180	1.8	Camera io
LD022	OFF	150	2.8	Back Camera Analog
LD023	ON	150	3.2	HKADC
LD024	ON	200	2.8	X Sensor AVDD
LD025	OFF	400	2.85	Camera VCM
LD026	ON	30	1.35	38.4 AVDD
LD027	ON	50	1.8	HKADC
LD028	OFF	50	1.8	RF MIPI I/O
LD029	ON	140	1.8	UFS PHY/SYS CLK BUF
LD030				
LD031	OFF	300	3.0	Vibrator
LD032	OFF	400	1.1	S Camera Core
LD033	OFF	120	1.8	EFUSE
LD034	ON	150	3.45	CODEC RCV/MICBIAS

11.PMU BUCK/CODEC



The type and specification of the components refer to the BOM					
				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464			03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 11_PMU BUCK/CODEC	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

12. PMU Digital

USB CON TEMP DETUSB Board ID DET

HKADC-0A±i

HKADC_IN0	APU Board ID0(RF USE)
HKADC_IN1	APU Board ID1
HKADC_IN2	APU Board ID2
HKADC_IN3	RESERVED
HKADC_IN4	PA TEMP DET0
HKADC_IN5	Charge TEMP
HKADC_IN6	USB TEMP ADC
HKADC_IN7	AP TEMP
HKADC_IN8	USB BOARD ID
HKADC_IN9	RESERVED
HKADC_IN10	BATT TEMP
HKADC_IN11	BATT ID
HKADC_IN12	HKADC_IN12_OTG
HKADC_IN13	RESERVED

R1218	Code	Value
JSN-AL/TL	07091406	200k
JSN-L21D/L31C	07092138	150k
JSN-L23C/L4	07091246	100k
Reserved	07091302	51k
Reserved	07091408	68k
Reserved	07091299	30k
Reserved	07091172	22k
Reserved	TBD	TBD

Board ID Resistor Set

ID	UP RES	DOWN RES
0	NC	0K
1	150K	22K
2	100K	30K
3	200K	100K
4	150K	121K
5	121K	150K
6	51K	100K
7	30K	100K
8	20K	150K
9	150K	NC

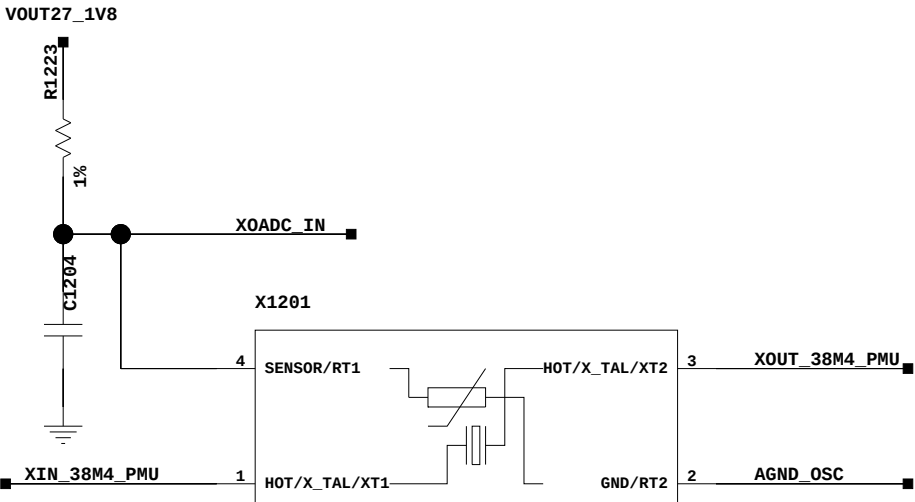
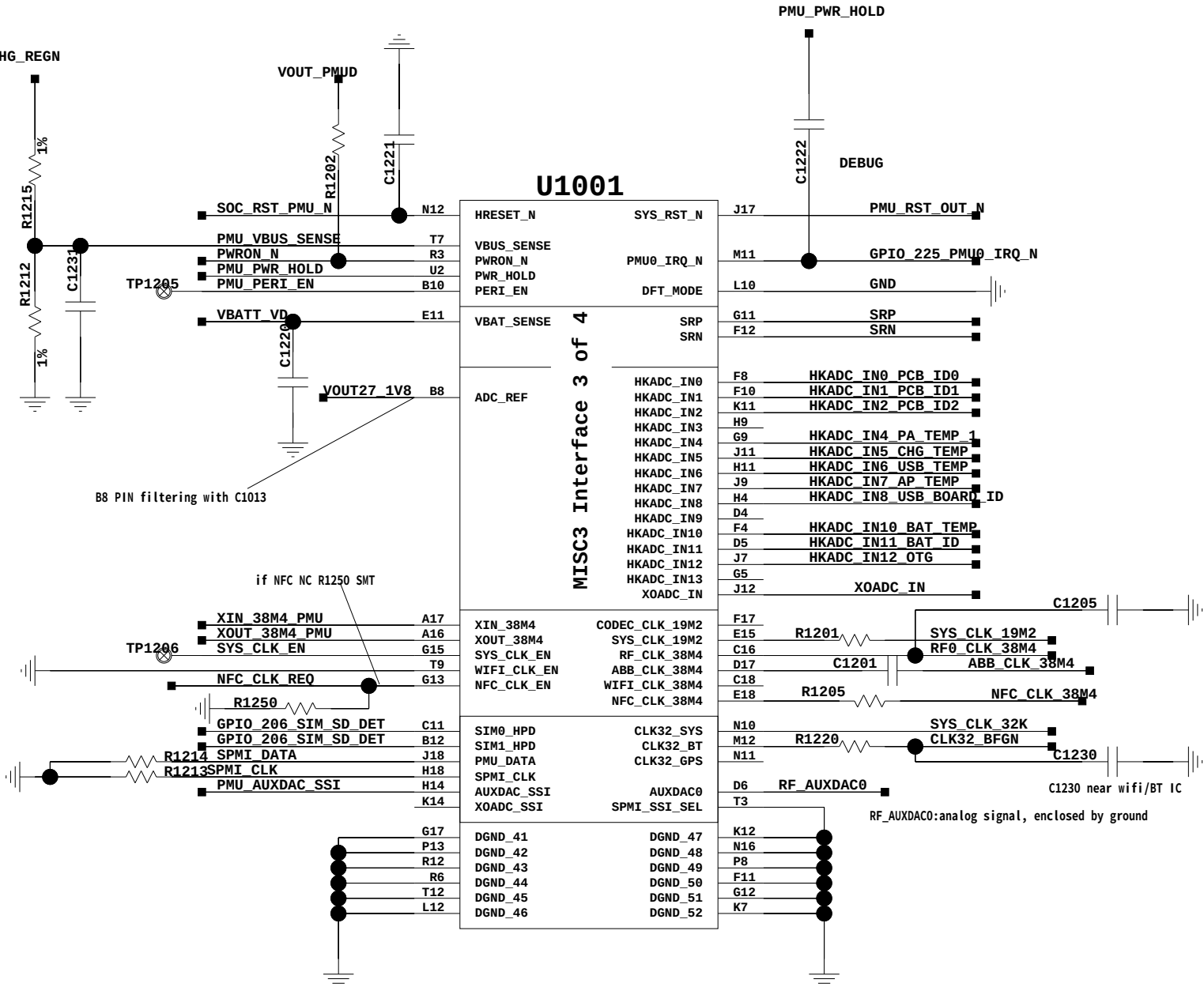
Resistor Code

0K	07090911
20K	07092448
22K	07091172
30K	07091299
51K	07091302
100K	07091246
121K	07091176
150K	07092138
200K	07091406

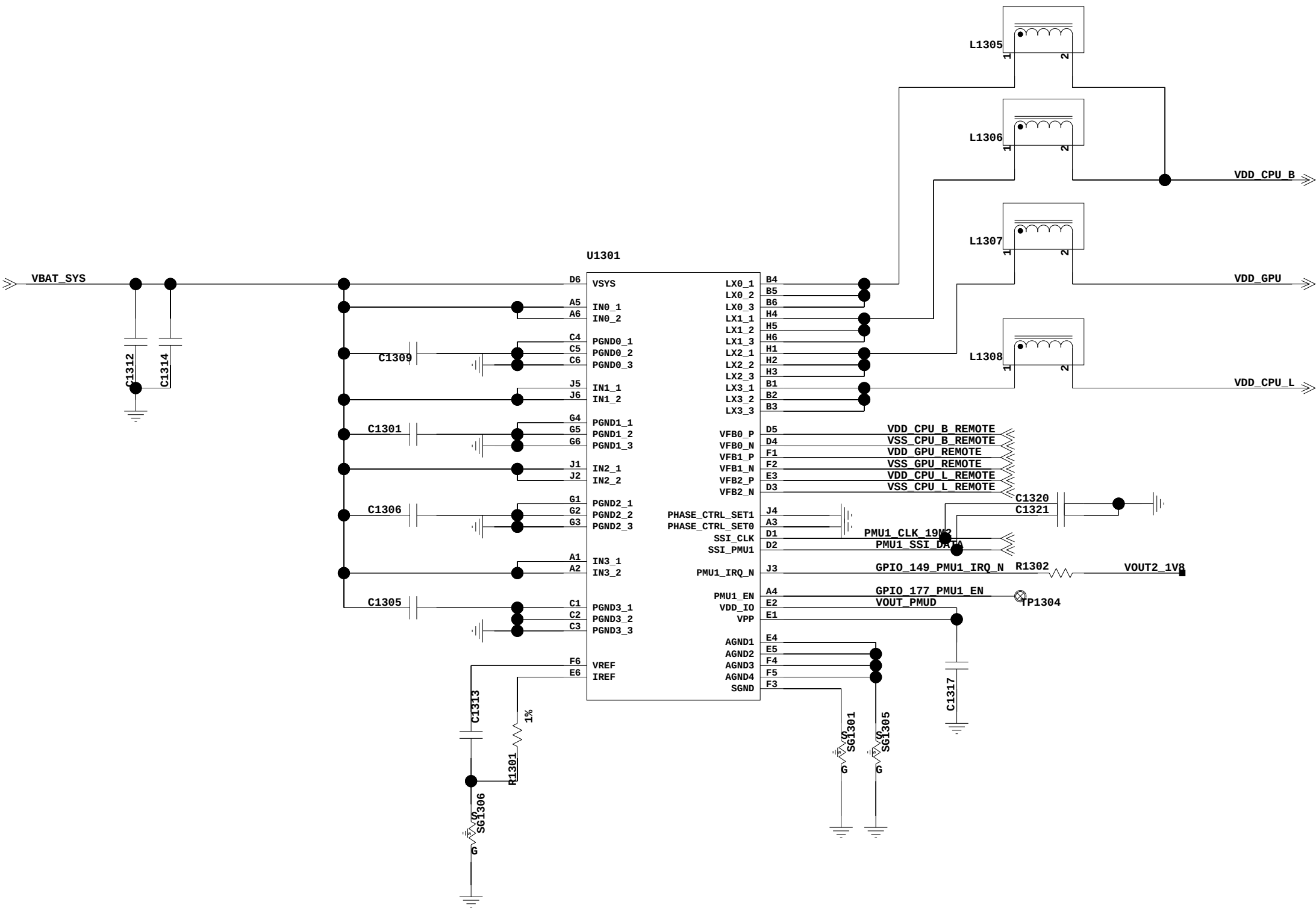
Mode	boardID	R1207	R1208	R1211	R1209	R1203	R1210	
AL00B/C/D/E L42IB/IC/ID	7606	51K	100K	NC	0	51K	100K	V1.1-V3
AL00C/E/F L42IC/ID/IE	7610	51K	100K	150K	22K	NC	0	VN1
TL00C/D L22C/L22D	7602	51K	100K	NC	0	100K	30K	V3
TL00/L22	7612	51K	100K	150K	22K	100K	30K	VN1
JSN-L21D	7607	51K	100K	NC	0	30K	100K	V3
JSN-L21C/D	7613	51K	100K	150K	22K	200K	100K	VN1
JSN-L23C	7609	51K	100K	NC	0	150K	NC	VN1
AL00C/E/F L42IC/ID/IE	7614	51K	100K	150K	22K	150K	121K	VN1.1
TL00/L22	7615	51K	100K	150K	22K	121K	150K	VN1.1
JSN-L21C/D	7616	51K	100K	150K	22K	51K	100K	VN1.1
JSN-L23C	7619	51K	100K	150K	22K	150K	NC	VN1.1

The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	15H1PMU Digital 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	



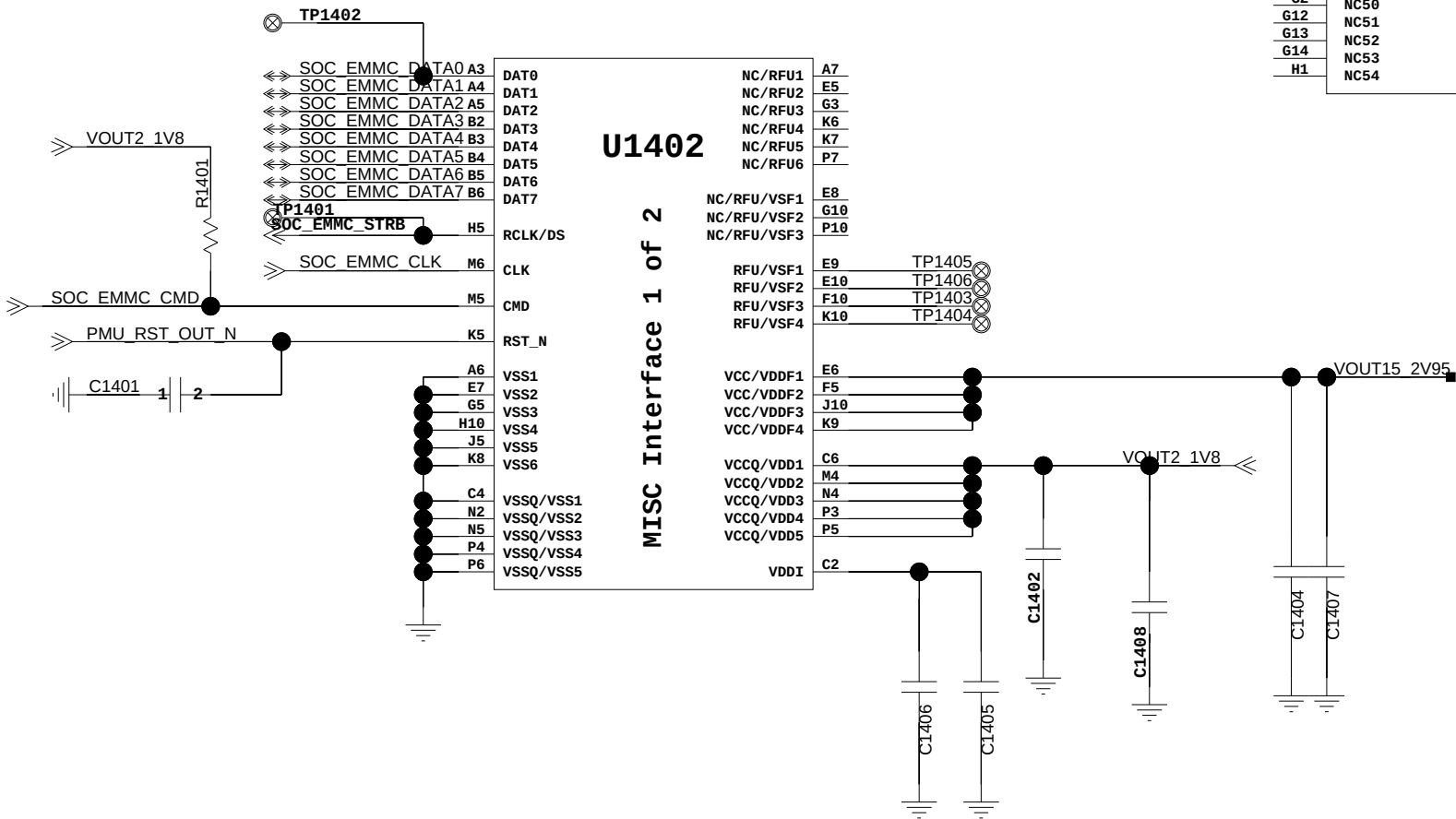
13.Hi6422



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 13_Hi642260	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

14. UFS/eMMC/DDR



A1	NC1	NC55	H2
A2	NC2	NC56	H3
A8	NC3	NC57	H12
A9	NC4	NC58	H13
A10	NC5	NC59	H14
A11	NC6	NC60	J1
A12	NC7	NC61	J2
A13	NC8	NC62	J3
A14	NC9	NC63	J12
B1	NC10	NC64	J13
B7	NC11	NC65	J14
B8	NC12	NC66	K1
B9	NC13	NC67	K2
B10	NC14	NC68	K3
B11	NC15	NC69	K12
B12	NC16	NC70	K13
B13	NC17	NC71	K14
B14	NC18	NC72	L1
C1	NC19	NC73	L2
C3	NC20	NC74	L3
C5	NC21	NC75	L12
C7	NC22	NC76	L13
C8	NC23	NC77	L14
C9	NC24	NC78	M1
C10	NC25	NC79	M2
C11	NC26	NC80	M3
C12	NC27	NC81	M7
C13	NC28	NC82	M8
C14	NC29	NC83	M9
D1	NC30	NC84	M10
D2	NC31	NC85	M11
D3	NC32	NC86	M12
D4	NC33	NC87	M13
D12	NC34	NC88	M14
D13	NC35	NC89	N1
D14	NC36	NC90	N3
E1	NC37	NC91	N6
E2	NC38	NC92	N7
E3	NC39	NC93	N8
E12	NC40	NC94	N9
E13	NC41	NC95	N10
E14	NC42	NC96	N11
F1	NC43	NC97	N12
F2	NC44	NC98	N13
F3	NC45	NC99	N14
F12	NC46	NC100	P1
F13	NC47	NC101	P2
F14	NC48	NC102	P8
G1	NC49	NC103	P9
G2	NC50	NC104	P11
G12	NC51	NC105	P12
G13	NC52	NC106	P13
G14	NC53	NC107	P14
H1	NC54		

U1402

NC Interface 2 of 2

POP LPDDR 4X

U300_POP

GND3 interface 10 of 10

V12	VSS_154	VSS_193	AD17
V14	VSS_155	VSS_194	AD18
V16	VSS_156	VSS_195	AD19
V19	VSS_157	VSS_196	AD20
V20	VSS_158	VSS_197	AD21
V21	VSS_159	VSS_198	AD22
V22	VSS_160	VSS_199	AD23
V23	VSS_161	VSS_200	AE6
W24	VSS_162	VSS_201	AE15
W29	VSS_163	VSS_202	AE24
Y1	VSS_164	VSS_203	AE29
Y2	VSS_165	VSS_204	AF8
Y8	VSS_166	VSS_205	AF10
Y10	VSS_167	VSS_206	AF11
Y12	VSS_168	VSS_207	AF13
Y14	VSS_169	VSS_208	AF14
Y16	VSS_170	VSS_209	AF16
Y18	VSS_171	VSS_210	AF17
Y19	VSS_172	VSS_211	AF23
Y20	VSS_173	VSS_212	AH21
Y21	VSS_174	VSS_213	AH29
Y22	VSS_175	VSS_214	AJ4
Y23	VSS_176	VSS_215	AJ19
AA24	VSS_177	VSS_216	AJ22
AB8	VSS_178	VSS_217	AK1
AB10	VSS_179	VSS_218	AK10
AB12	VSS_180	VSS_219	AK16
AB14	VSS_181	VSS_220	AK18
AB17	VSS_182	VSS_221	AK21
AB18	VSS_183	VSS_222	AK24
AB19	VSS_184	VSS_223	AK29
AB20	VSS_185	VSS_224	AL1
AB21	VSS_186	VSS_225	AL2
AB22	VSS_187	VSS_226	AL4
AB23	VSS_188	VSS_227	AL7
AC16	VSS_189	VSS_228	AL13
AC24	VSS_190	VSS_229	AL28
AD10	VSS_191	VSS_230	AL29
AD14	VSS_192		

eMMC 5.1

64GB 40061006

128GB 40061007

LPDDR4X

4GB 40020492

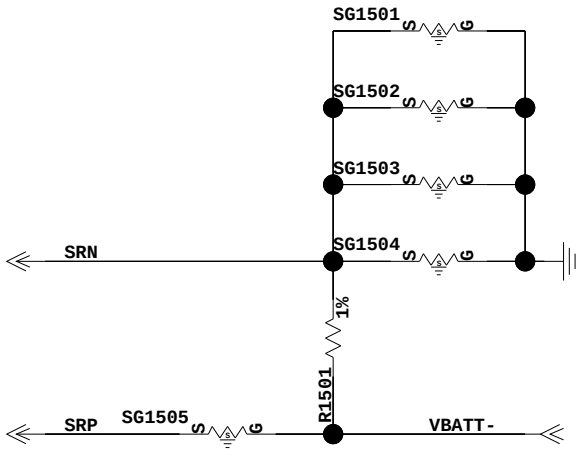
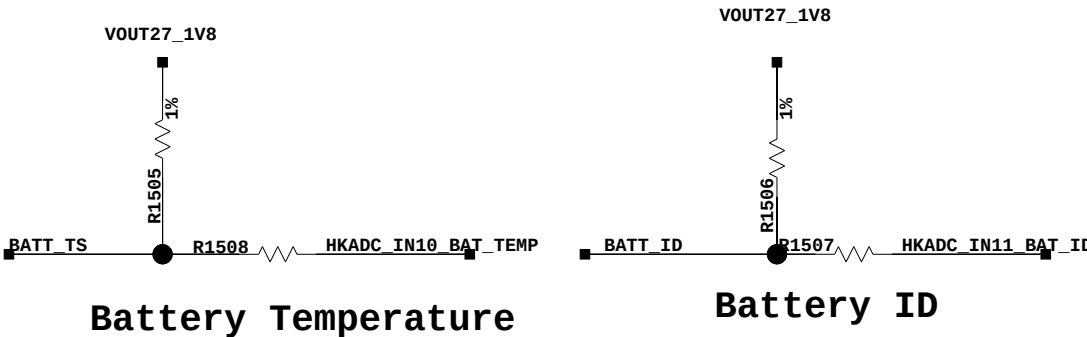
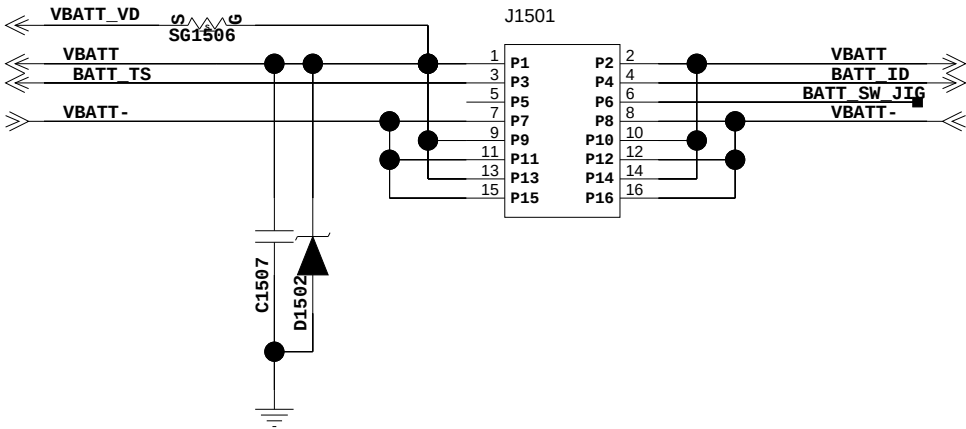
6GB 40020493

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 4 eMMC/DDR 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

15. Battery & Fuel guage

Battery Connector



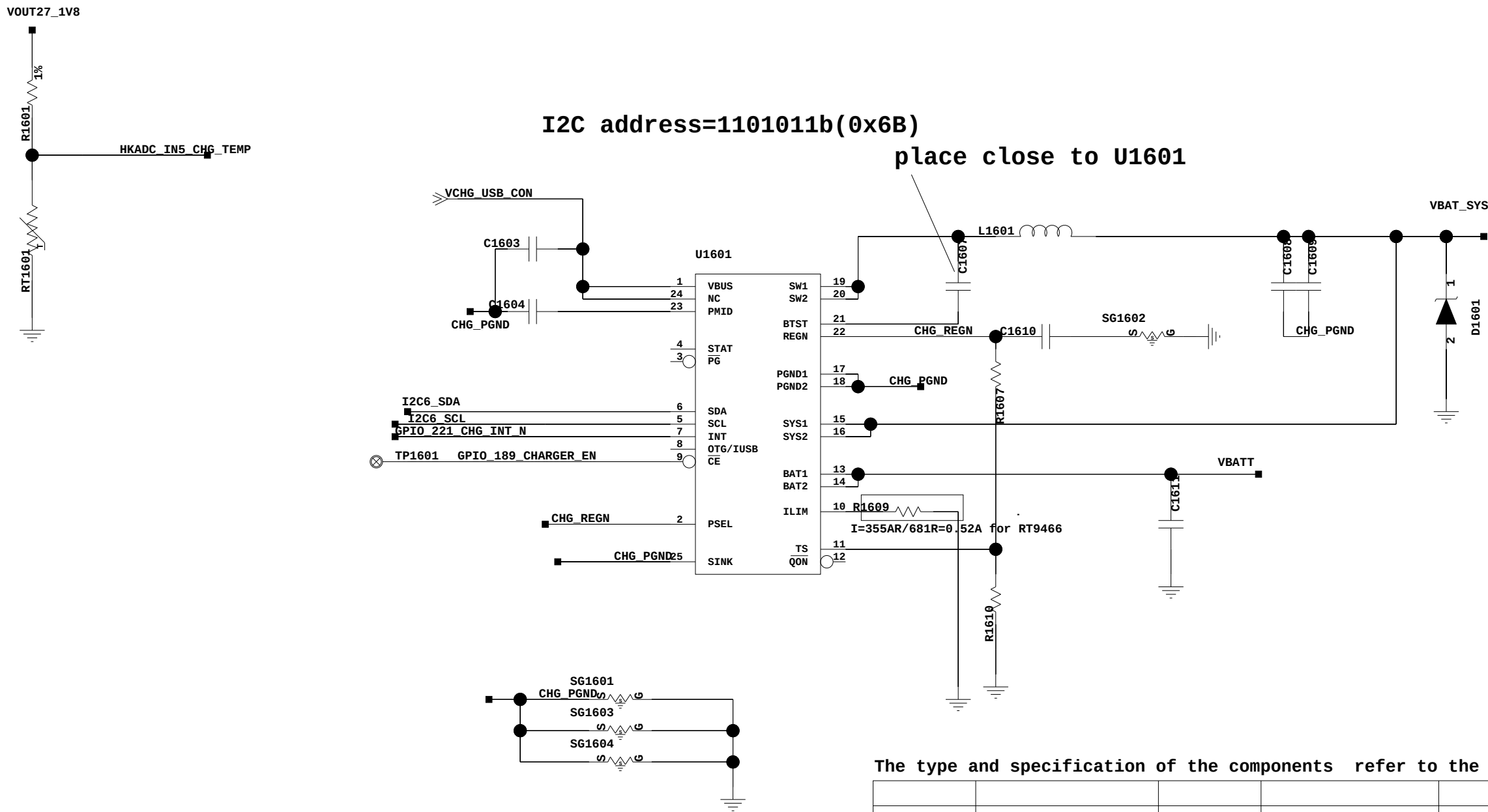
CAD note:1.Trace for 6A
2.Differential trace

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET5_Battery	60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

16. Charge Management

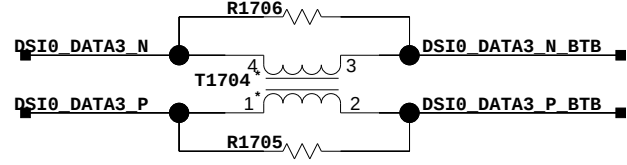
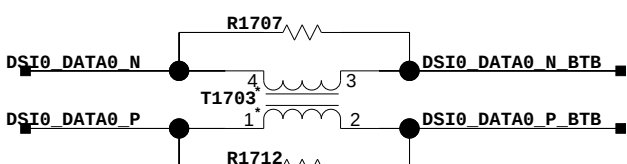
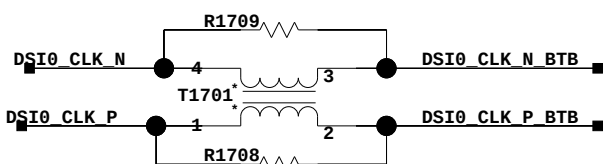
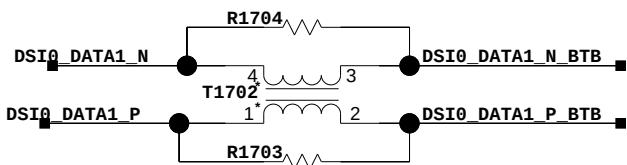
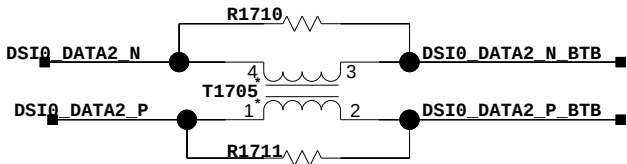
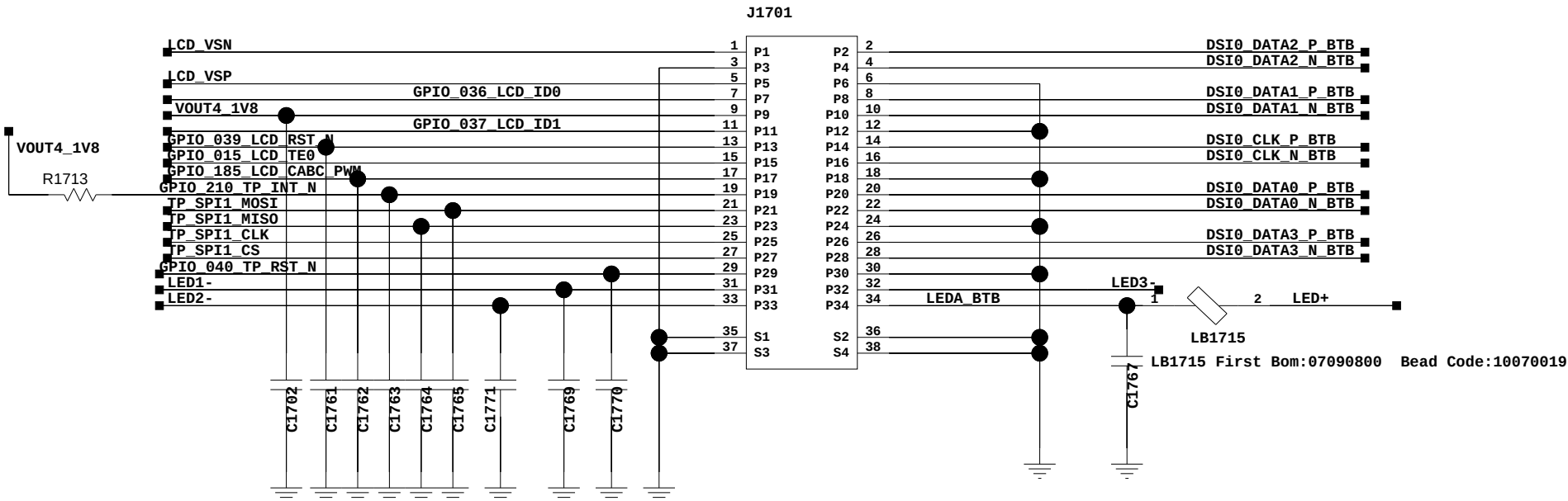
Charger IC



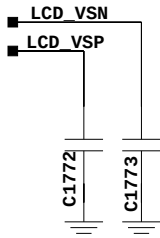
The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHE Charge of 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

17. LCD and TP INTERFACE

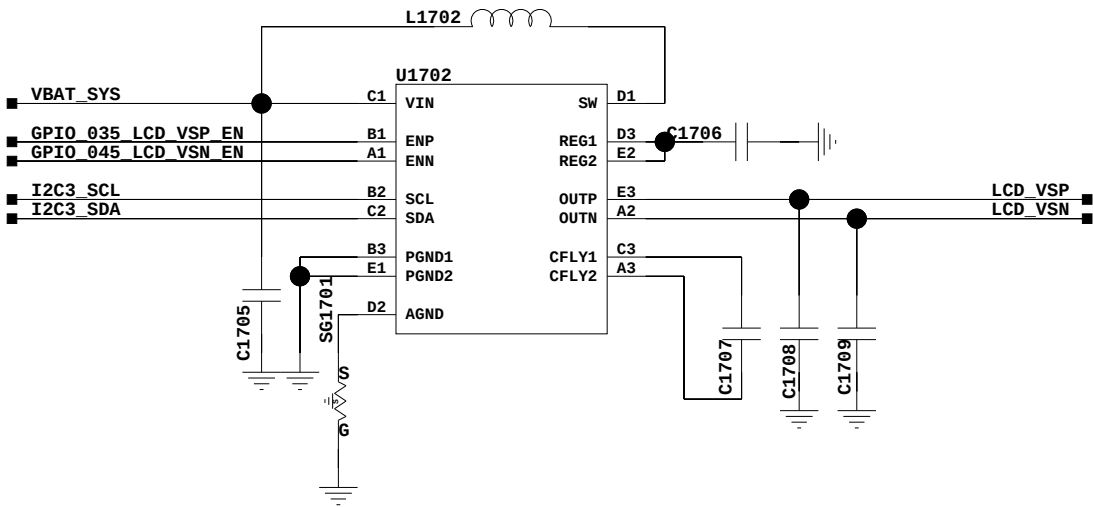


Johnson I/F at V0 and V1 stage



LCD POS/NEG Voltage Driver

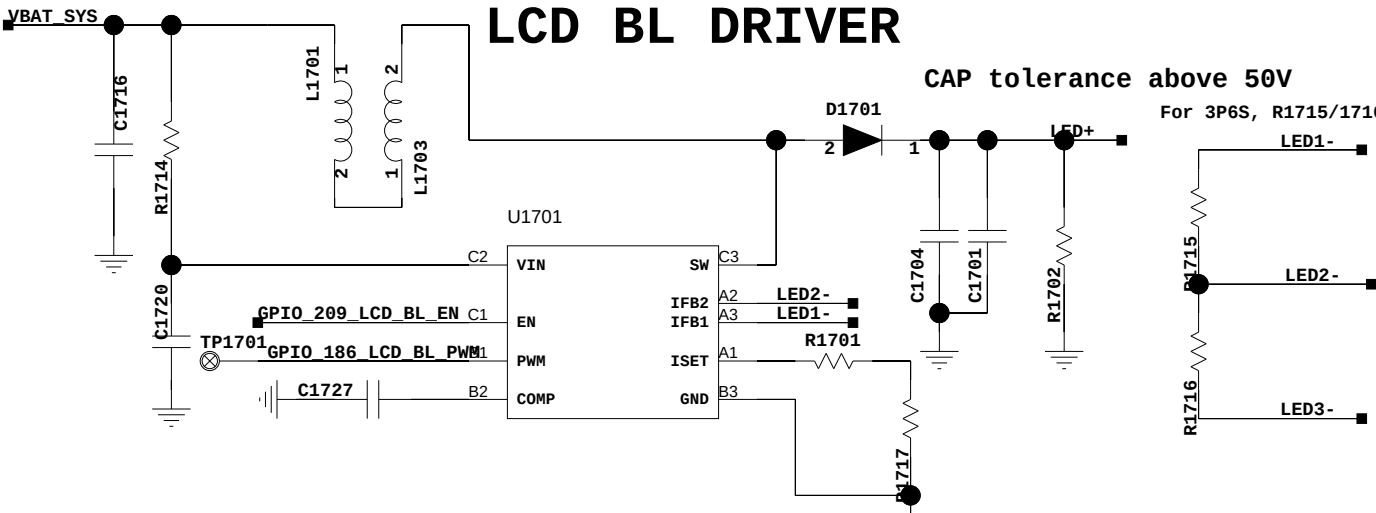
modularization ok



LCD BL DRIVER

CAP tolerance above 50V

For 3P6S, R1715/1716 can DNI when 2P9S

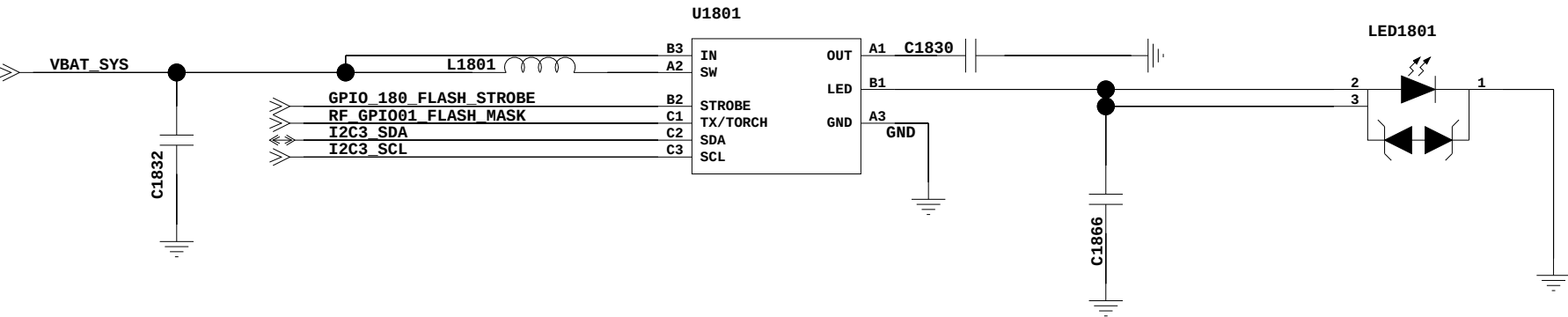


	2P9S	3P6S
R1715	DNI	R1715
R1716	DNI	R1716
R1717	07001300	07001299
R1701	07001400	07001250
L1701	SMT	DNI
R1718	DNI	SMT

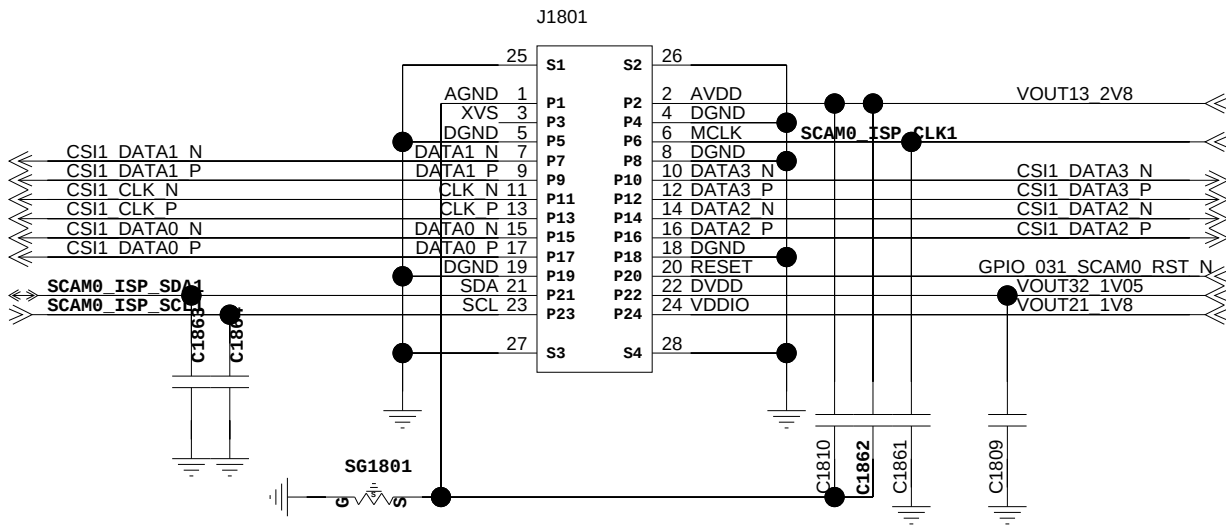
The type and specification of the components refer to the BOM

				2018-07-06	
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET17_LCD OF 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

18. Flash/front Camera



Front SUB Camera
16M Sub 23060300 Max Mated High=0.8mm

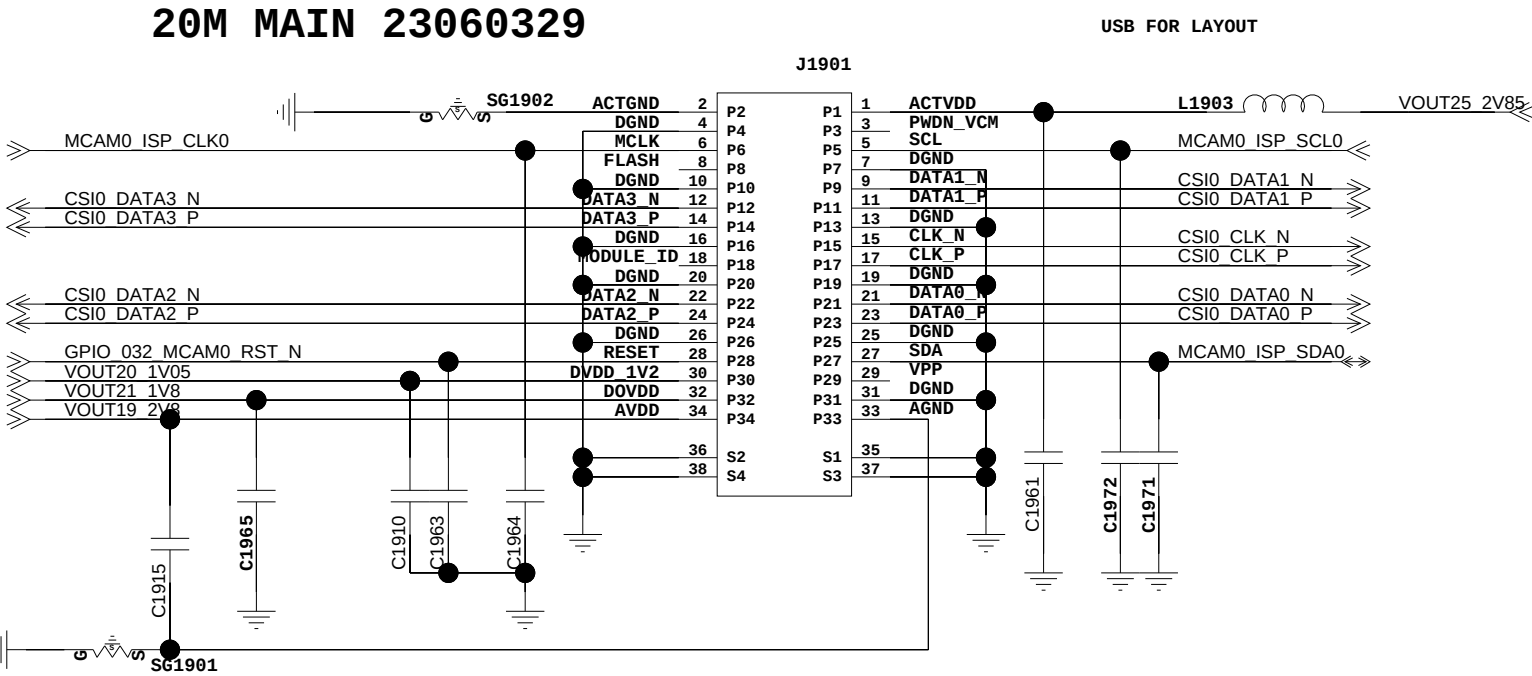


The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	18-Flash/FrontCamera	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

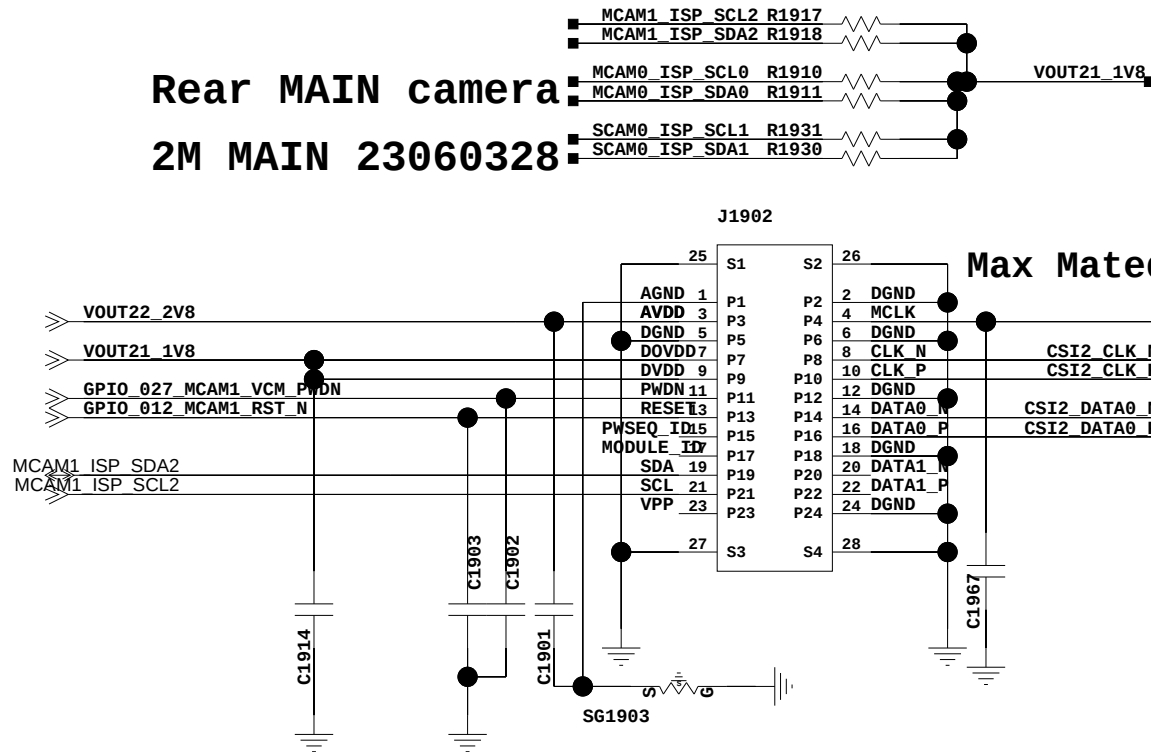
CAD note: C1825 & C1821 must close to J1802

19. M0/M1



Rear MAIN camera

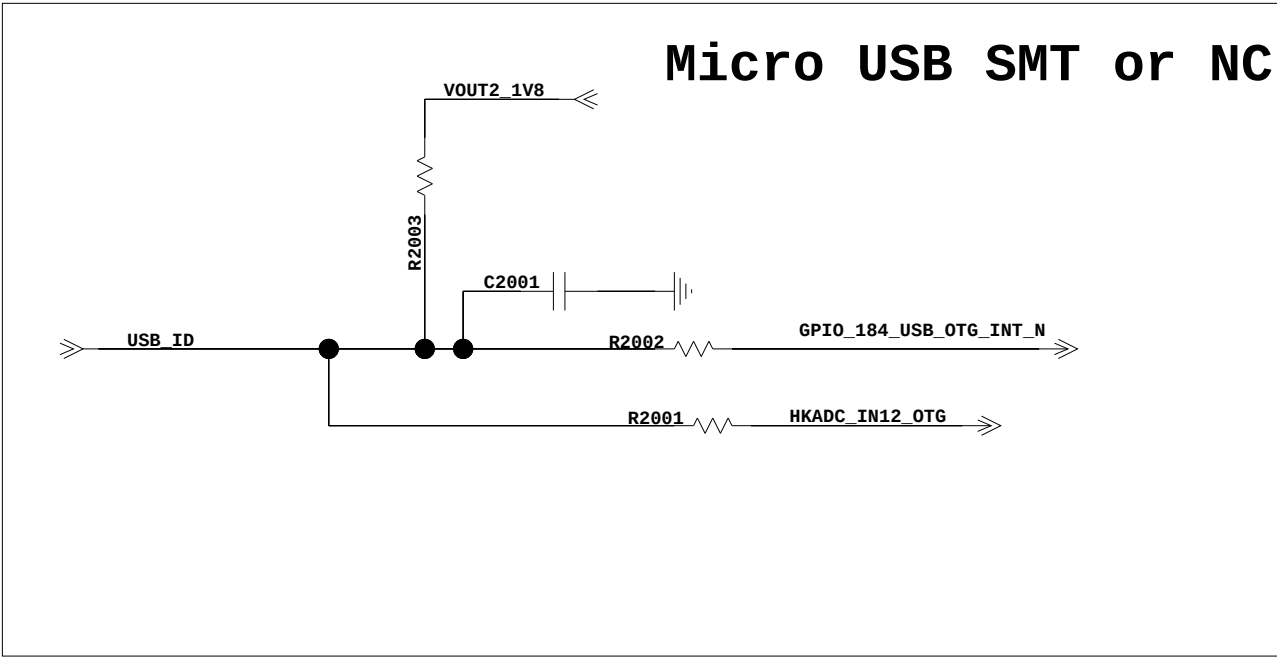
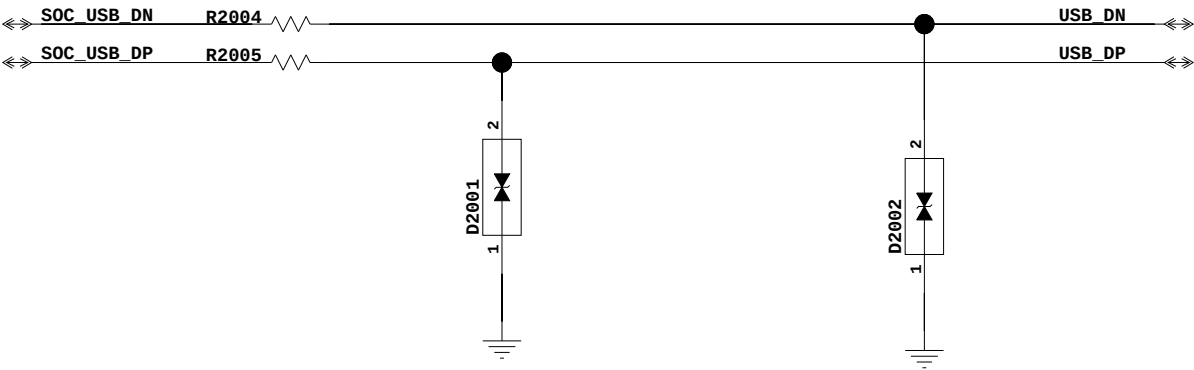
2M MAIN 23060328



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SUB Main Camera 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

20. USB

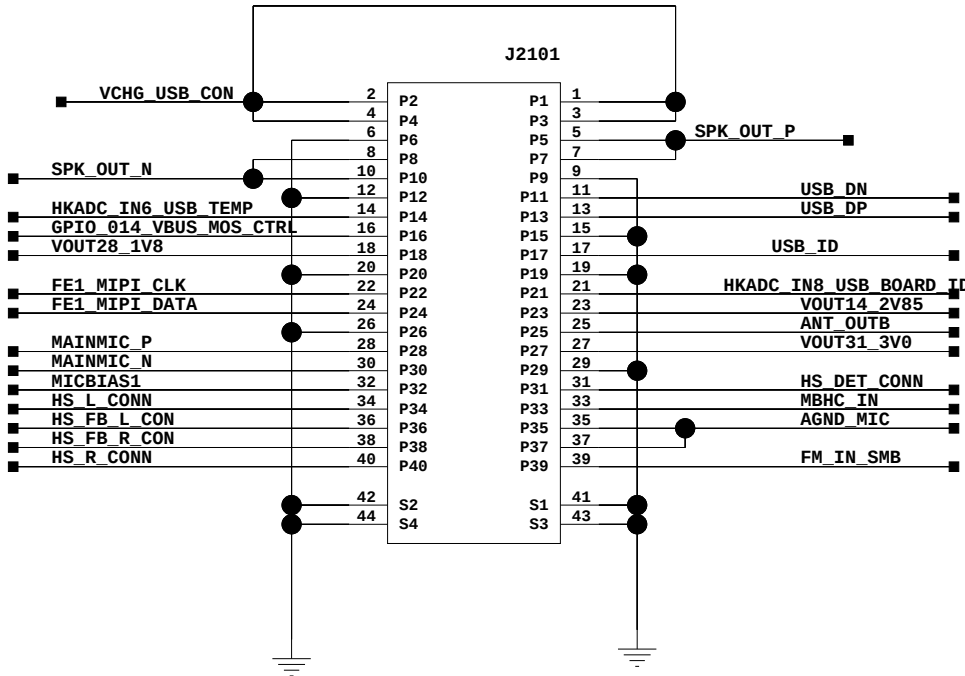


The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	2018-07-06	60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

21. Main FPC

Main FPC BTB



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET Main FPC OF 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

22. MIPI_SW

The type and specification of the components refer to the BOM

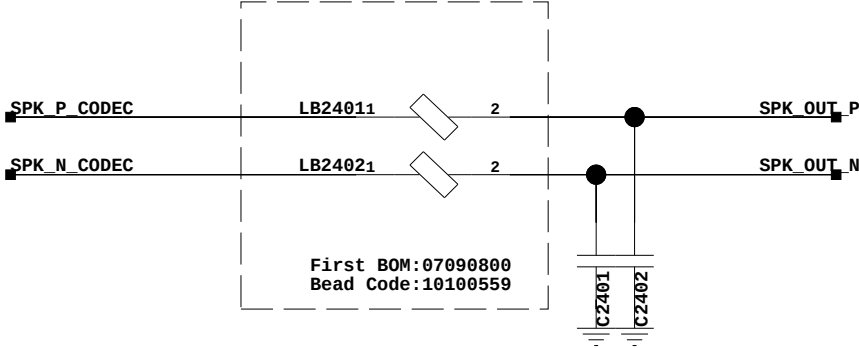
				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	22_MIPI_SW0
		E	03025GKM	HUAWEI TECH CO.,LTD.	

23. SC Charge

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	23_NOF 60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

24. SPK_PA

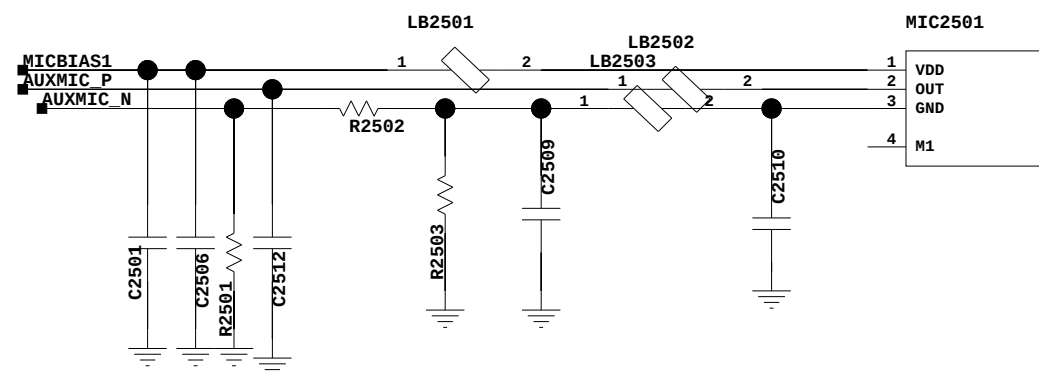


The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	24_SPK_PA60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

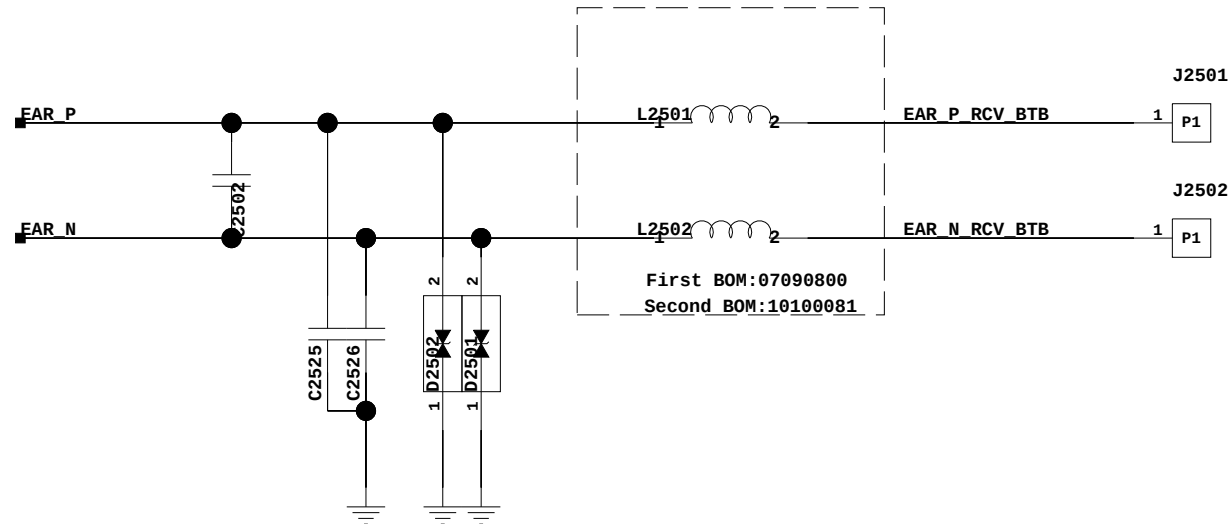
25. MIC/RCV

Second MIC



CAD note: 1, MIC need differential trace
2, MIC GND pad need use cycle via to GND net.

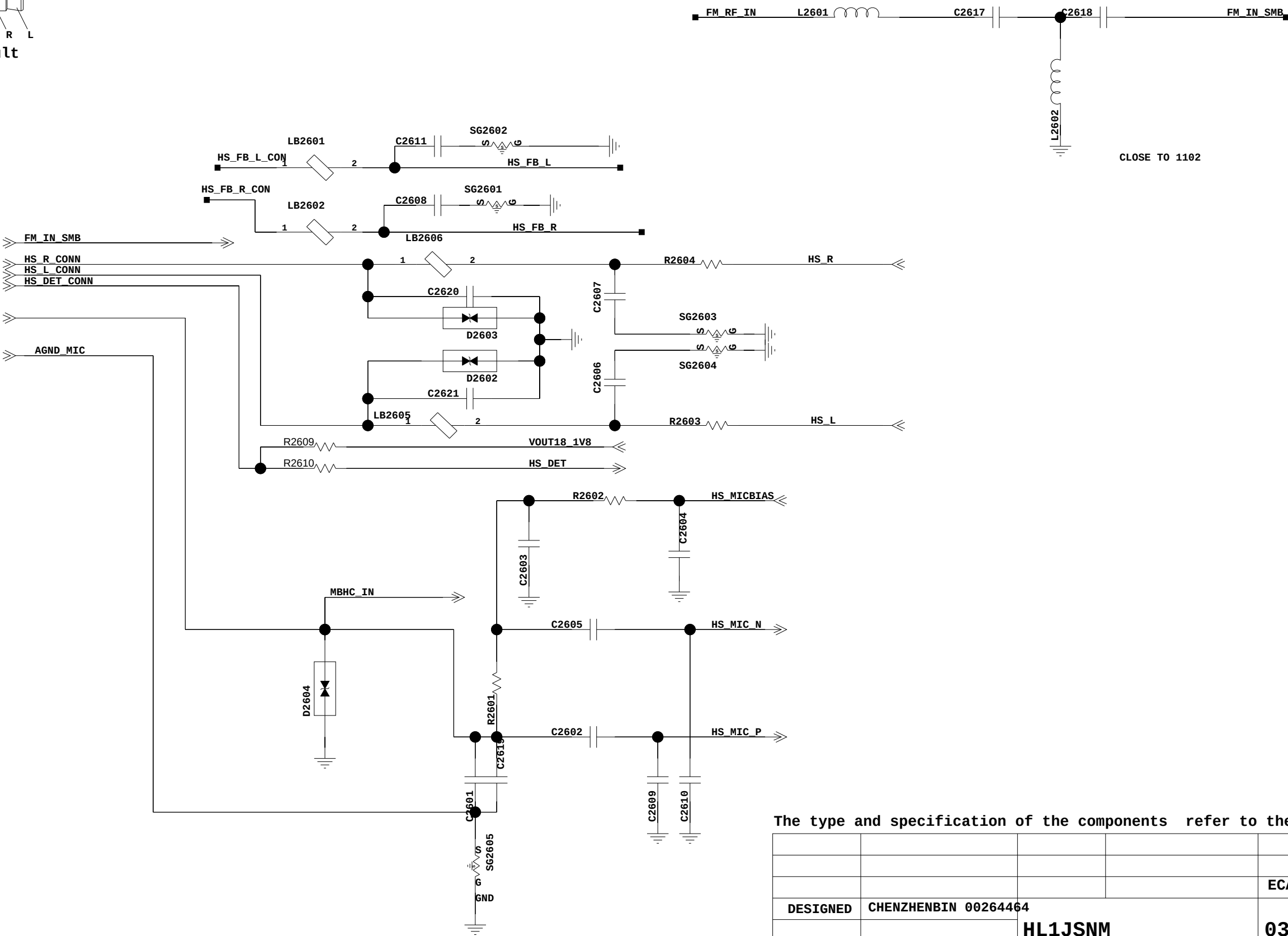
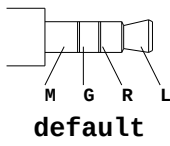
RCV



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	25. MIC/RCV OF 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

24. SPK SMART PA

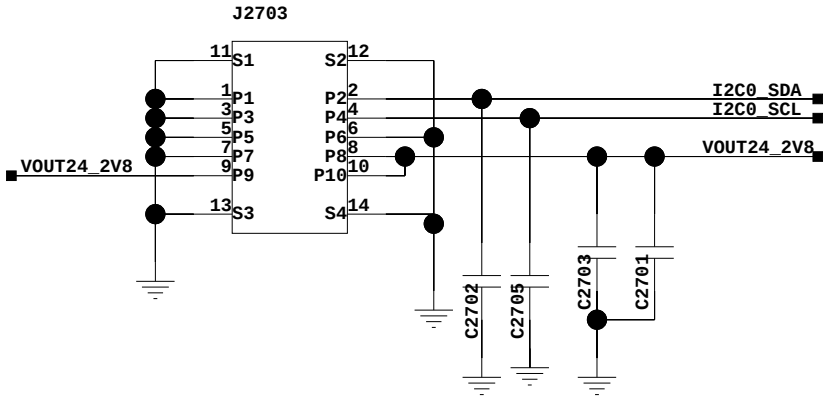


The type and specification of the components refer to the BOM

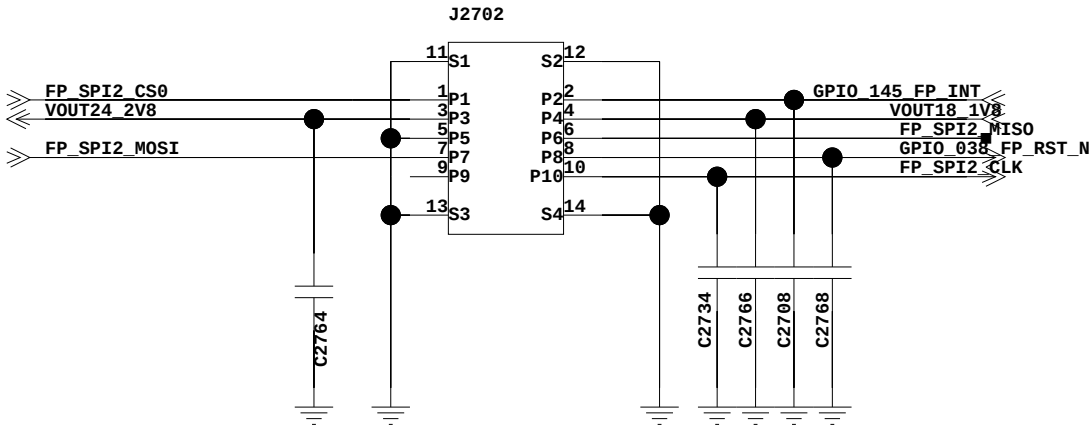
				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126			SHEET 26_Ho	
		VER	PART_NUMBER	03025GKM	
		E		HUAWEI TECH CO.,LTD.	

27. X-Sensor

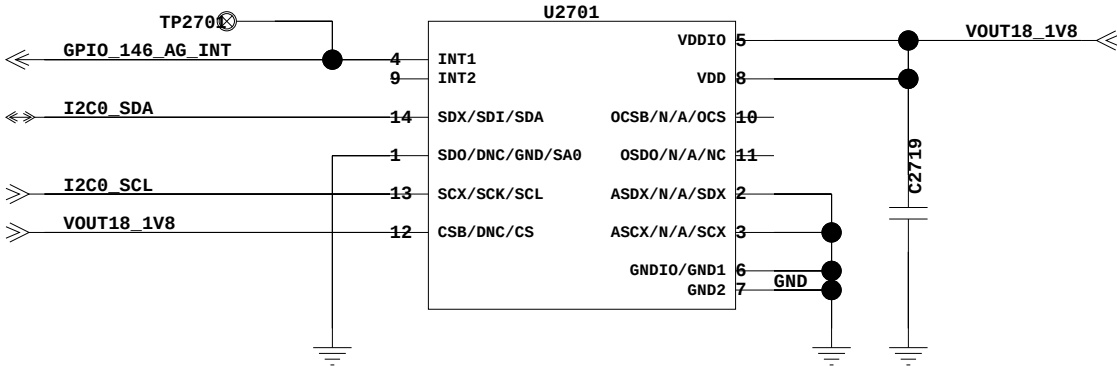
PROXIMITY&RGB AMBIENT Sensor



FingerPrint ZIF

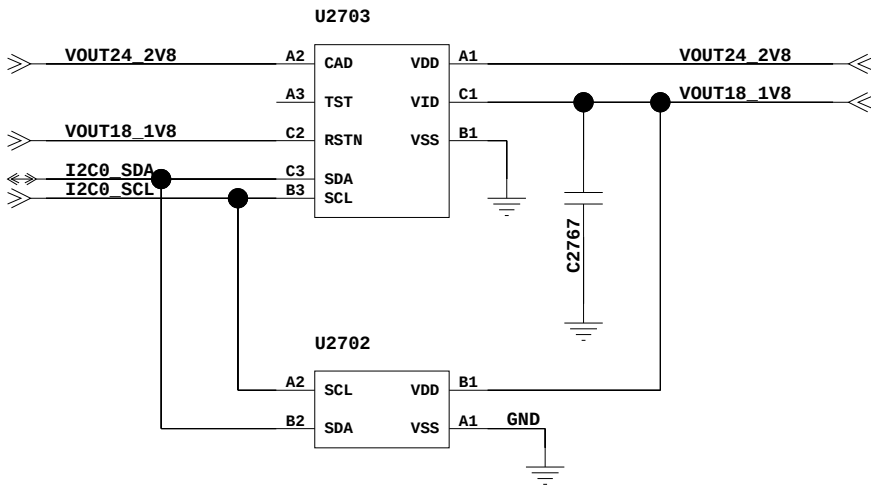


Accelerometer and Gyroscope 6-AXIS SENSOR



Compass

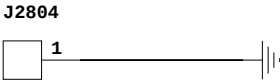
modularization ok



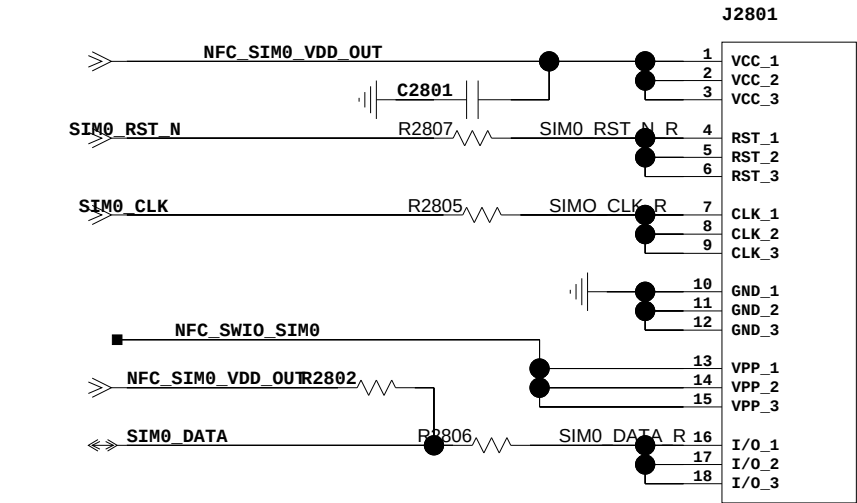
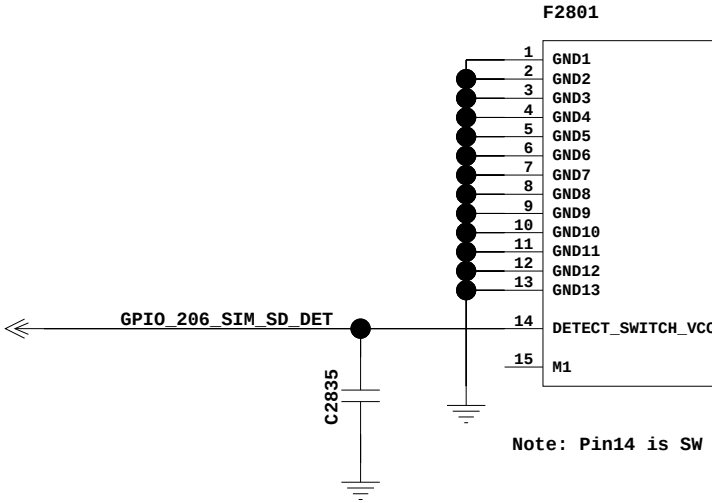
The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET-SensorOF 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

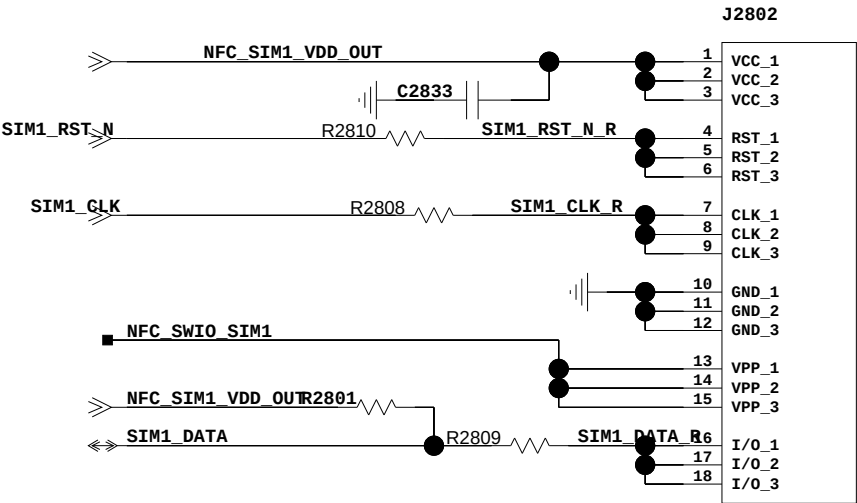
28.SIM/uSD Card



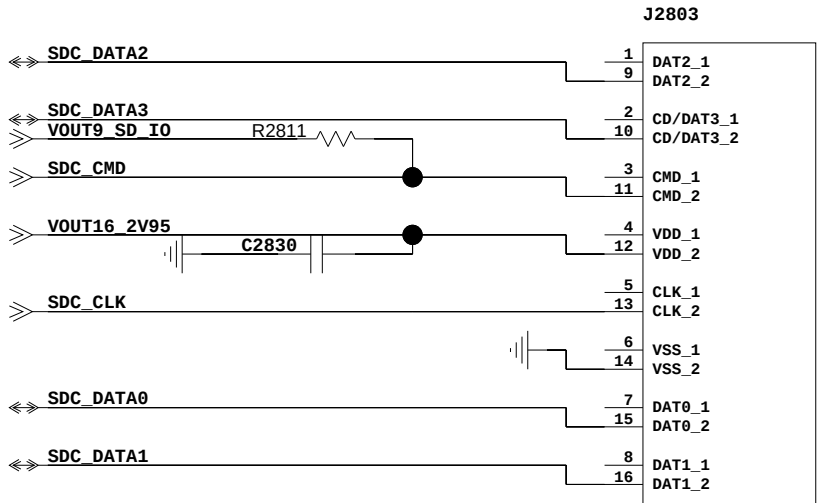
Holder



SIM0



SIM1



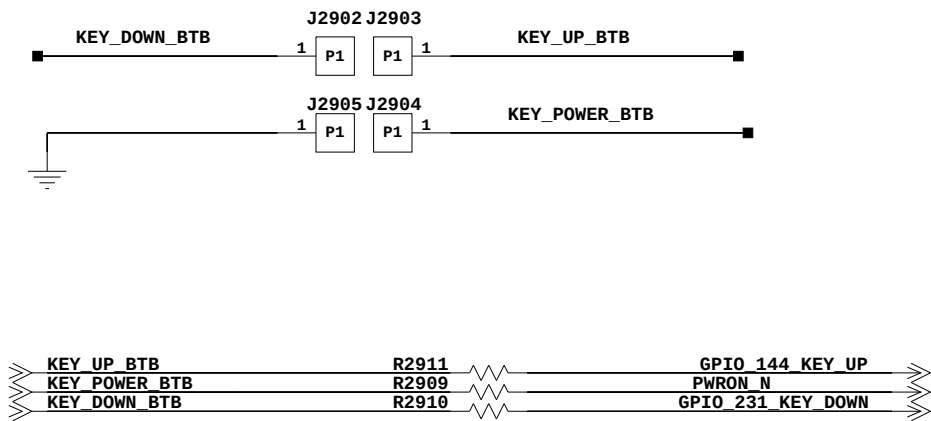
Micro SD

The type and specification of the components refer to the BOM

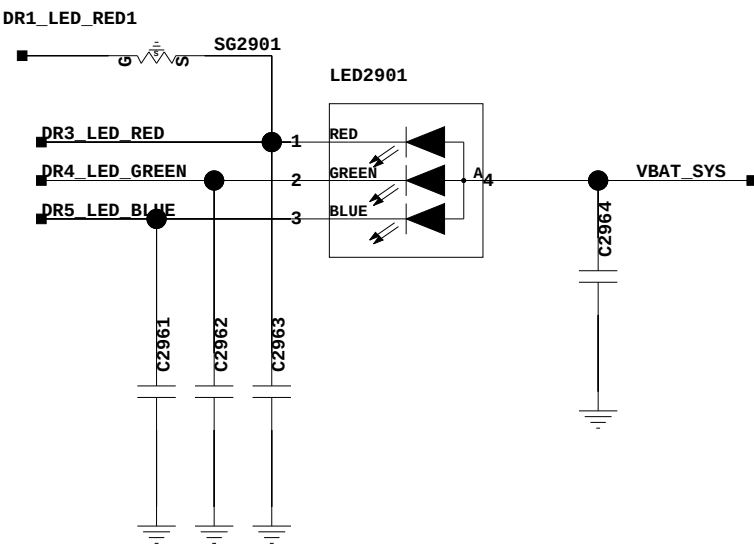
				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	28_SIM/uSD Card
		E	03025GKM	HUAWEI TECH CO.,LTD.	

29. LED/Key

KEY BTB



RGB LED



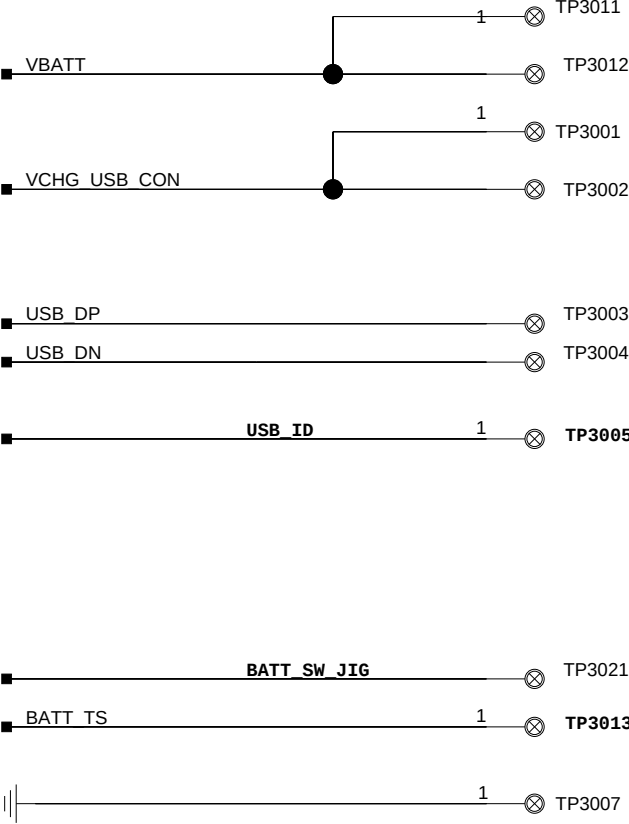
The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHENZHEN LED/Key	60
		E	03025GKM	HUAWEI TECH CO.,LTD.	

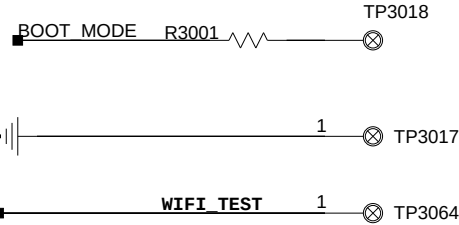
30. Test Points/Shields

CBT/PT

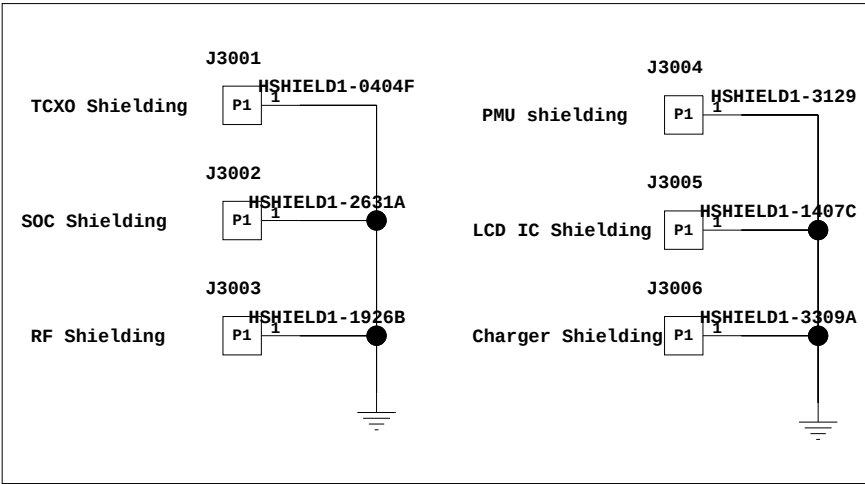
VBATT must route to D1502



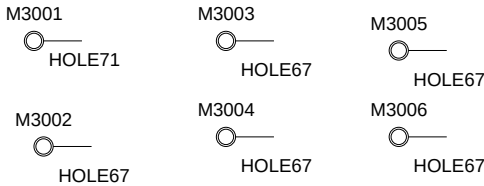
BOOT MODE



Shielding



HOLE



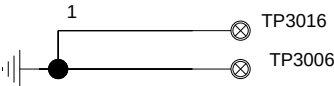
FUNCTION TEST

LCD BL



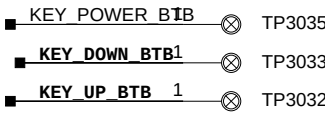
MICBIAS

GND



HEADPHONE

KEY



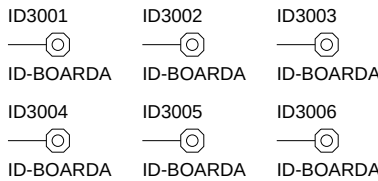
SPK

TYPE CC

VIBRATOR

RCV

MARK POINT



The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	30_1381	30_1381
		E	03025GKM	HUAWEI TECH CO.,LTD.	

31.RF Interface

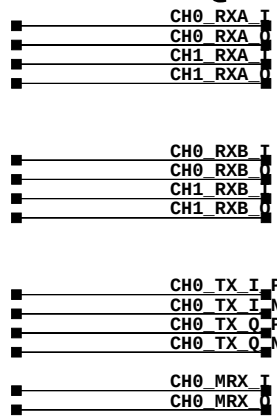
A

B

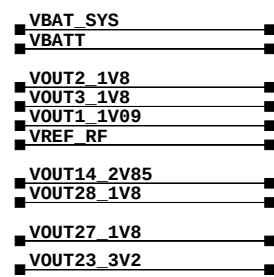
C

D

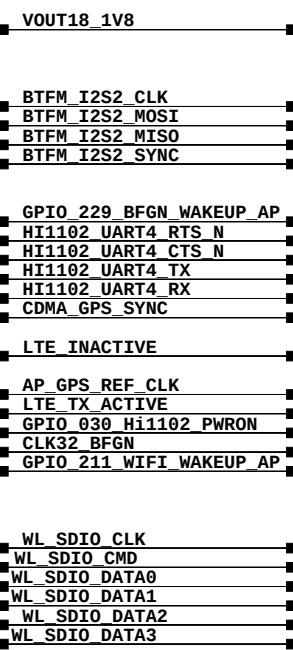
RFIC IQ



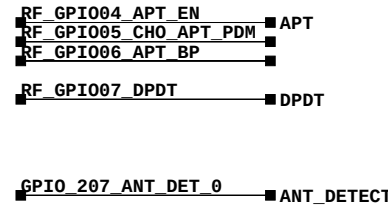
POWER



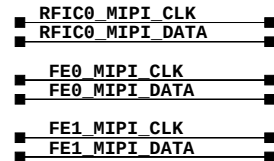
NC Interface



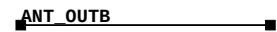
GPIO Interface



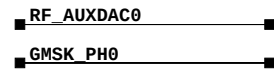
MIPI Interface



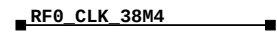
ANT Interface



GSM



CLK



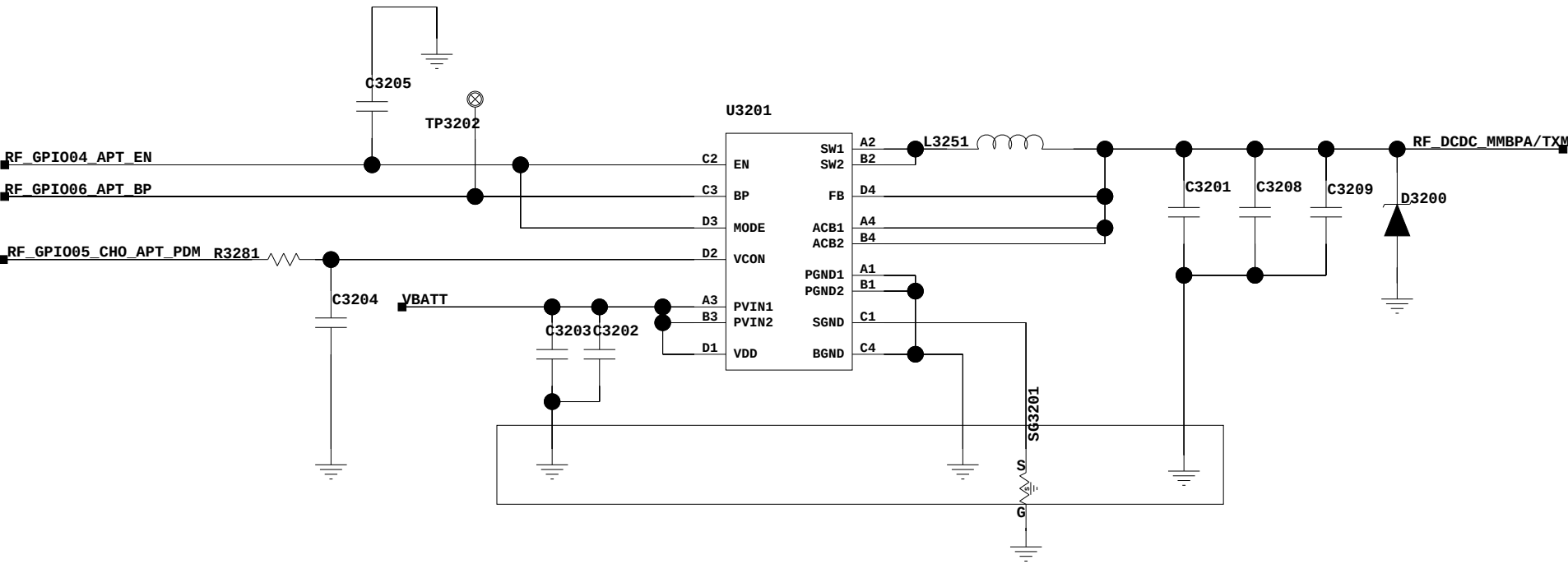
HKADC



The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 31 of 100	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

32 APT_LM3243



- 1. DCDCの出力電圧を調整するためのコンデンサ、インダクタ、抵抗の値を調整する。
- 2. インダクタの値を調整する。インダクタの値は、出力電圧の調整に使用される。
- 3. インダクタの値を調整する。インダクタの値は、出力電圧の調整に使用される。

The type and specification of the components refer to the BOM

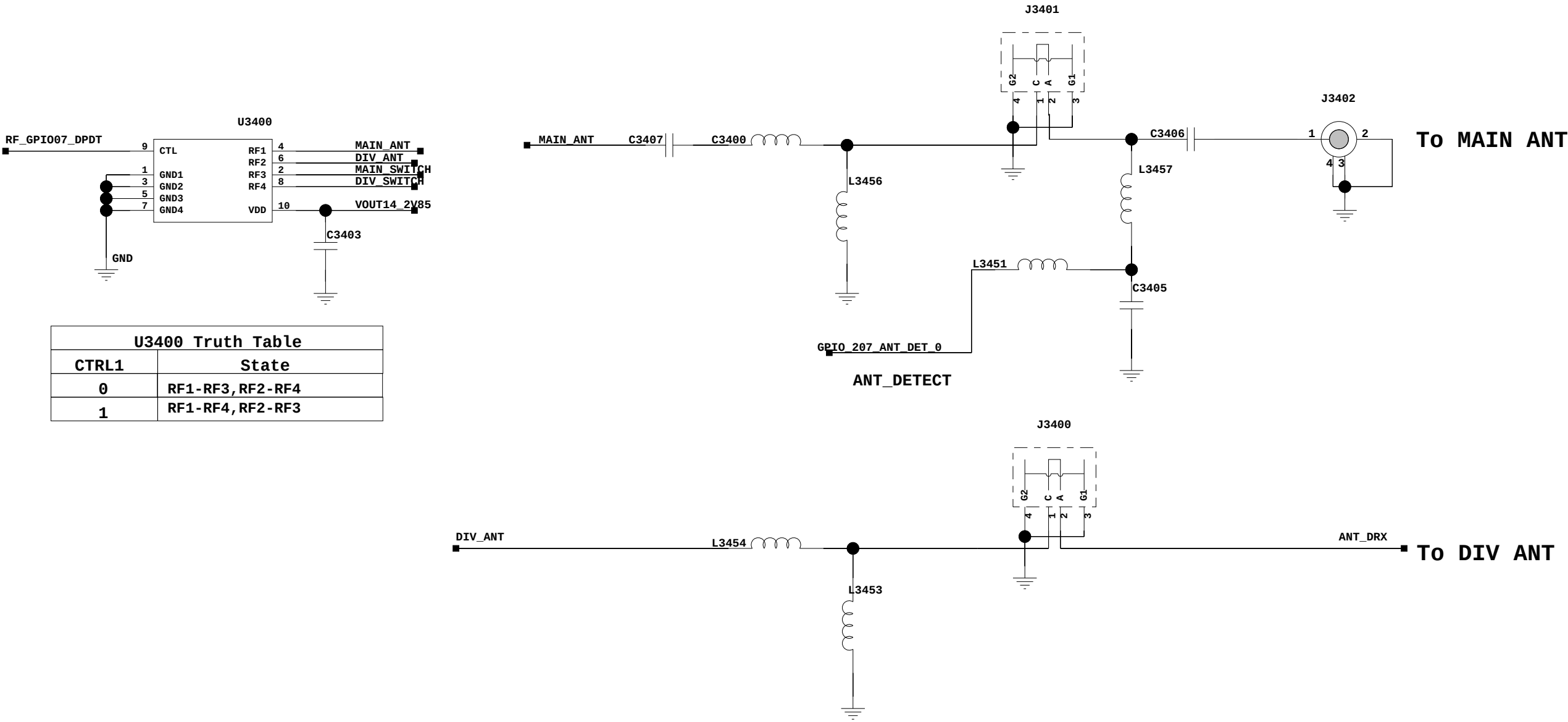
				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	32 APT_060
		E	03025GKM	HUAWEI TECH CO.,LTD.	

A



					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	33 R0FC0_6053
		E	03025GKM	HUAWEI TECH CO.,LTD.	

34 DPDT_Connector



U3400 Truth Table	
CTRL1	State
0	RF1-RF3, RF2-RF4
1	RF1-RF4, RF2-RF3

The type and specification of the components refer to the BOM

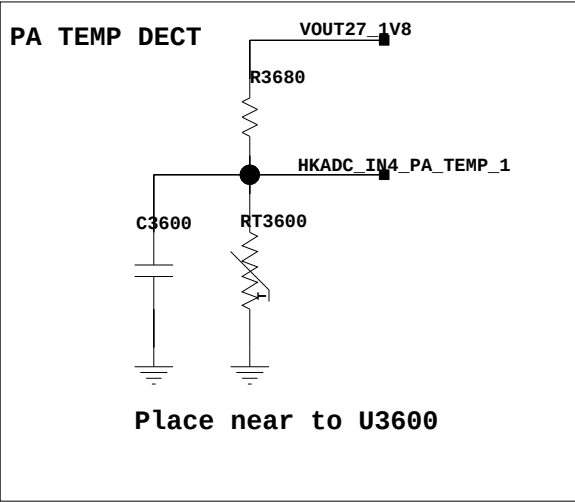
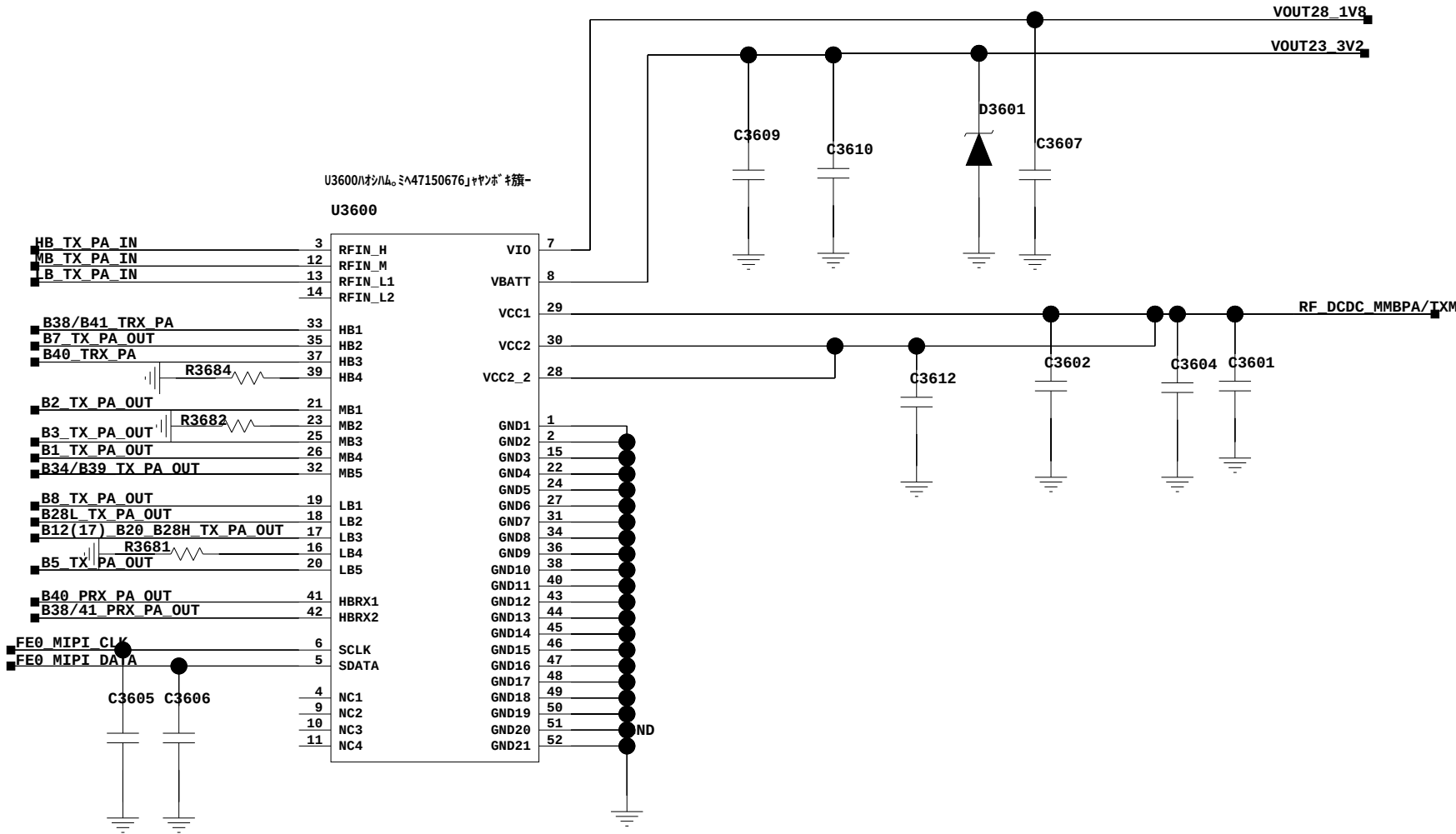
				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 34 DPDT_Connector	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

35. TXM

The type and specification of the components refer to the BOM

DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126	VER		PART_NUMBER	
		E		03025GKM	
		SHEET		35 TXM 60	
		HUAWEI TECH CO.,LTD.			

36 MMBPA

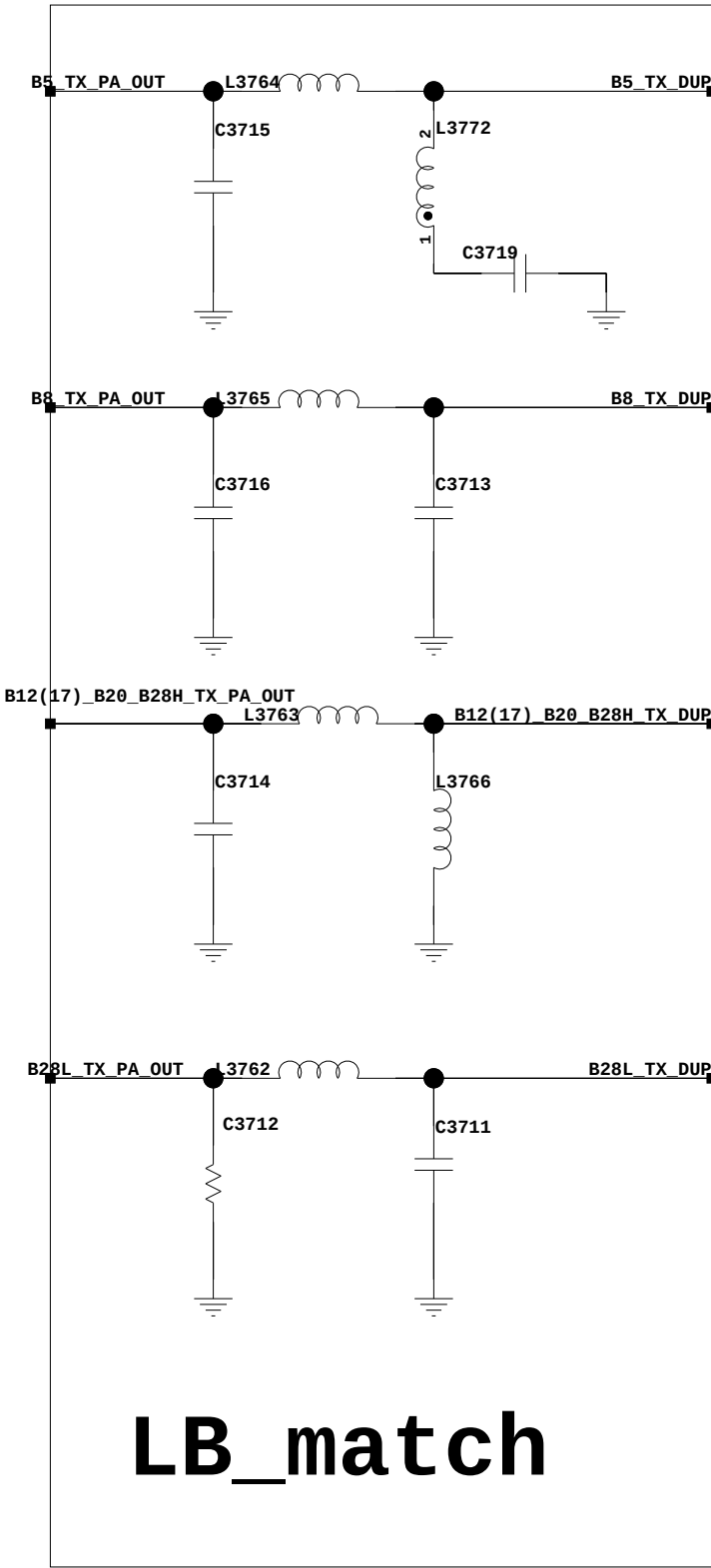


- 1.「銅鍍め」機能 A」+マイコン規格 ワイヤ」+サ ンクはPCBにメ ンソノメニタケル EPA_TEMP_DET2;
- 2.「銅鍍め」EPA_TEMP_DET2,ミニコン/幕材Sub-TMGニタ イ コ ーストHKADC_IN9.

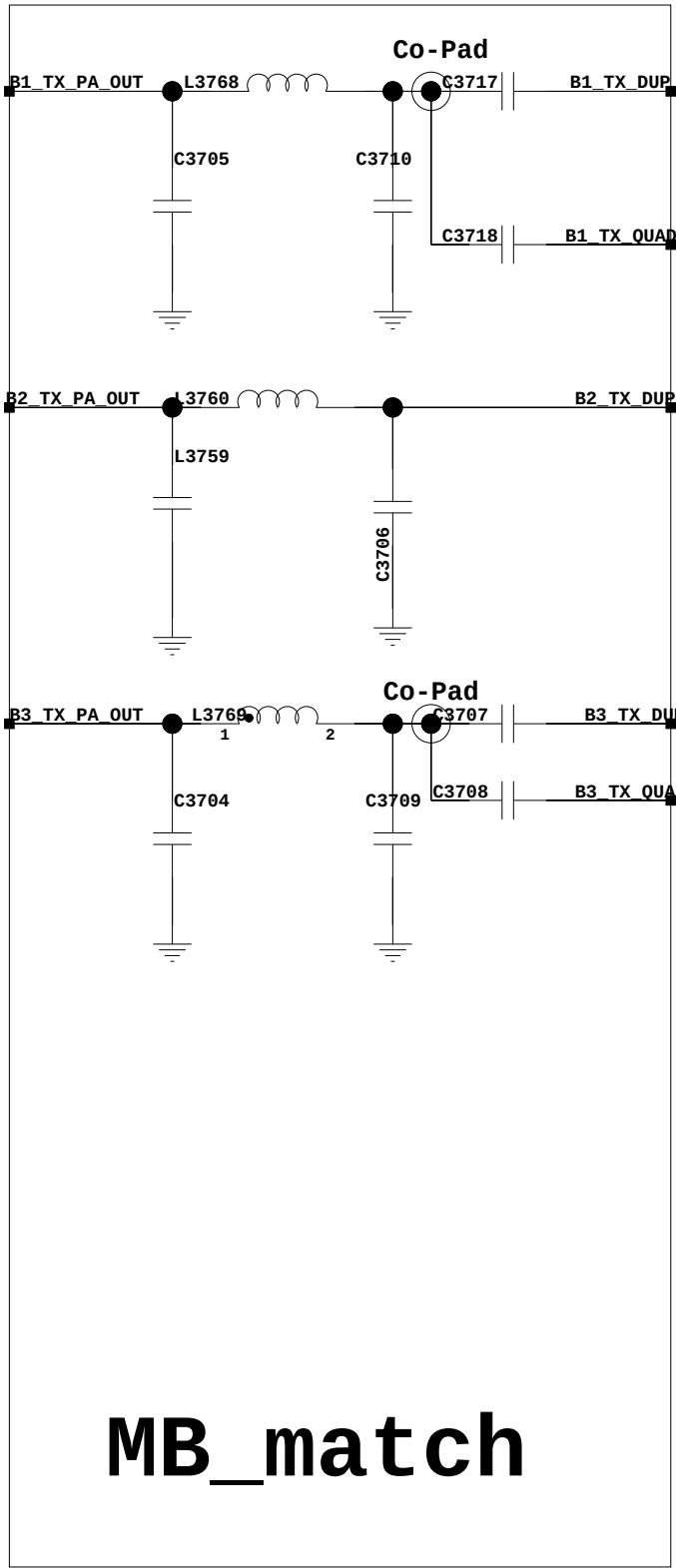
The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 36 MMBPA 60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

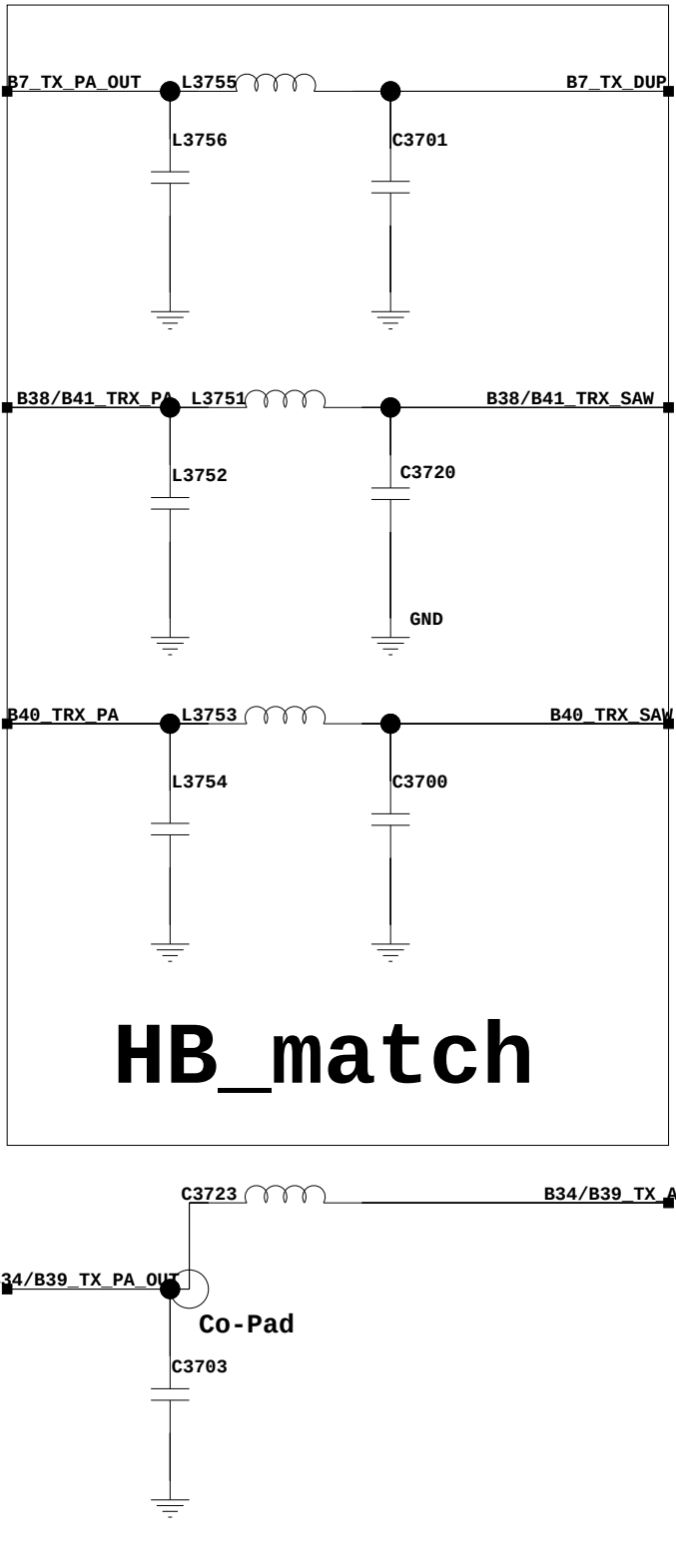
37.TX_Loadpull



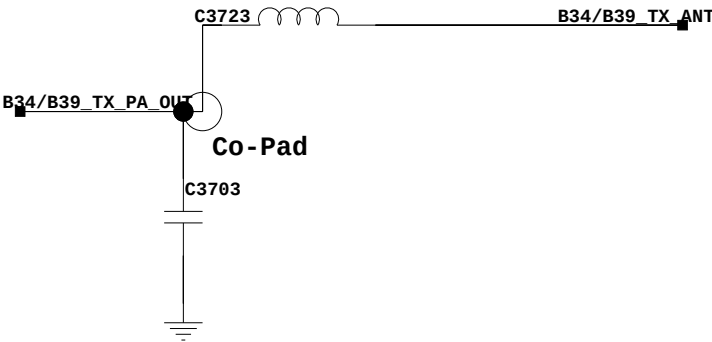
LB_match



MB_match

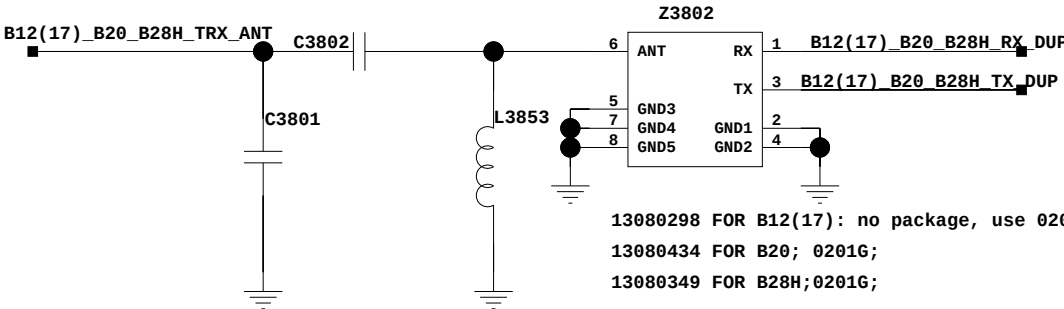
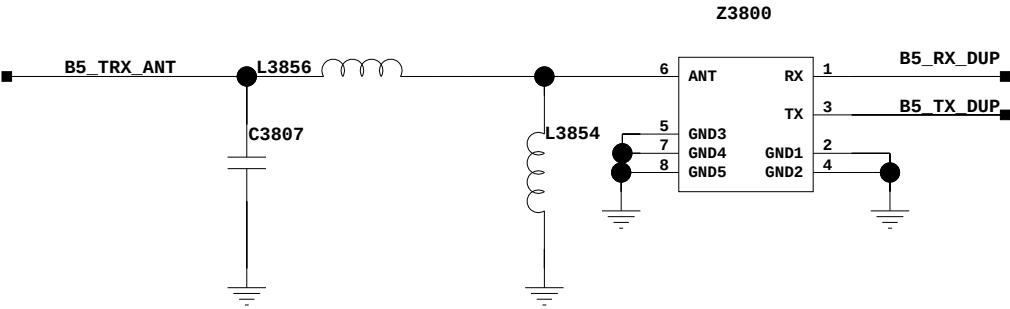


HB_match

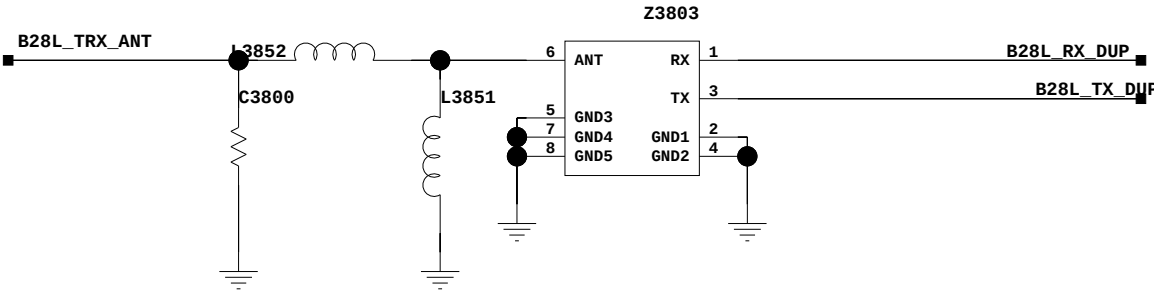
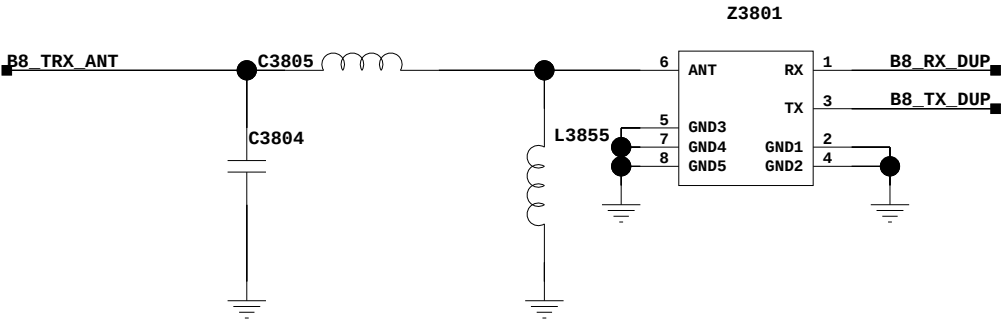


The type and specification of the components refer to the BOM					
					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 37 TX_Loadpull	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

38 TRX_LB_1



13080298 FOR B12(17): no package, use 0201H temporarily;check with DFX before product
13080434 FOR B20; 0201G;
13080349 FOR B28H;0201G;



13080348 FOR B28L- Package SFLT8-0201G

The type and specification of the components refer to the BOM

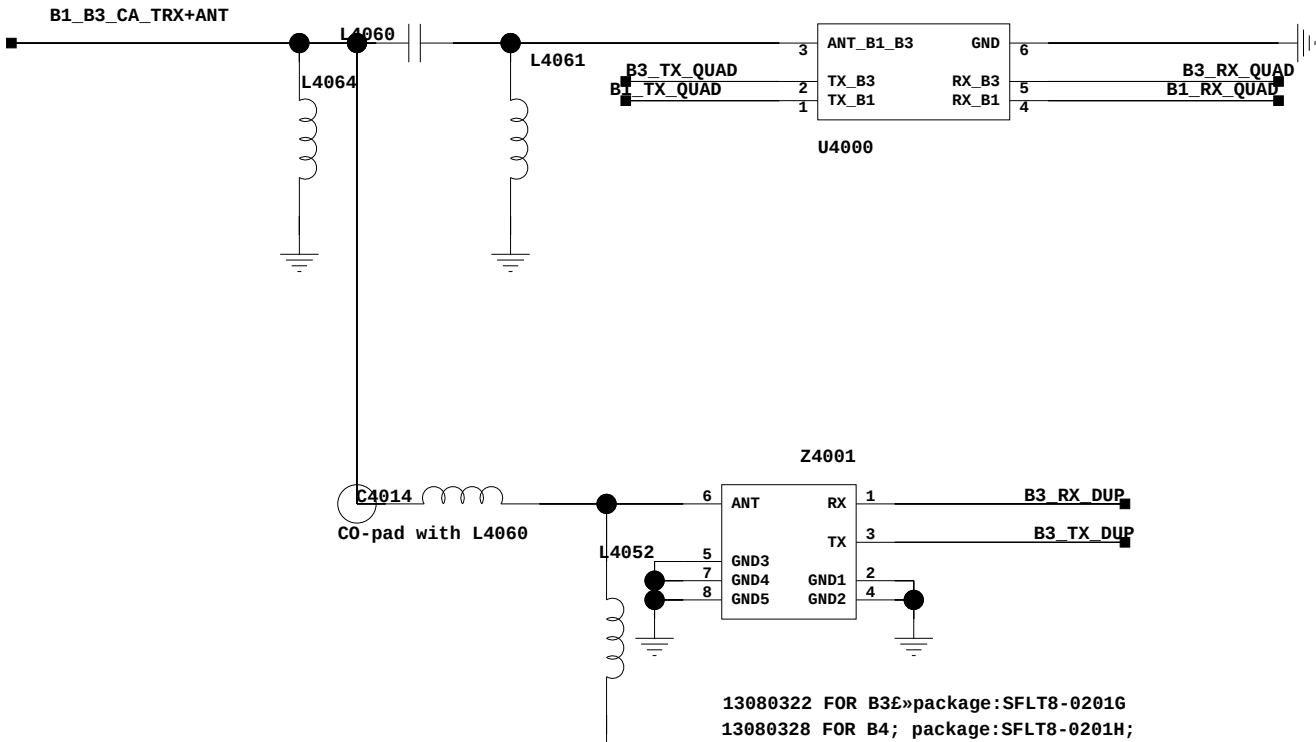
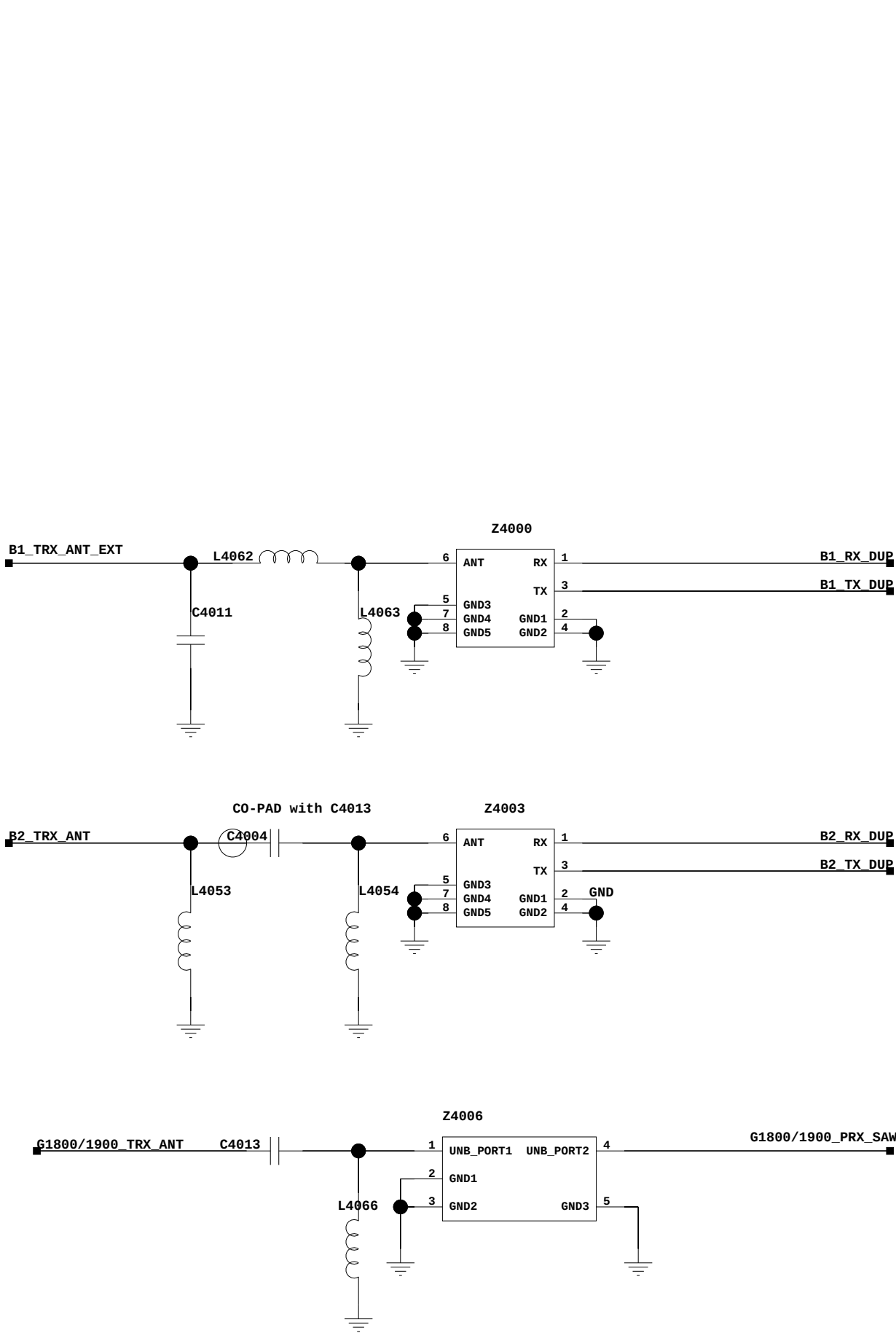
				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM			03025GKM_SCH1ZH
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 38 TRX_LB_1	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

39 TRX_LB_2

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 39 TRX_LB_2_Reserved	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

40 TRX_MB_1

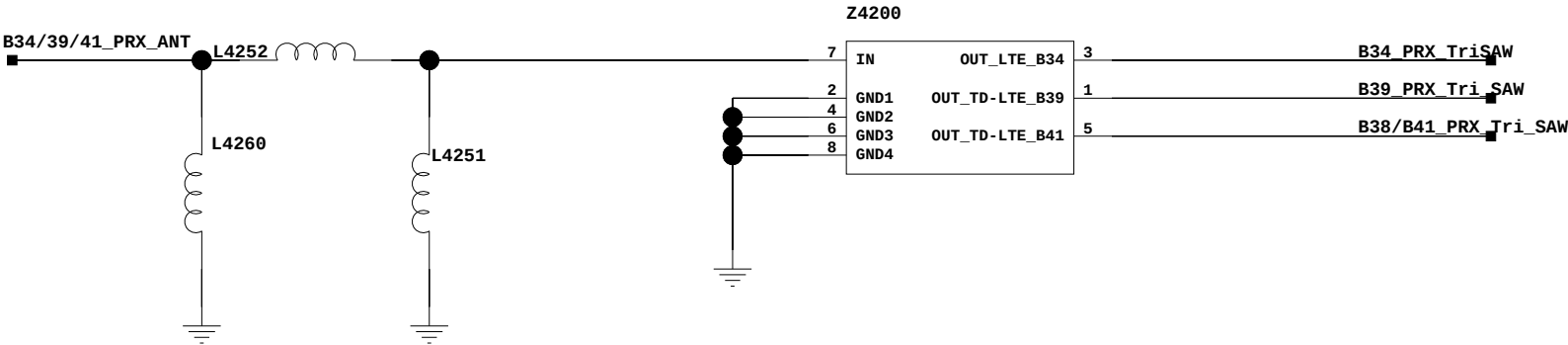
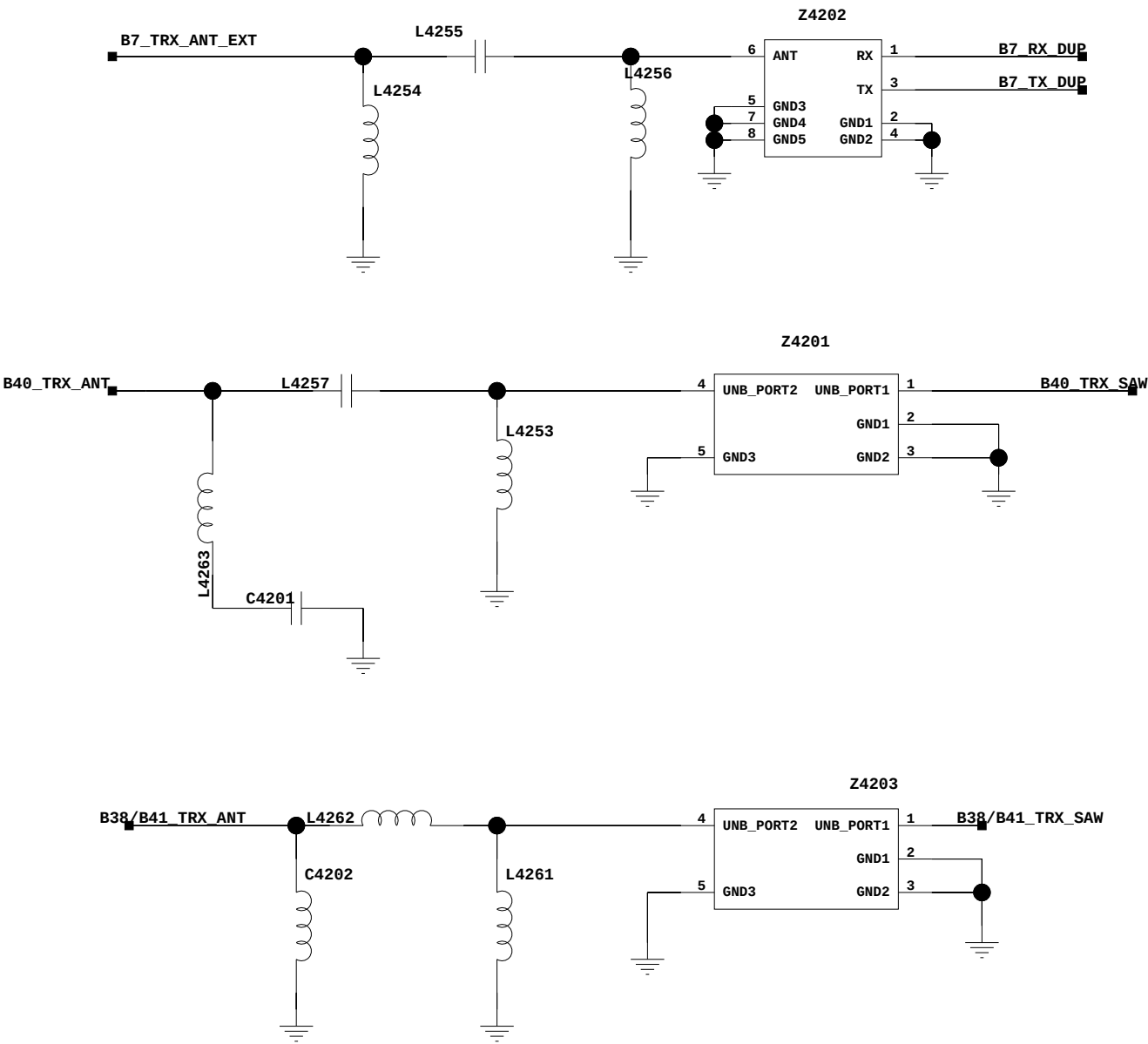


The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 40 TRX_MB_1	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

1	2	3	4	5	6
41 TRX_MB_2					
A					A
B					B
C					C
D					D
The type and specification of the components refer to the BOM					
					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 41 TRX_MB_2 Reserved	
		E	03025GKM	HUAWEI TECH CO.,LTD.	
1	2	3	4	5	6

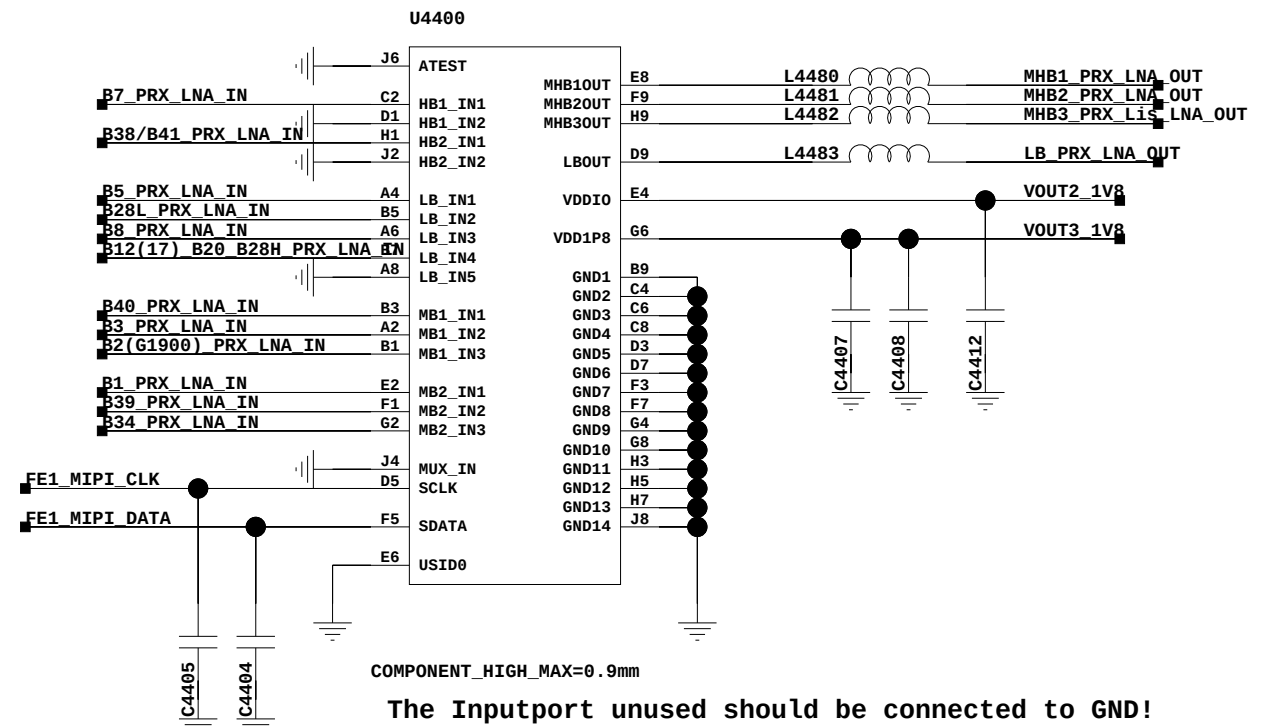
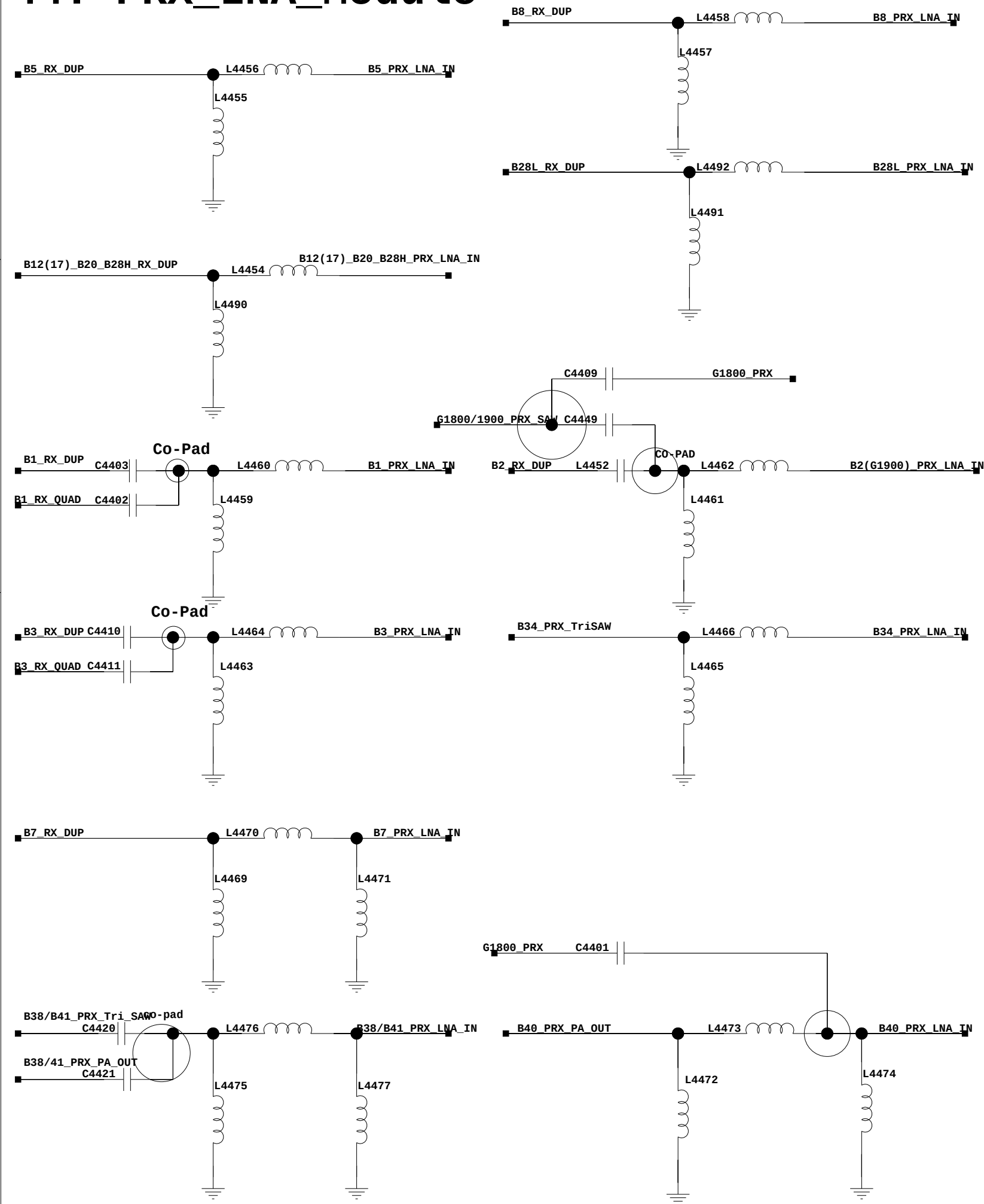
42 TRX_HB_1



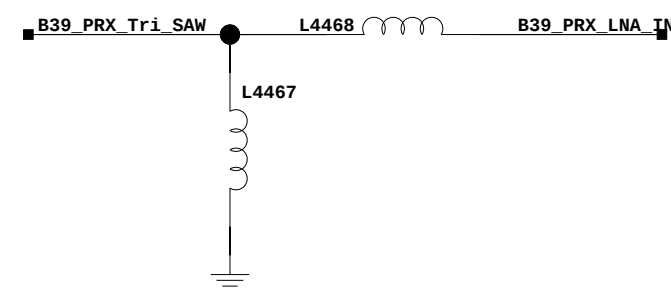
The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	42 TRX_HB_1
		E	03025GKM	HUAWEI TECH CO.,LTD.	

44. PRX_LNA_Module



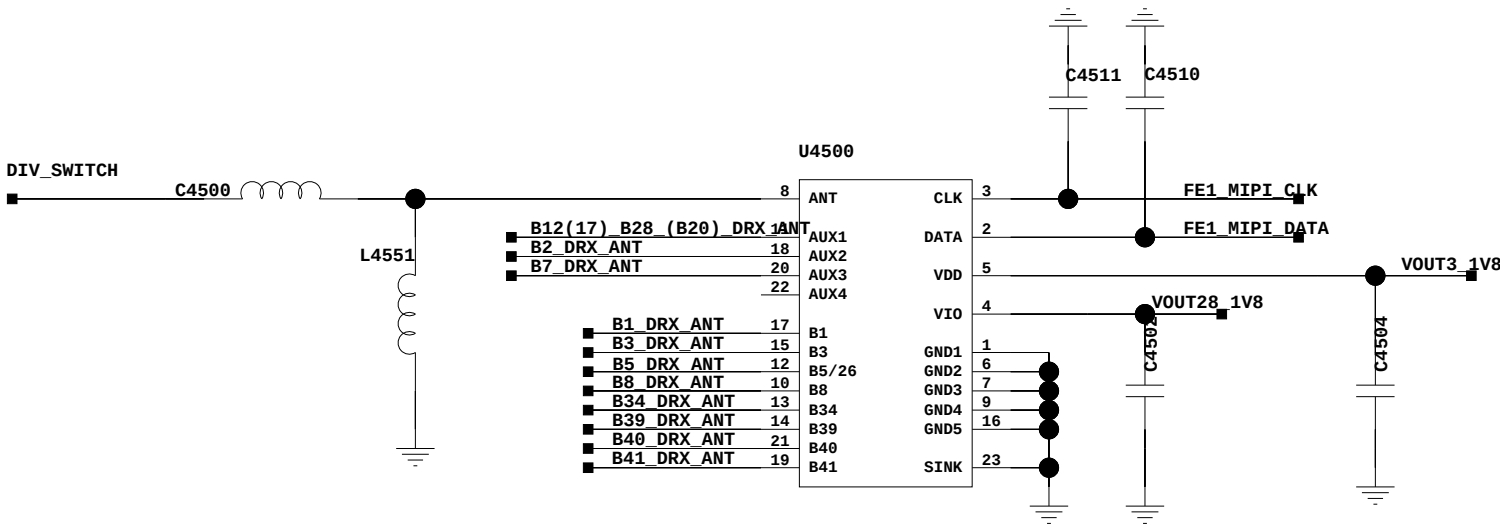
6H03 Frequency Range	
LB_IN1	B5
LB_IN2	703-894MHz
LB_IN3	B8
LB_IN4/5	717-821MHz
MB1_IN1	1805-2200MHz B40
MB1_IN2/3&MB2_IN1/3	1805-2200MHz
HB1/2_IN1	B41/38/7
HB1/2_IN2	2300-2690MHz



The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 44 OF 40	Module
		E	03025GKM	HUAWEI TECH CO.,LTD	

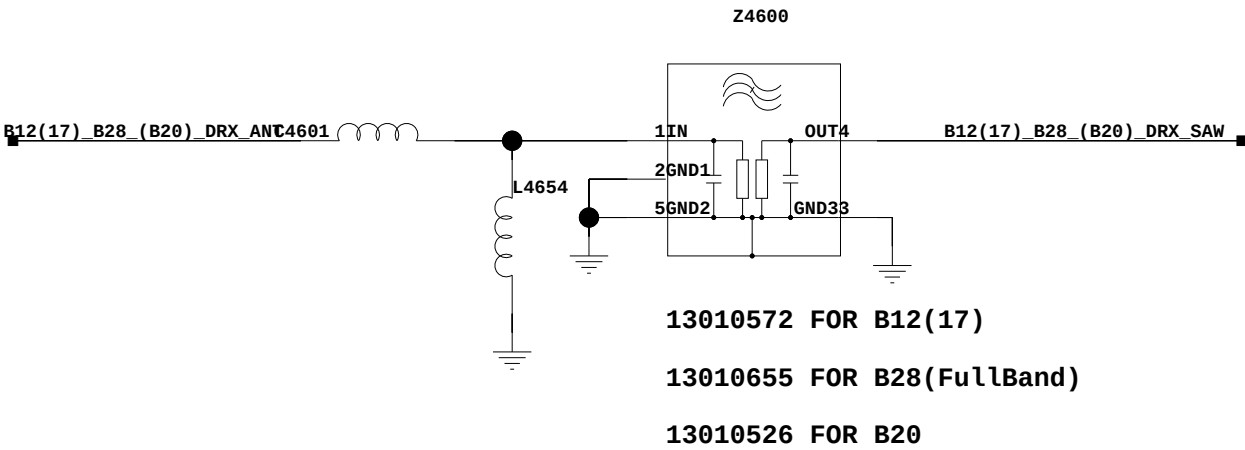
45.DRX_SWITCH



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 45 DRX_Switch	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

46. DRX_LB

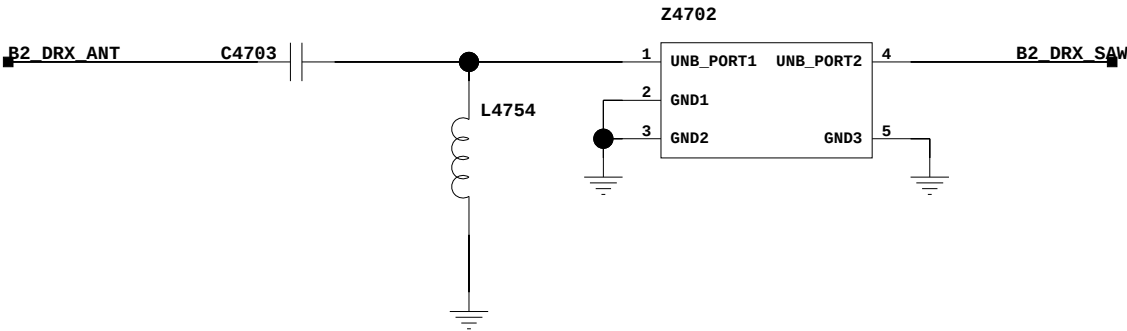


- 13010572 FOR B12(17)
- 13010655 FOR B28(FullBand)
- 13010526 FOR B20

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 46 DRX_LB60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

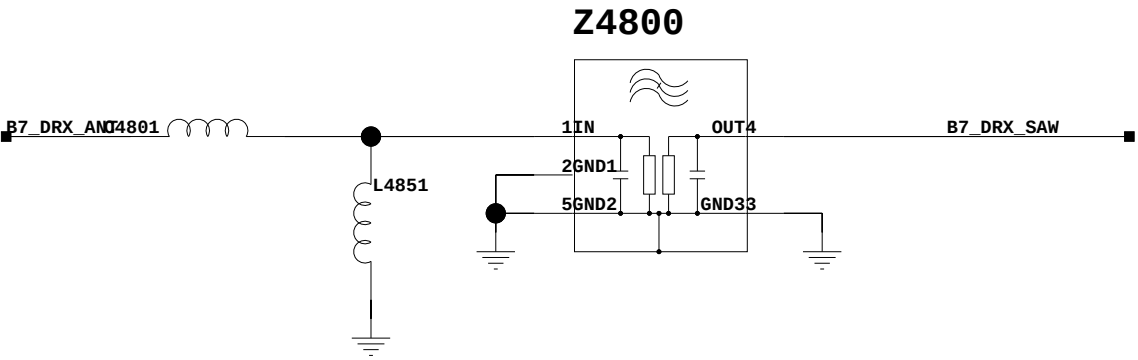
47. DRX_MB



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 47 DRX_MB60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

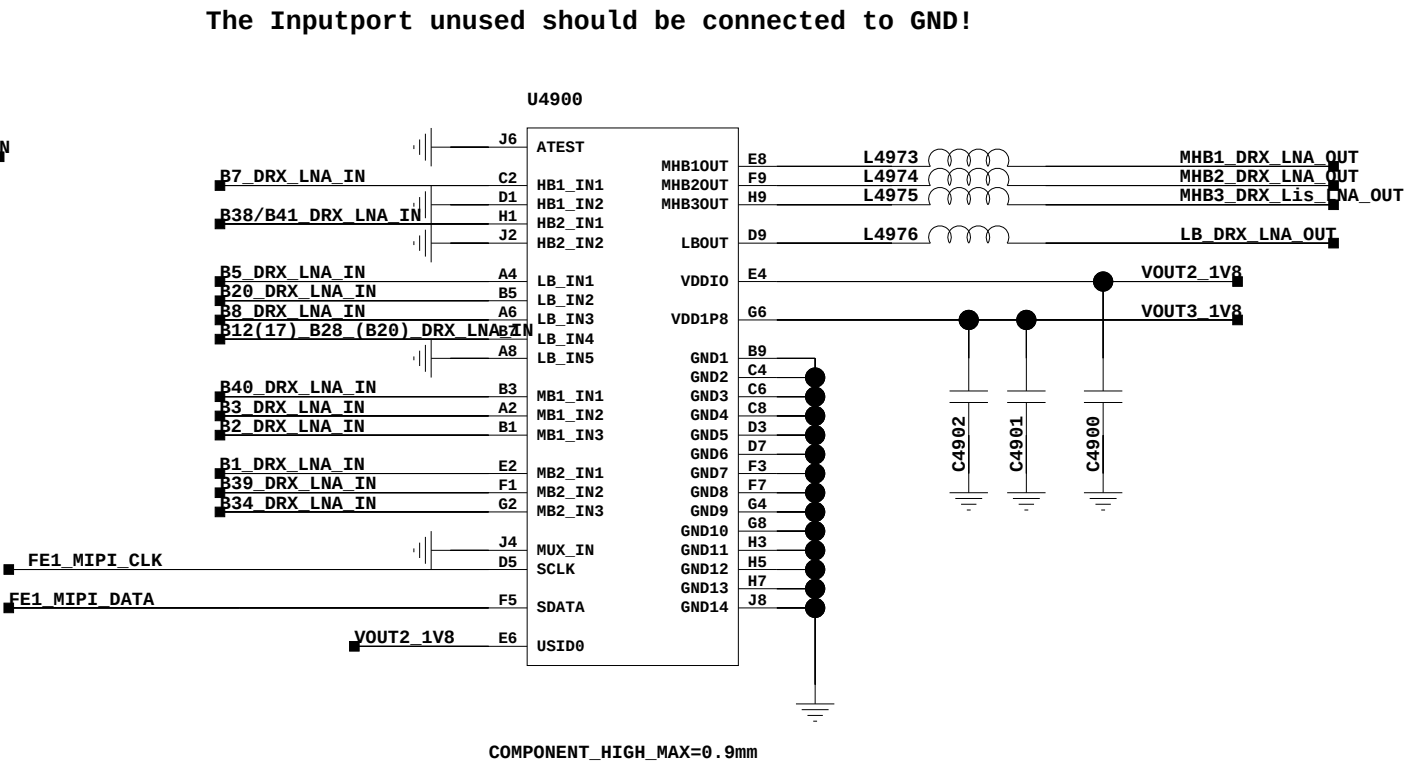
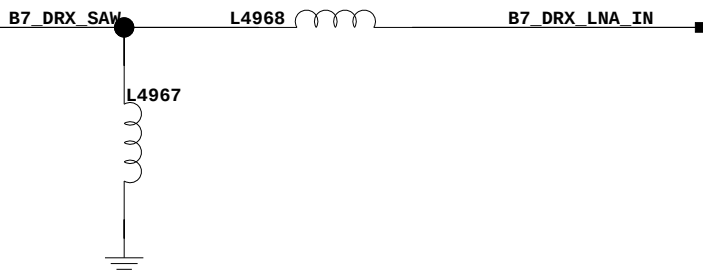
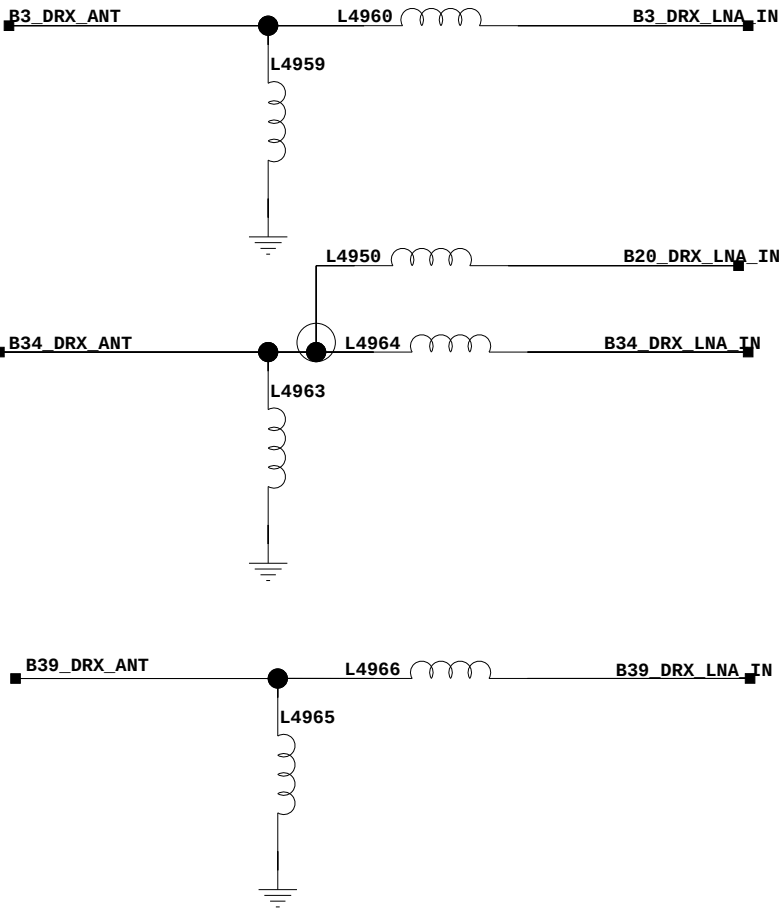
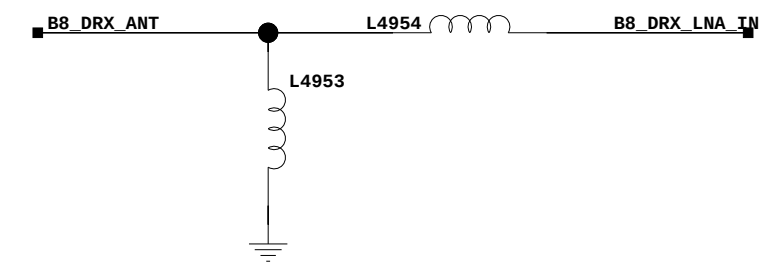
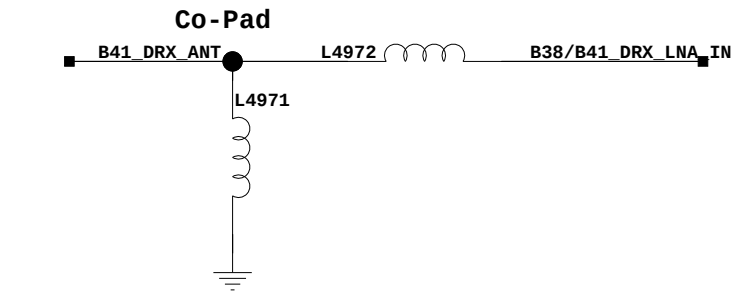
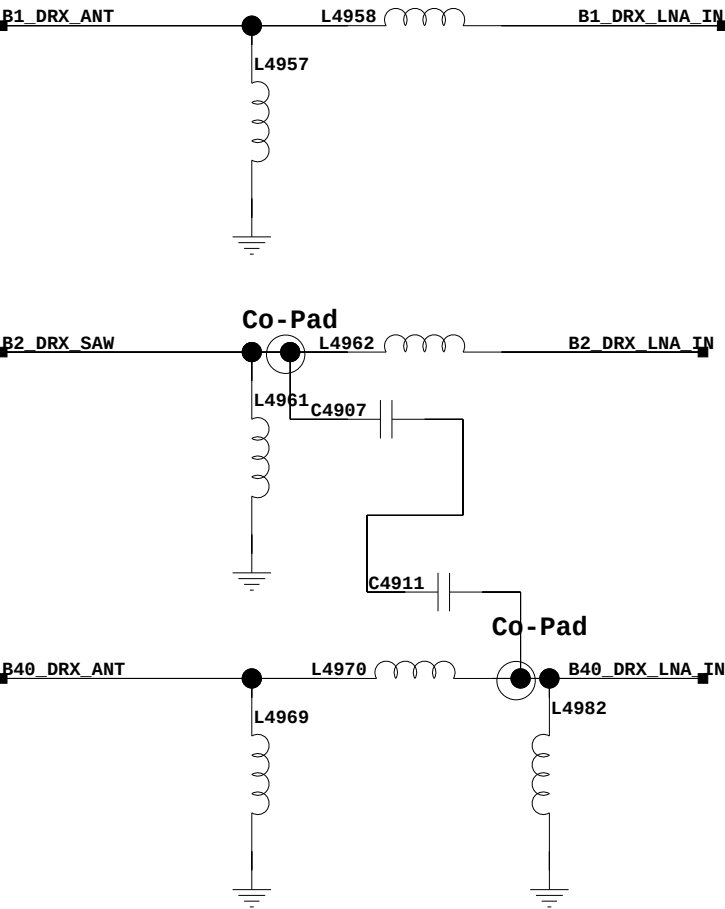
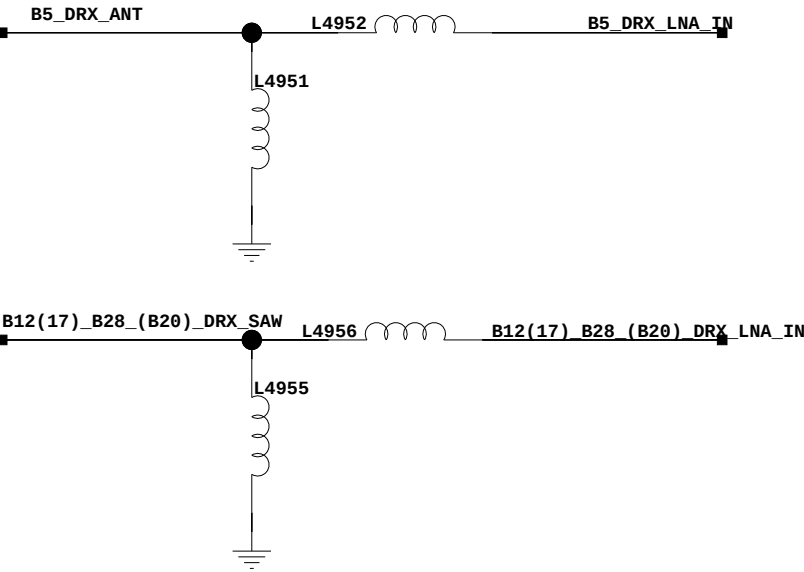
48. DRX_HB



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM			03025GKM_SCH1ZH
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 48 DRX_HB60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

49. DRX_LNA_Module



6H03 Frequency Range	
LB_IN1	B5
LB_IN2	703-894MHz
LB_IN3	B8
LB_IN4/5	717-821MHz
MB1_IN1	1805-2200MHz B40
MB1_IN2/3&-MB2_IN1/3	1805-2200MHz
HB1/2_IN1	B41/38/7
HB1/2_IN2	2300-2690MHz

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 49 DRX_LNA_Module	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

1

2

3

4

5

6

50. Reserved

A

A

B**B**

C

C

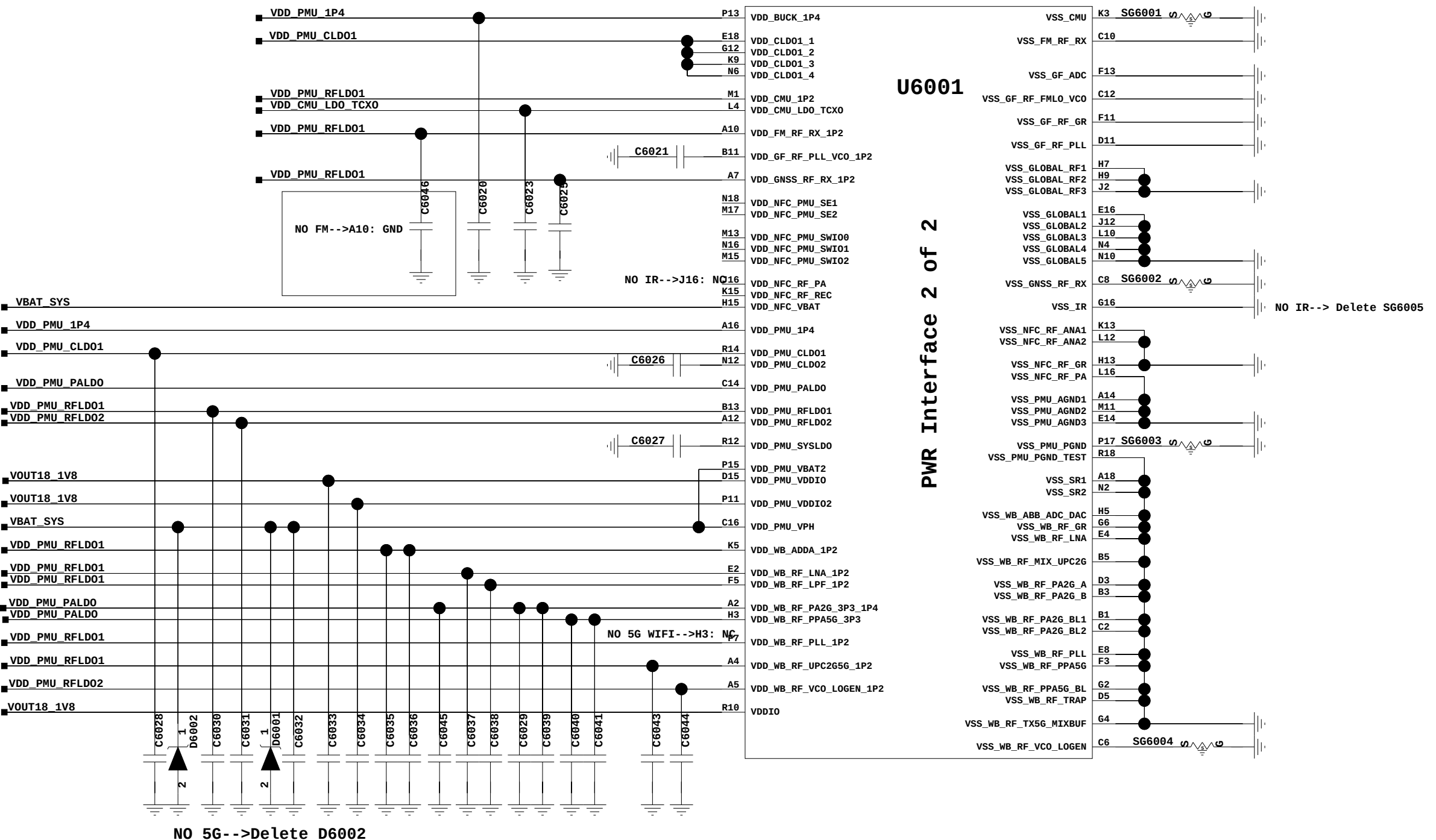
D

D

The type and specification of the components refer to the BOM

					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 50 of 50	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

60 NC_POWER



Add by Hisilicon for debug

VOUT18_1V8

VBAT_SYS

Boston,Miami: VOUT2->VOUT18_1V8

Chicago,Dallas: VOUT2

R6082;C6083:Æ%Ì"Ê×ÏiÄ¿ÊÖÖÆ±£ÁÔ£¬×iÖÖ¹éµµÊ±£%µô,Ö±Á¬£»·ÇÆ%Ì"Ê×ÏiÄ¿Ö±Á¬

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	60 NC_POWER
		E	03025GKM	HUAWEI TECH CO.,LTD.	

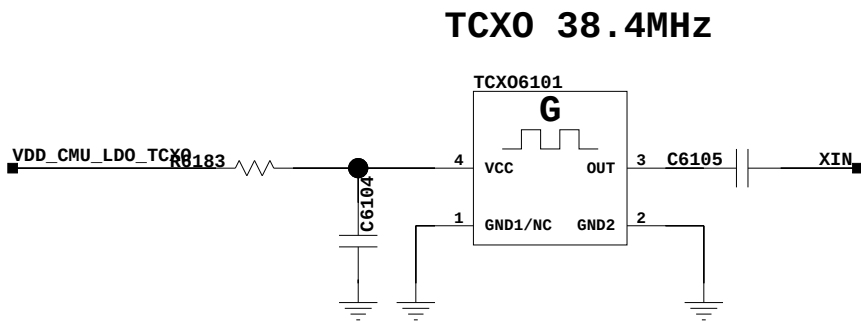
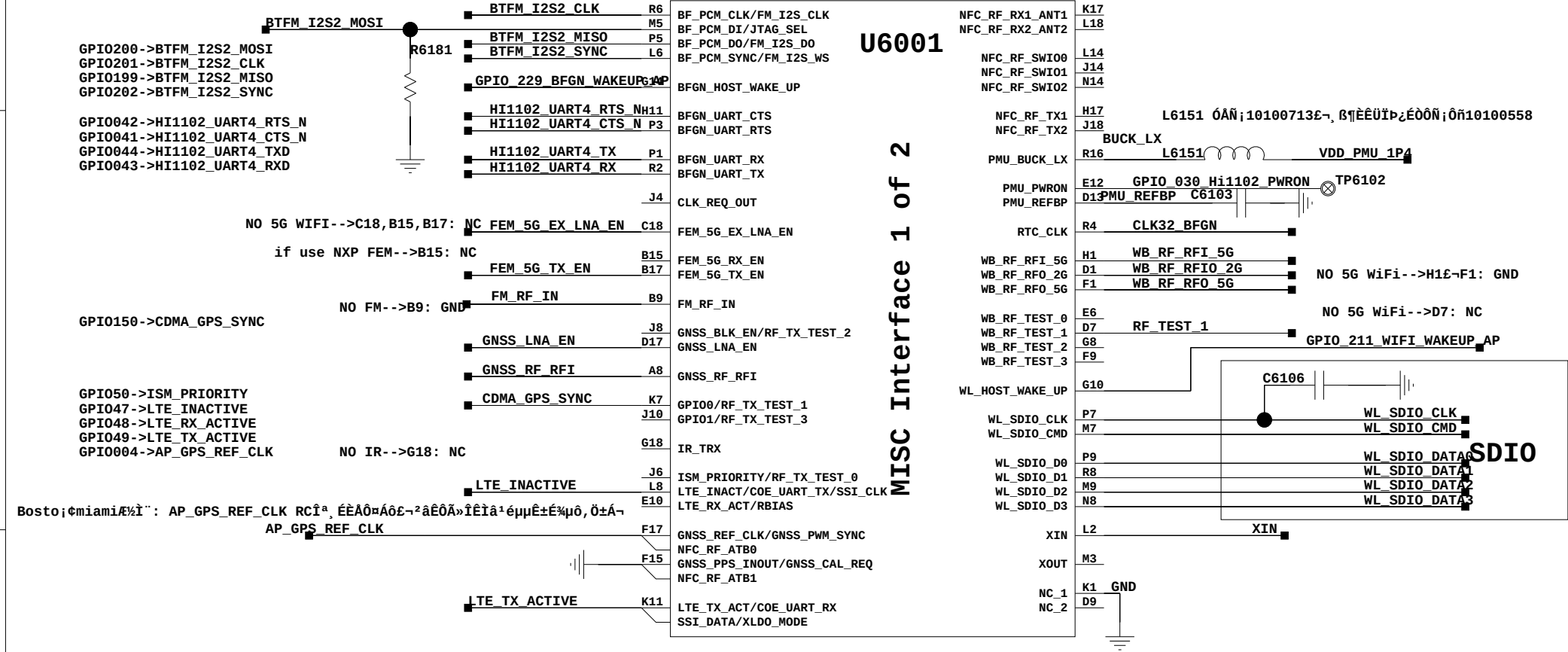
61 NC_BB

A

B

C

D



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 61 NO FBB_00ami	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

A

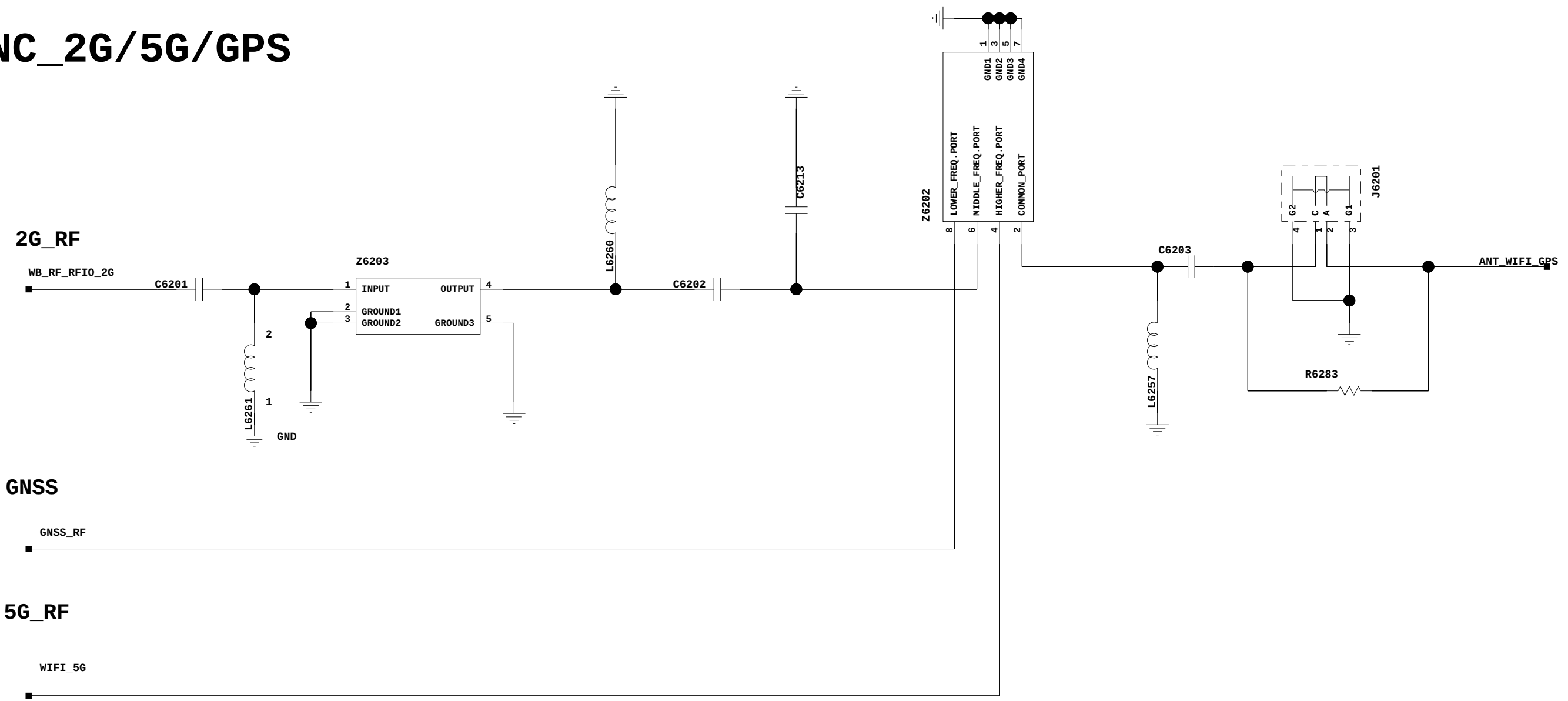
B

C

D

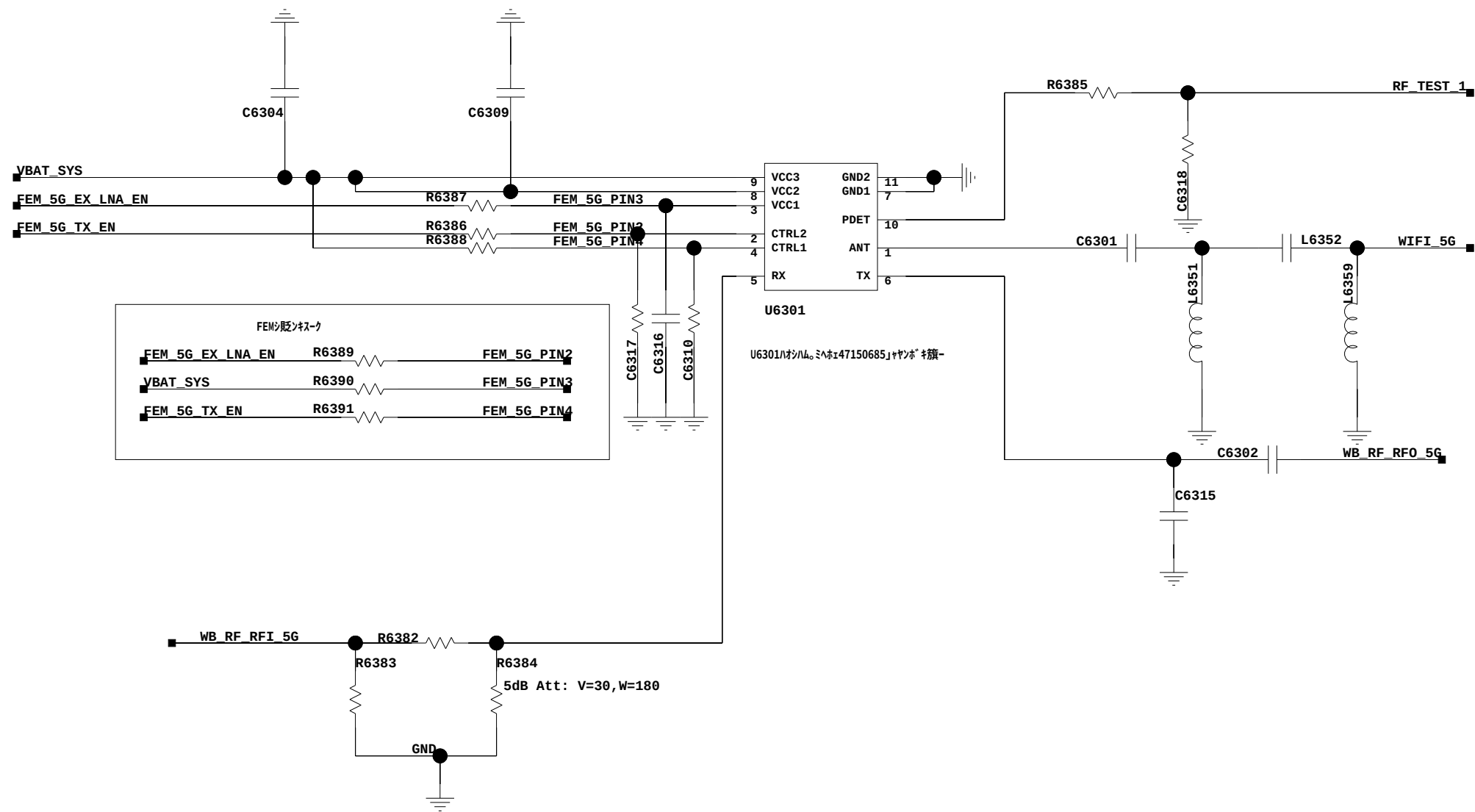
D

62 NC_2G/5G/GPS



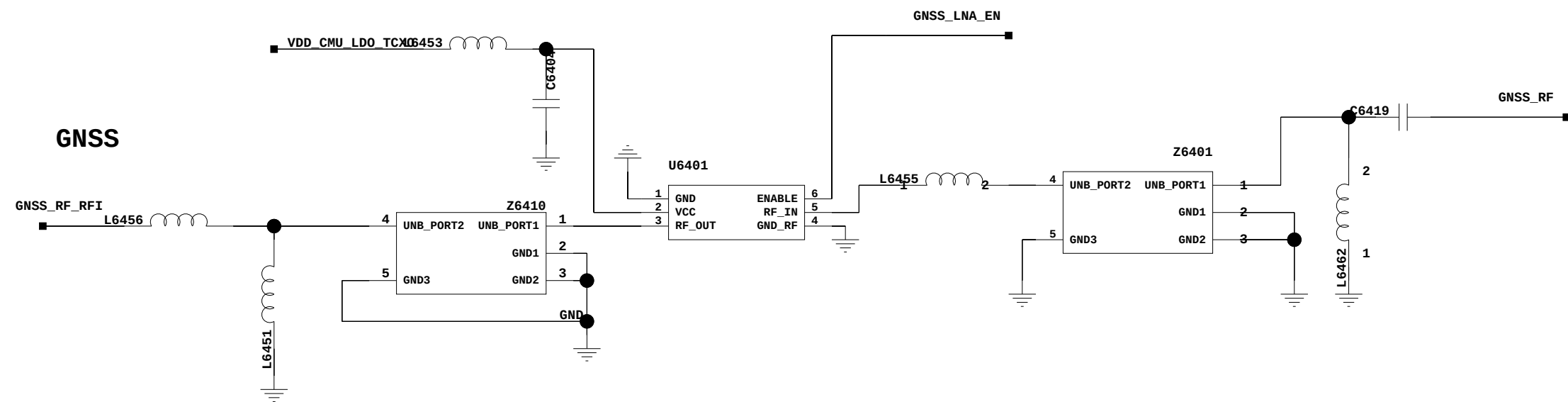
The type and specification of the components refer to the BOM					
					2018-07-06
				ECA NO	DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 62 NO	2G/5G/GPS
		E	03025GKM	HUAWEI TECH CO.,LTD.	

63 NC_FE_WIFI_5G



The type and specification of the components refer to the BOM					
				ECA NO	2018-07-06
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	63 NC_FE_WIFI_5G_599
		E	03025GKM	HUAWEI TECH CO.,LTD.	

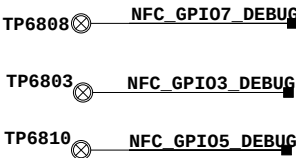
64 NC_GPS



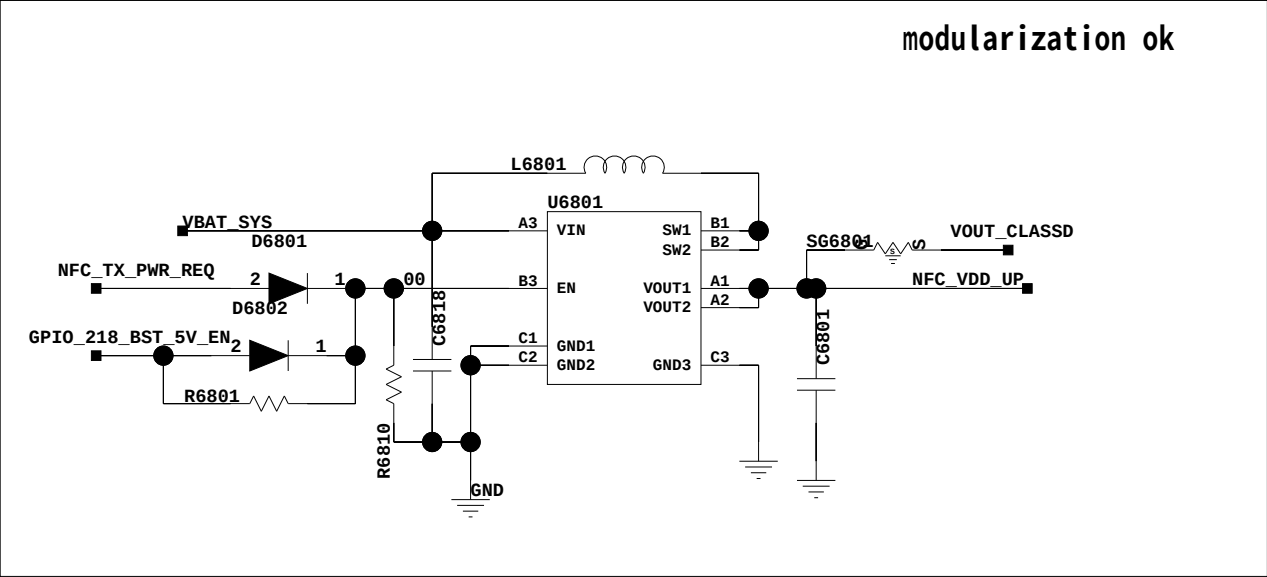
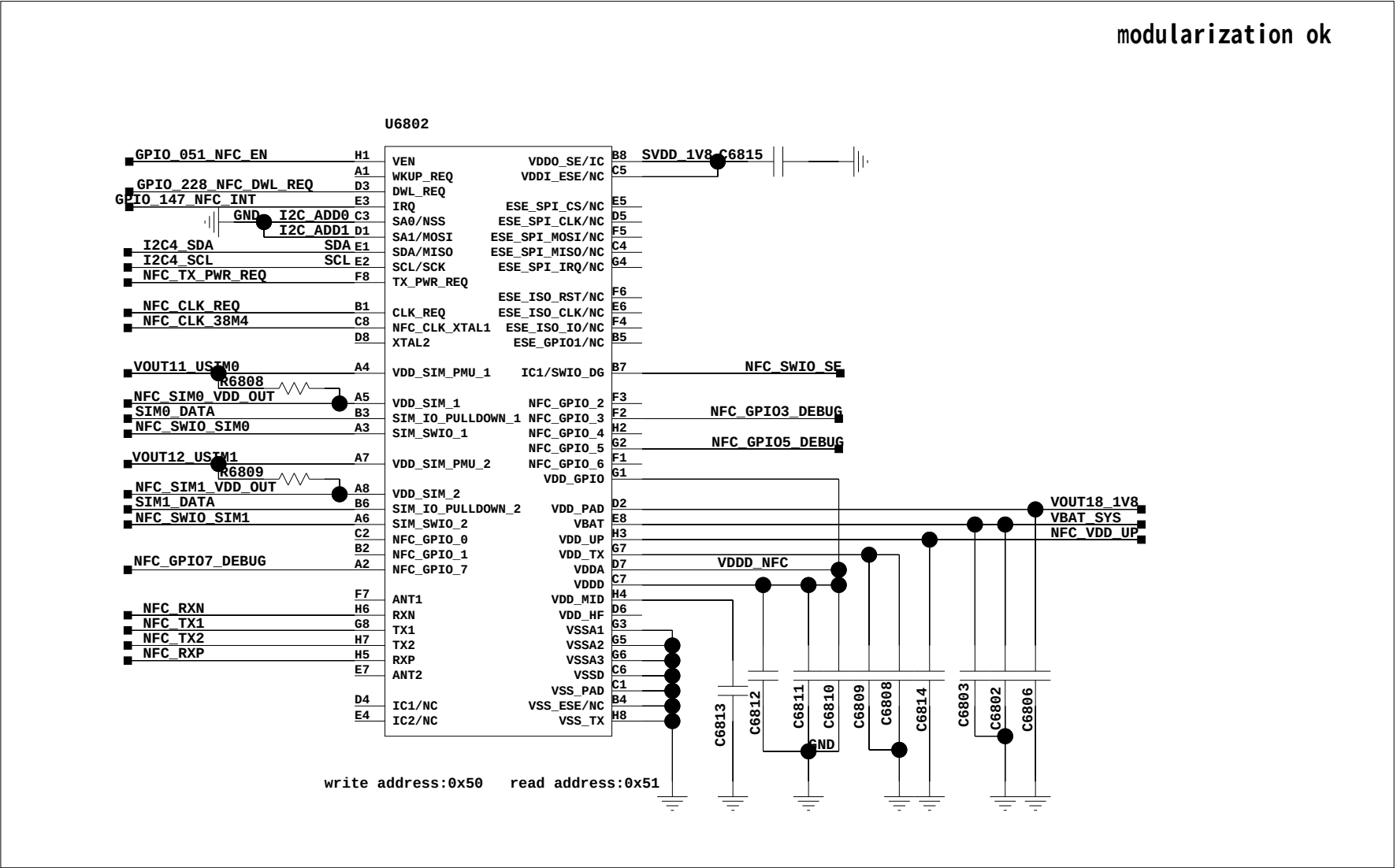
The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	64 NO
		E	03025GKM	06GPS60	
				HUAWEI TECH CO.,LTD.	

68. NFC_BB



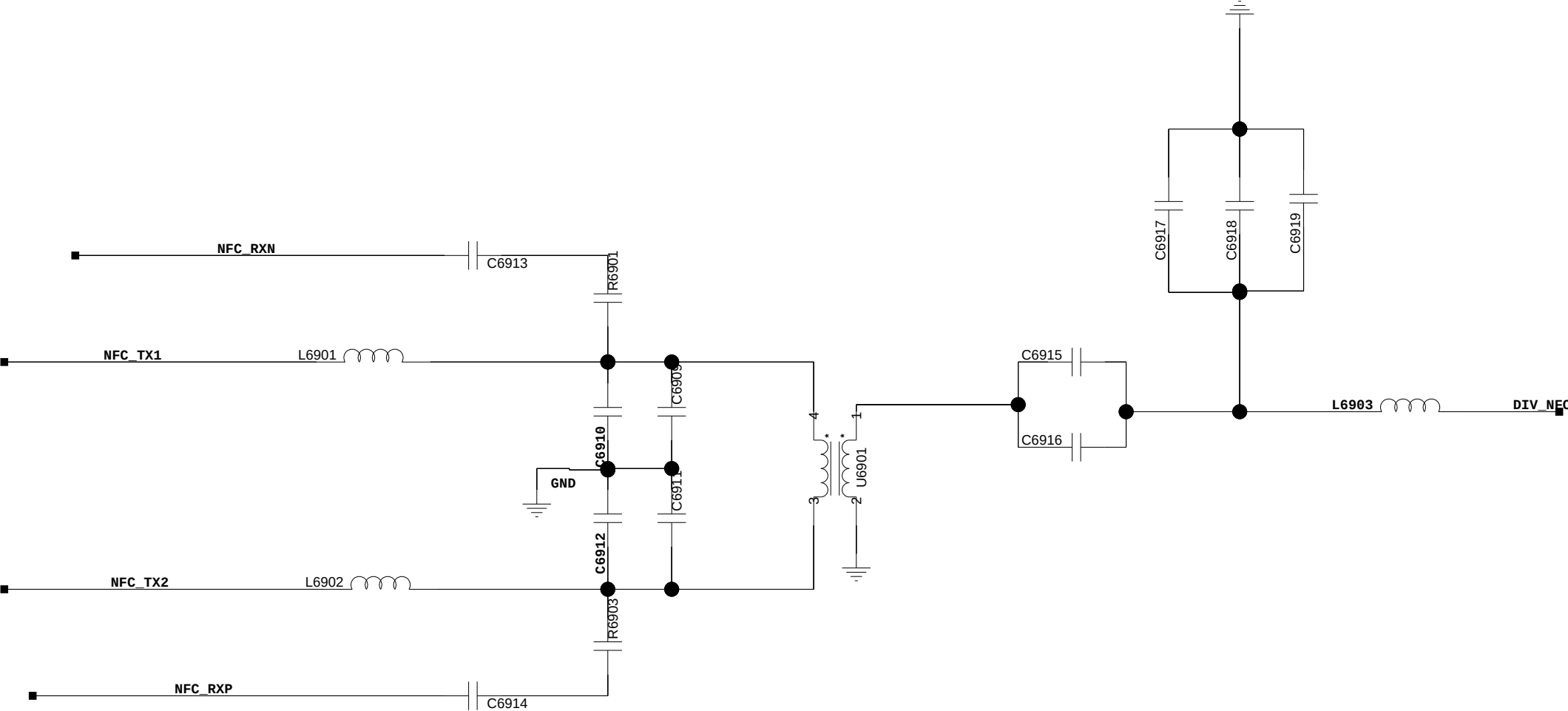
page	nember	NFC SMT	NFC NC
page7	R731	DNI	SMT
page56	R6808	DNI	SMT
	R6809	DNI	SMT
	D6801	SMT	DNI
	D6802	SMT	DNI
	R6801	DNI	SMT
page12	R1250	DNI	SMT
page12	R1205	SMT	DNI
page56	U6801	39111034	39110908
page7	R710	SMT	DNI
page7	R711	SMT	DNI



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 68_NFC_BB60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

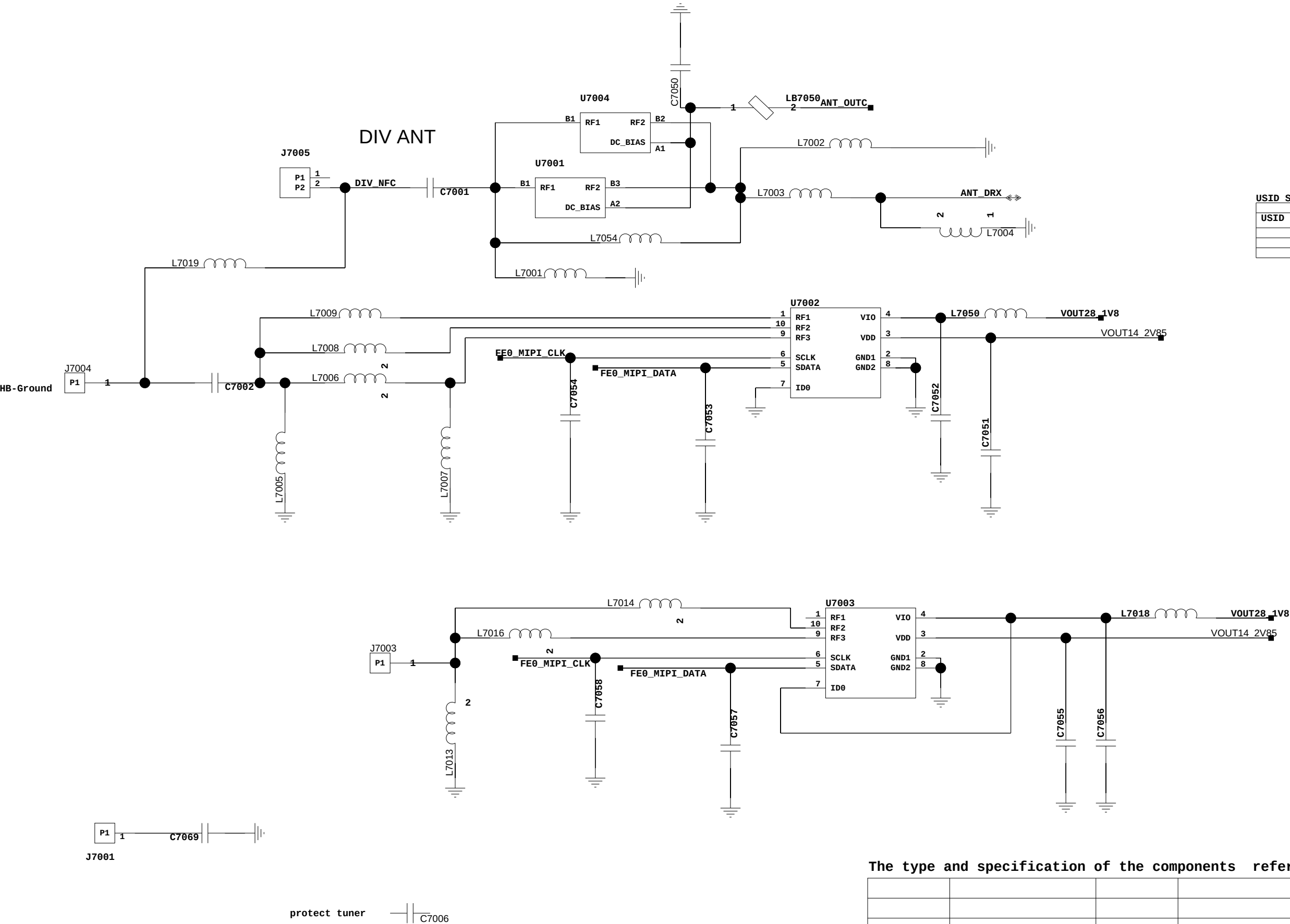
69. ANT_NFC



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06 DATE
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 69 ANT_NF60	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

70.ANT_DIV



USID Setting Table(Register:0X1F D3:D0)

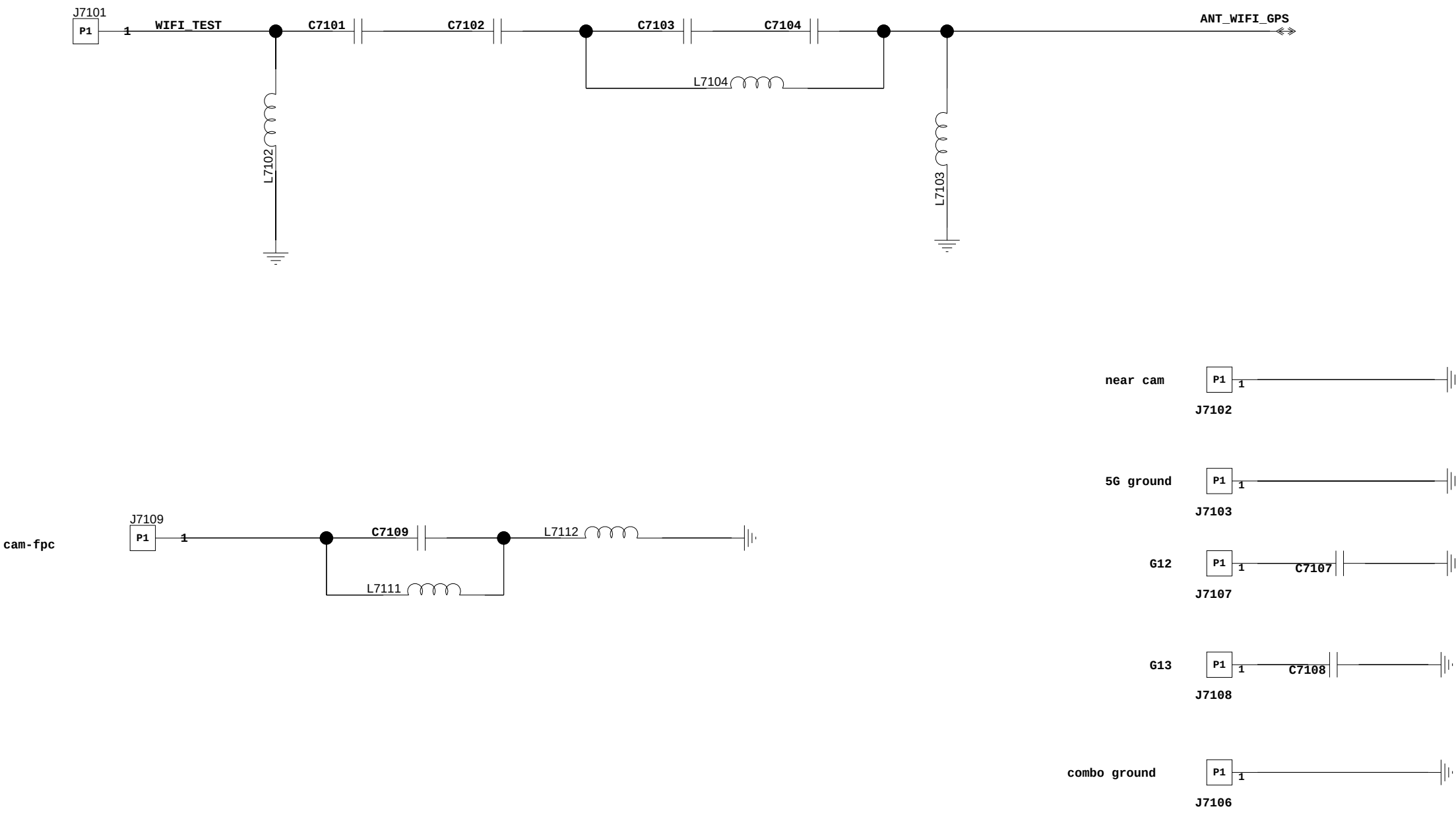
USID	USID			
	D3	D2	D1	D0
GND	0	1	1	0
Open	0	1	1	1
VIO	1	0	0	1

The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 70 ANT_DIV0	
		E	03025GKM	HUAWEI TECH CO.,LTD.	

71 ANT_GPS_WIFI

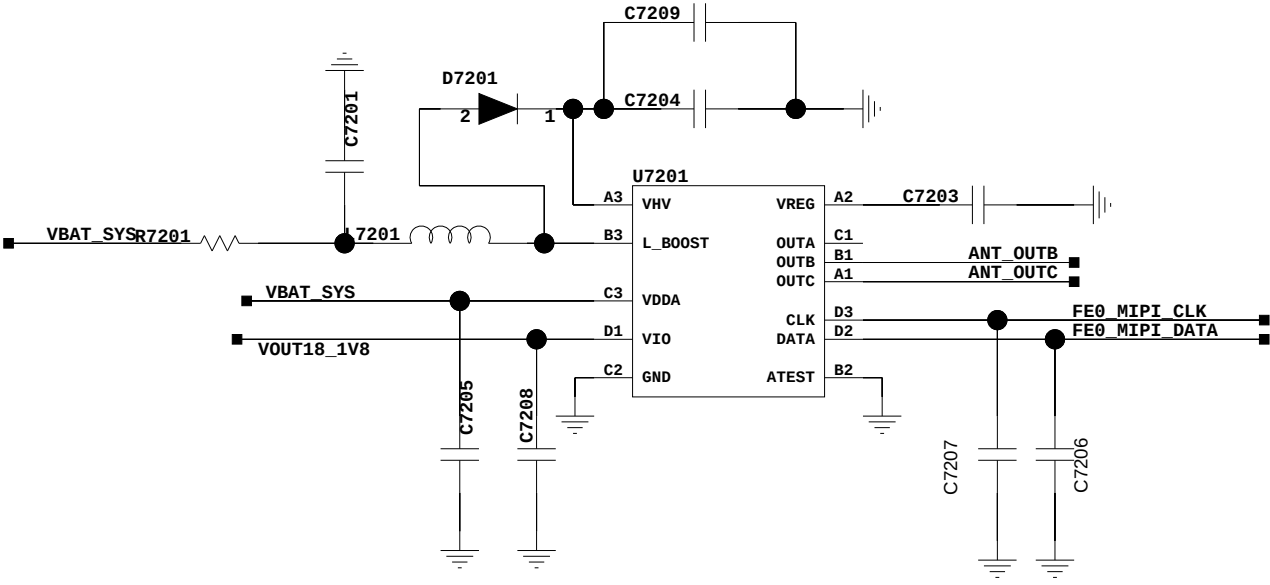
WIFI/GPS ANT



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET	71 ANT_GPS_WIFI
		E	03025GKM	HUAWEI TECH CO.,LTD.	

72.ANT_Tuner_Controller



The type and specification of the components refer to the BOM

				ECA NO	2018-07-06
				DATE	
DESIGNED	CHENZHENBIN 00264464	HL1JSNM		03025GKM_SCH1ZH	
REVIEWED	MABO 00278126				
		VER	PART_NUMBER	SHEET 72 ANT_Tuner_Controller	
		E	03025GKM	HUAWEI TECH CO.,LTD.	